

# AM62P, AM62P-Q1 Processor Family Schematic Design Guidelines and Schematic Review Checklist



## ABSTRACT

The application note includes schematic design guidelines, implementation recommendations, and schematic review checklist for board designers using the AM62P, AM62P-Q1 processor family. This application note discusses the processor configurations, processor peripherals and the interface to attached (external) devices. Schematic review checklist at the end of each section, provides a comprehensive list of review points for each of the peripheral and guidelines section for board designers to verify the custom board.

Additionally, links are provided to processor product pages, processor related collaterals, FAQs related to processor and processor peripherals published on E2E, and some of the commonly referenced documents. The board designers can reference to the links during custom board design to minimize design errors, optimize the design efforts and optimize the timeline.

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## 1 Introduction

### 1.1 Application Note Usage Guidelines

The application note (*Schematic Design Guidelines and Schematic Review Checklist*) provides custom board design guidelines that can be used by board designers during custom board schematic design and schematic review checklist at the end of each section that can be used by board designers to review the custom board schematics.

#### 1.1.1 Custom Board Design - Implementation References

The application note provides schematic design guidelines and schematic review checklist that can be used during custom board hardware design using the selected processor and peripherals (on-board or add-on) including memory, power, interface and other functional blocks.

Processor references to the selected processor and the attached device references to the external (on-board or add-on) peripherals that are interfaced to the processor based on the end equipment being designed and the application use case.

#### 1.1.2 Processor Family Specific Application Note

The application note is for the AM62Px family of processors covering AM62P, AM62P-Q1 processor families covers the custom board schematic design guidelines and schematic review checklist. The document is specific to AM62Px family of processors and makes this easy-to-use for the chosen family of processors.

#### 1.1.3 Schematic Design Guidelines

The application note provides schematic design guidelines for all the peripherals supported by AM62Px processor family. Board designers can follow schematic design guidelines during the custom board schematic design. Along with the guidelines, links to FAQs have been added for use during custom board schematic design.

Schematic design guidelines can help board designers reduce the design efforts and minimize design errors that can affect functionality and performance.

#### 1.1.4 Schematic Review Checklist

Schematic review checklist at the end of each section has been newly added to the application note. All the relevant peripheral or power sections in the application note includes checklist categorized as General, Schematic Review, and Additional. Board designers can use the checklist to do a self-review of the custom board design schematic to minimize possible errors that can cause functional or performance issues resulting in increased custom board.

Refer below FAQ for information on available checklists and format:

[\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM62D-Q1 / AM64x / AM243x Design Recommendations / Custom board hardware design - Schematics review checklists](#)

#### 1.1.5 FAQ Reference for Application Note Usage Guidelines

[\[FAQ\] AM625 / AM623 / AM62A / AM62Dx / AM62P / AM64x / AM243x Design Recommendations / Custom board hardware design - Custom Board Schematics Self Review](#)

## 1.2 Family Wise List of Processors

The application note applies to all the processors listed in the listed below. All relevant documents are available on the product pages on TI.com. Follow the processor page link below to access the product page.

### 1.2.1 AM62Px Processor Family

See the *Ordering and Quality* section for information on supported OPNs on the following product pages:

- [AM62P](#)
- [AM62P-Q1](#)

## 2 Related Collaterals

### 2.1 Links to Commonly Available and Applicable Collaterals

There are a number of documents relevant to the selected processor available on the processor-specific product page on TI.com. Before starting the custom board design, reading all the documents by the board designers is strongly recommended.

The below link summarize the collaterals that can be referred to when starting the custom board design.

[\[FAQ\] AM62P / AM62P-Q1 Custom board hardware design – Collaterals to Get started](#)

### 2.2 Hardware Design Considerations for Custom Board Design

Before start of the custom board design, the recommendation is to read through and take note of the recommendations in the processor-specific *Hardware Design Considerations for Custom Board Design* user's guide linked below:

[Hardware Design Considerations for Custom Board Design Using AM62P, AM62P-Q1 Family of Processors](#)

## 3 Processor Selection

### 3.1 Data Sheet Use Case and Version Referenced

Processor-specific data sheet includes pin attributes (pin-to-function mapping), signal descriptions, pin connectivity requirements, electrical characteristics, timing and switching characteristics, and timing diagrams for all the applicable processor peripherals and recommended operating conditions, power sequencing for all the processor supply rails.

**List of data sheet with revision number referenced during the document update:**

SPRSP89A – DECEMBER 2023 – REVISED DECEMBER 2024

For more information, refer to [\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM62D-Q1 / AM64x / AM243x Design Recommendations / Custom board hardware design - Current Data sheet revision, updates and usage notes](#).

### 3.2 Processor Selection (OPN Orderable Part Number)

To get an overview of the processor architecture and for selecting the processor (base production part number), features, package (AMH) and speed grade, see the *Functional Block Diagram* and *Device Comparison* sections of the processor-specific data sheet.

Refer to *Device Comparison* section, *Device and Documentation Support* section of the processor-specific data sheet to choose the required processor OPN.

The recommendation is to update the selected processor ordering part number in the schematics with the chosen OPN.

### 3.3 Peripheral Instance Naming Convention

For peripherals naming and instances, the processor-specific TRM tends to be *generic* and the processor-specific data sheet is *specific*.

In the data sheet, a suffix number is assigned, even when there is a single peripheral instance. Documents that reference the peripheral name do not need to change from processor to processor.

The suffix starts with 0. For the common platform Ethernet® switch 3-port gigabit (CPSW3G) port names, port 0 is the internal (communications port programming interface (CPPI) host) port of the switch.

### 3.4 Unused Peripherals

Peripherals that have a dedicated function have connectivity requirements when not used. Refer to the *Pin Connectivity Requirements* section of processor-specific data sheet for connecting unused peripherals. The connectivity requirements include recommendations to connect the power supplies and the interface signals.

Peripherals (processor IOs) that have alternate functions, when not used can be left unconnected when there are no connectivity requirements specified. The pad configurations can be the reset state configuration.

For more information, refer [\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM62D-Q1 / AM64x / AM243x Design Recommendations / Custom board hardware design - Data sheet Pin Attributes and Pin connectivity related queries](#)

### 3.5 Processor Ordering and Quality

For information related to ordering and quality for the selected processor family, see the links below:

[AM62P-Ordering and quality](#)

[AM62P-Q1-Ordering and quality](#)

### 3.6 Processor Selection Checklist

#### General

During the custom board schematic design process, review and verify the following collaterals and information:

1. Device selection (selected processor OPN (Orderable part number) based on the required features)

2. Pin attributes (Ball names, Signal names and the contents of each column including power) and pin mapping as per the data sheet
3. Pin connectivity requirements (for used and unused, peripherals)
4. Connection recommendations for RSVD (reserved) pins
5. Debug provision on-board for probing (OBSCLK and CLKOUT)
6. Errata related to the supported boot modes and the peripherals of interest
7. Recommended operating conditions, power-up and power-down sequencing for core, memory interface, analog and IO supplies
8. Electrical characteristics and timing information for selected peripherals
9. Application notes, Implementation recommendations, and Layout guidelines for selected peripherals

## 4 Power Architecture

For an overview, see the TI [Power management](#) page.

Additionally, the [WEBENCH® circuit designer tool](#) provides a visual interface that creates a customized power supply and active filter circuits.

### 4.1 Generating Supply Rails

The required supply rails for the selected processor are generated using integrated or discrete power architecture. Use of integrated power architecture (PMIC) simplifies design of processor-specific power architecture (power supplies). The PMIC generates commonly used supply rails to power the processor and the attached devices. Manages power-up sequencing, power-down sequencing, and supply slew rate control and meet the processor-specific power requirements. Along with the PMIC, use additional DC/DC converters and LDOs to generate additional on-board supplies, based on the use case.

Discrete power architecture provides flexibility in design and component selection. Board designer is responsible for power device selection that sources the required current, provides the required output voltages, supports the required load transient response, controls supply slew rate, and supply sequencing.

Processor power supply rails have slew rate requirements specified. Follow the section *Power Supply Slew Rate Requirement* of processor-specific data sheet for all the generated or switched supply rails.

The recommended family of devices and related collaterals for generating the on-board supplies using different power architectures are summarized in the next sections.

#### 4.1.1 AM62P , AM62P-Q1

##### 4.1.1.1 Power Management IC (PMIC)

PMIC that can be used for integrated power architecture includes [TPS65224-Q1](#). Space, performance, and the bill of materials (BOM) optimized power architecture is designed to power the processor and the attached devices.

For automotive functional safety use cases, connect MCU\_I2C0 of the processor to PMIC (TPS65224 / TPS65222) I2C1.

For implementation (without functional safety), refer to the [Starter Kit SK-AM62P-LP](#) schematic.

Refer to the following FAQs:

[\[FAQ\] TMUX1308-Q1: EN and Control inputs termination - AM62P, AM62A use case](#)

[\[FAQ\] AM62P / AM62P-Q1 Design Recommendations / Custom board hardware design – common queries for PMIC TPS65224-Q1](#)

Refer FAQ related to residual voltage and detection:

[\[FAQ\] AM625 / AM623 / AM62A / AM62D-Q1 / AM62P / AM64x / AM243x Design Recommendations / Custom board hardware design – Queries related to Residual Voltage and Detection](#)

#### 4.1.1.1.1 PMIC Checklist for TPS65224x

##### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links.
2. PMIC selection (orderable part number).
3. PMIC checklist for addition of required input and output capacitors including values, feedback configuration, and pin connections.
4. Voltage rating of the selected capacitors considering derating (> twice the worst-case applied voltage is a commonly used guideline).
5. Configuration of the recommended PMIC control and IO signals.
6. Provision to configure processor core voltage using GPIO3.
7. Connection of analog inputs to PMIC ADC inputs GPIO4 or GPIO5.
8. Naming of the supply rails (indicate configured output voltage level)
9. Matching of the PMIC voltage levels with the supply requirements for the processor and attached devices
10. Net name matches (same name) for processor and attached devices IO supplies

##### Schematic Review

Follow the below list for the custom schematic design:

1. Compare the custom PMIC implementation with the SK schematic implementation for capacitors and values, IOs connections, and DC/DC output feedback connection.
2. Core voltage configuration using GPIO3 (GPIO3 High -- BUCK1,2 : 0.85V, GPIO3 Low/Floating -- BUCK1,2 : 0.75V), VDD\_CORE and VDDR\_CORE sequencing, and provision for alternate core voltage configuration.
3. Processor to PMIC and PMIC to processor IO interface connections.
4. Connection of the required control signals for processor IO supply sequencing (load switch EN for processor and attached device IO supply voltage and output voltage slew rate control).
5. Processor and PMIC I2C interface used versus recommend, considering the use case.
6. PMIC nRSTOUT slew (pullup value) when connected directly to processor MCU\_PORz input (recommend using a discrete push-pull output buffer).
7. Configuration of other discrete DC/DC supplies and LDOs used along with the PMIC.
8. VPP supply (eFuse programming) external LDO implementation, output control and addition of bulk and decoupling capacitors considering load current transient and provision for isolation resistor for testing the VPP enable timing.
9. External Implementation of SD card supply supporting UHS-I speed
10. Connection of interrupt, EN/PB/VSESNS and sleep signals and connection of the required pulls for the PMIC IOs
11. Connection of analog inputs and input range for GPIO4 or GPIO5.

##### Additional

1. In case power architecture is based on TI PMIC, obtain a review of the implementation done with the PMIC business unit or product line.
2. A 0Ω resistor or jumper is recommended at the output of the supply rails for isolation or current measurement for the initial board build.
3. Show the PMIC input bulk capacitors connection for DC/DC inputs and VSYS separately and near to each of the pin separately for ease of placement and routing.
4. Reviewed and followed the FAQ related to residual voltage.

#### 4.1.1.1.2 Additional References

For more information, see the following sections in the processor-specific data sheet.

- Device Connection and Layout Fundamentals
- Power Supply
- Power Supply Designs



#### 4.1.1.2 Discrete Power

Use a discrete power architecture to generate the processor and the attached devices supply rails. Discrete power architecture is based on DC/DC converters and LDOs. Implement the power sequence using the power good output and discrete logic.

When custom discrete power architecture is used, take note of the MCU\_PORz (L->H) hold time (delay) (for oscillator start-up) requirements after all the supplies ramp specified in the data sheet.

MCU\_PORz active (low) during power-up until the supplies are valid (using external crystal circuit) plus minimum delay of 9.5ms or MCU\_PORz active (low) at power-up until the supplies are valid and external clock is stable (when using external LVCMOS clock source).

Currently there are no recommended discrete power architecture implementations, the recommendation can change in the future. See the processor ([AM62P](#) , [AM62P-Q1](#)) product page on TI.com for additional information.

##### 4.1.1.2.1 DC/DC Converter

Consider DC/DC converters such as the [TPS62826](#) or [LM61460-Q1](#) devices.

For an overview of the DC/DC converters available, see the [AC/DC & DC/DC converters \(integrated FET\)](#) page.

Additionally, refer below:

[Quick Reference Guide To TI Buck Switching DC/DC Application Note](#)

[Power Supply Design training resources - Video library](#)

##### 4.1.1.2.2 LDO

Consider LDO devices such as [TPS74518](#), [TLV7103318](#), [TLV75518](#).

For an overview of the LDOs available, see the TI [Linear and low-dropout \(LDO\) regulators](#) page.

Additionally, refer below:

[Low Dropout Regulators Quick Reference Guide](#)

[Linear Regulator Design Guide For LDOs](#)

[A Topical Index of TI LDO Application Notes](#)

##### 4.1.1.2.3 Discrete Power Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above section, including relevant application notes.
2. The configured output voltage and the required current rating for all the supply rails.
3. Output voltage feedback connection and feedback divider resistors tolerance.
4. Selected discrete DC/DC architecture supports active discharge.
5. DC/DC output supplies slew rate meets the processor requirements and sequencing of all the supply rails as per the processor requirement.
6. MCU\_PORz input (PG output) slew rate (connect through discrete push-pull output buffer) and L to H delay (MCU\_PORz input low hold time) implementation after all the supplies ramp.
7. Voltage rating of the selected capacitors considering derating (> twice the worst-case applied voltage is a commonly used guideline).
8. Device selection including output voltage level and current rating, active discharge capability, residual voltage detection (Allow to power-up only when the supply voltages are < 0.3V after power-down)
9. Implementation of SD card interface IO supply supporting UHS-I speed and eFuse programming VPP supply.
10. Naming of the supply rails (indicate configured output voltage level)
11. Matching of the PMIC voltage levels with the supply requirements for the processor and attached devices
12. Net name matches (same name) for processor and attached devices IO supplies



## Schematic Review

Follow the list below for the custom schematic design:

1. The resistor divider value including tolerance connected to the feedback input to generate the required output supply voltage matches with the calculated value.
2. PG outputs have the required pullup and connects to the other DC/DC or LDO EN for supply sequencing.
3. DC/DC or LDO output supply rails slew rate
4. MCU\_PORz input low hold time after supplies ramp, in case the DC/DC PG output connects directly to the processor MCU\_PORz input.

### Additional

1. In case power architecture is based on TI power, obtain a review of the implementation done with the relevant business unit or product line
2. A 0Ω resistor or jumper is recommended at the output of the supply rails for isolation or current measurement for the initial board build

## 4.2 Power Control and Circuit Protection

### 4.2.1 Load Switch (Power Switching)

Load switches are used to control (turn on and off) power to a specific peripheral or sub-system powered by the same supply rail, instead of using multiple DC/DC converters or LDOs to generate the supply. In some applications, there is a recommended power-up and power-down sequence that must be followed. Load switches simplifies the implementation of power sequencing to meet the power-up and power-down sequence requirements. The load switch enable is controlled by the PMIC or DC/DC converter PG to meet the processor power sequencing requirements.

Consider load switches such as [TPS22965](#), [TPS22918](#), [TPS22902](#), and [TPS22946](#).

For an overview of the load switches available, see the TI [load switches](#) page.

#### 4.2.1.1 Load Switch Checklist

##### General

Review and verify the following for the custom schematic design:

1. Above section, including relevant application notes and FAQ links
2. Load switch current rating
3. Sequencing of the load switch enable (PMIC GPIO or DC/DC PG)
4. Output voltage slew rate configuration
5. Voltage rating of the selected capacitors considering derating (twice the applied voltage is a commonly used guideline)

### Schematic review

Follow the below list for the custom schematic design:

1. Input and output capacitor values and voltage rating
2. Output voltage slew rate is configured (capacitor value selection) per the processor IO supply slew rate requirements

### 4.2.2 eFuse IC (Power Switching and Protection)

eFuse power switching and protection ICs are integrated power path protection devices that are used to limit circuit current and voltages to a safe level during fault conditions. eFuses offer many benefits to the design and include protection features that are often difficult to implement with discrete components. For an overview of the eFuses available, see the TI [eFuses and hot swap controllers](#) page.

## 5 General Recommendations

The below general recommendations section contains the recommendations and guidelines for board designers to be familiar while designing the custom board.

### 5.1 Processor Performance Evaluation Module (SK - Starter Kit)

Processor (hardware) performance evaluation modules and platforms (SKs) are not reference designs, the modules and platforms do not represent a proper or complete board or system implementation. In many cases, the SKs are partially or completely designed and released for fabrication before the processor design is complete. The time line is so that a hardware platform is available when the first silicon arrives. New processor requirements come up during processor bring-up and bench validation. All the new requirements are not accounted for in the hardware evaluation platform. Therefore, TI expects board designers to carefully review and follow all requirements defined in the processor-specific data sheet, silicon errata, and TRM when designing the custom board.

Processor (hardware) performance evaluation platforms are not designed to be comprehensive of any board or system specific requirements, such as EMI or EMC purposes (reduce radiated emissions), noise susceptibility, thermal management, and so forth.

See the following FAQ for design update notes that board designers can refer along with the SK schematics:

[\[FAQ\] AM625 / AM623 / AM62A Common design Errors / Recommendations for Custom board hardware design – SK Schematics Design Update Note.](#)

#### 5.1.1 Evaluation Module Checklist

##### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. SK referenced matches the selected processor family
3. Processor package on the referenced SK board matches with the processor selected for custom board design
4. The SK schematic revision referenced includes D-Notes, R-Notes, and CAD Notes

### 5.2 Processor-Specific SK Versus Data Sheet

In case of any discrepancy between the processor-specific SK and the data sheet during evaluation or the custom board design, follow the data sheet. Despite the best efforts by the board designer, the SK can contain errors that still function but are not completely aligned with the data sheet specifications.

#### 5.2.1 Notes About Component Selection

Selection of SK components is not always optimized. Review the BOM and optimize the component selection based on the data sheet recommendations, application requirements, and board circuit design.

Design calculations, design review, and performing board level tests and measurements as required is recommended before finalizing the components value and ratings (such as voltage and power).

##### 5.2.1.1 Series Resistor

The recommended values for the series resistors are a starting point for board designers. Verify the values on the board and adjust accordingly (step function that occurs on the pin is not near the mid-supply).

##### 5.2.1.2 Parallel Pull Resistor

Provide provision for adding parallel pulls to the processor IOs. Parallel pull polarity and the values depend on the specific peripheral connectivity recommendations, recommendations for improved processor performance, and relevant interface or standards requirements.

Processor-specific SK pull values can be used as a starting point and board designer can select the appropriate pull values based on the recommendations for the processor and attached device, or specific board design implementation.

When traces are connected to the processor IO pads and is not being actively driven, a parallel pull is recommended. Pull polarity is design use case dependent. During reset, processor IO buffers are off and the IOs are in a high impedance state, effectively serving as an antenna that picks up noise. Without any termination, the IOs are high impedance. High impedance makes noise easy to couple energy on the floating signal trace and develop a potential that can exceed the recommended operating conditions, which creates an electrical over-stress (EOS) on the IOs. Electrostatic discharge (ESD) protection circuits inside the processor are designed to protect the device from handling before being installed on a PCB assembly.

### 5.2.1.3 Drive Strength Configuration

TI currently does not support configuring any other drive strength besides the nominal (default) value for SDIO and LVCMOS buffers, as the nominal value is the only configuration at which chip-level STA (Static Timing Analysis) is closed. The nominal value corresponds to a 40Ω for SDIO and 60Ω for LVCMOS. Processor family implement a dedicated eMMC PHY and the nominal impedance is set to 50Ω. The IBIS model has been updated to contain only drive strengths where the timing is closed internally.

Refer below FAQ for information related to drive strength configuration support:

[\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM62D-Q1 / AM64x / AM243x Design Recommendations / Custom board hardware design - I/O Drive Strength Configuration for SDIO and LVCMOS](#)

### 5.2.1.4 Data Sheet Recommendations

The board designers are responsible for implementing whatever precautions are necessary or required to establish that the custom board design does not violate the requirements specified in the processor-specific data sheet. Example processor requirements include I2C Open-Drain and Fail-Safe (I2C OD FS) Electrical Characteristics - Input Slew Rate.

When data sheet recommendations are not available, use recommendations provided in the following checklist or implementation in the SK schematic as a starting point.

### 5.2.1.5 Processor IOs - External ESD Protection

An external ESD protection is recommended to any of the processor IOs connected directly to an external connector or exposed to external inputs, because internal ESD protection circuit were not designed to handle the board level ESD requirements. For an overview of the ESD protection devices, see the TI [ESD protection](#) page.

### 5.2.1.6 Peripheral Clock Output Series Resistors

Series resistor on the clock output near to the processor clock output pin is required to resolve issues with signal distortion at the source of the clock since the clock output is also used for retiming. For MMCx and OSPI, an unbonded pad is used (internal), so series resistor is not a requirement. In some cases, a low value series resistor is added for signal integrity purpose. The recommendation is to have the series resistor as a place holder just in case the resistor is needed for improving signal integrity.

### 5.2.1.7 Component Selection Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes
2. Selection of resistor values, tolerance, size and wattage
3. Only specific resistors need 1% tolerance (refer to the processor or attached device data sheet, SK schematics, or EVMs)
4. Standard tolerance resistors can be used for other use cases, example: pullup, pulldown or series resistor
5. Compare the pull values on the custom board with the SK schematics
6. Voltage rating of the capacitors used to include derating (twice the applied voltage is a commonly used guideline)
7. Voltage rating of capacitors considering DC bias effect (to be within the recommended value)
8. Package selection (application and use case dependent, consider voltage and temperature range)
9. Selection of compatible attached devices (DDR and flash memory, EPHY)

10. Recommended memory size, selection of required memory size (DDR) and providing provision for expanding the memory as required
11. Reviewed the FAQ related to passive components value, tolerance and voltage rating

Reference the below FAQ as a starting point for information on key components used on the EVMs and SKs, component values and tolerances:

[\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM64x / AM243x Design Recommendations / Custom board hardware design - Starter kit / EVM variants \(versions\) and Key components list](#)

[\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM64x / AM243x Design Recommendations / Custom board hardware design - Queries related to passive components values, tolerance, voltage rating](#)

## 5.2.2 Additional Information Regarding Reuse of SK Design

### 5.2.2.1 Updated SK Schematic With Design, Review and CAD Notes Added

During custom board design, designers frequently reuse the SK design files and edit the design file. Alternatively, designers reuse common implementations, including processor, memory and communication interfaces. The SK is expected to have additional functions, so designers optimize the SK implementation to fit board design requirements. While optimizing the SK schematics, errors are introduced into the custom design that cause functional, performance or reliability problems. When optimizing, designers have queries regarding the SK implementation, resulting in design errors. Many of the optimization and design errors are common across designs. Based on the multiple board designers inputs and data sheet pin connectivity recommendations, comprehensive Design Notes (D-Note), Review Notes (R-Note) and CAD Notes (CAD-Note) are added near each section of the SK schematic for designers to review and follow to minimize errors. As part of the design downloads, additional files are included to support evaluation.

The list of documents that can be download on TI.com for each of the SK is listed in the product overview document below.

#### 5.2.2.1.1 AM62P, AM62P-Q1

[SK-AM62P-LP Design Package Folder and Files List Product Overview](#)

#### 5.2.2.2 SK Design Files Reuse

Based on the design approach followed during the custom board design and project schedule, the SK design files can be reused as a starting point to make the required updates. The recommendation is to verify the SK implementation and component selection.

The following link summarize the considerations board designers are required to be familiar with when reusing TI SK design files.

[\[FAQ\] AM62P / AM62P-Q1 Custom board hardware design - Reusing TI SK \(EVM\) design files](#)

#### 5.2.2.2.1 Reuse of SK Design Checklist

### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Latest version of the selected or required SK design is referenced
3. D-Notes and R-Notes are considered
4. Resetting of component DNIs configuration when saved as a different project or the schematic pages or circuit sections are rearranged
5. The change in connections including off-page connections when the schematics design is translated to an alternate CAD tool

## 5.3 Before Beginning the Design

### 5.3.1 Documentation

During the custom board design cycle, the recommendation is to refer to or use the latest version of the documentation, examples include the processor-specific data sheet, silicon errata, TRM, and other commonly referenced design collaterals. Verify the processor-specific product page for the latest available documents or addition of new documents.

Tips for documentation search: Search the documentation for words such as: *recommended*, *require*, *do not*, *note*, *pin connectivity*, and so forth. Important criteria for the processor typically contain one or more words.

Tips to get updated information: On a TI.com processor product page, there is a *Notifications* button. Registering at the button enables automatic notification of processor documentation changes.

### 5.3.2 Processor Pin Attributes (Pinout) Verification

Verify the following pin attributes

- Processor pin label corresponds to the correct pin numbers listed in the *Pin Attributes* section of the processor-specific data sheet. Maintain the data sheet names in the symbol and change the function (net) names per the application use case.
- Supply voltages that are connected to the processor power pins are within the *Recommended Operating Conditions*.
- All the processor pins (grouped into functions and having separate symbol blocks) including reserved pins are include in the schematics to minimize tool related and functional errors.
- Most of the processor IOs TX (Output) and RX (Input) buffers and pulls are turned off during reset. External pull resistors are recommended to hold inputs of any attached device in a valid logic state until software initializes the IOs when a TP or trace is connected and IOs are not being actively driven. Use of pull resistor depends on the attached device IO capabilities.
- For improved performance of custom board, recommendations include implementing external monitoring of voltage, current, or temperature.

Refer below FAQ for queries related to processor data sheet pin attributes.

[\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM62D-Q1 / AM64x / AM243x Design Recommendations / Custom board hardware design - Queries related to SOC data sheet Pin Attributes](#)

### 5.3.3 Device Comparison, IOSET and Voltage Conflict

Refer to the note regarding shared IO pins in the *Device Comparison* section of the processor-specific data sheet. IOSETs are a grouping of signals specific to an interface that are timed as a set. The processor is timing closed using IOSETs. Any interface that has IOSETs must select all interface signals from the same IOSET. Some interface signals can be shared over multiple IOSETs. The valid pin combinations are detailed in the SysConfig-PinMux tool.

Refer below FAQ for information on Voltage conflict and IOSET:

[\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM62D-Q1 / AM64x / AM243x Design Recommendations / Custom board hardware design - Queries related to SysConfig-PinMux IOSET and Voltage Conflict](#)

### 5.3.4 RSVD Reserved Pins (Signals)

Pins named RSVD are Reserved. Leave the RSVD pins unconnected (no TP connected) as recommended in the data sheet.

Recommendations are to not connect any PCB trace or test points to RSVD pins.

For more information, see the [\[FAQ\] AM625 / AM623 / AM625SIP / AM625-Q1 / AM620-Q1 Custom board hardware design – Connection recommendations for RSVD pins](#). The FAQ is generic and can also be used for AM62P, AM62P-Q1 processor family.

### 5.3.5 Note on PADCONFIG Registers

Many of the processor IOs support multiplexing of functions. The IO function is chosen from multiple functions. The list of functions available for each pad is enumerated in the *SIGNAL NAME* column in the *Pin Attributes* table of the processor-specific data sheet.



The required function is selected through the MUXMODE field of the associated pad configuration register. The PADCFG\_CTRL0\_CFG0\_PADCONFIG0 to PADCFG\_CTRL0\_CFG0\_PADCONFIG150 registers control the signal multiplexing of IOs in the processor Main Domain and MCU\_PADCFG\_CTRL0\_CFG0\_PADCONFIG0 to MCU\_PADCFG\_CTRL0\_CFG0\_PADCONFIG33 registers control the signal multiplexing of IOs in the processor MCU Domain.

The *Pad Configuration PADCONFIG Registers* table in the *Pad Configuration Registers* section of the processor-specific TRM summarizes the Bit Field Reset Values for all the PADCONFIG registers. Follow the notes listed at the end of the table while configuring the PADCONFIG registers. Never set the RXACTIVE bit without a valid logic state sourced to the pin that is associated with the respective PADCONFIG register. A floating input can damage the processor or affect reliability.

### 5.3.6 Processor IO (Signal) Isolation for Fail-Safe Operation

In case the processor and the attached devices or an additional host are powered by different power sources, signal isolation is recommended because most of the processor IOs are not fail-safe. The recommendations are to route the signals through a FET bus switch circuit designed to automatically isolate the two devices anytime the IO power is not valid for both devices. The FET bus switch and control logic are recommended to be powered from an always-on power supply and only enabled by an AND function of power good signals from different power sources.

### 5.3.7 Reference to Processor-Specific SK

When specific recommendations are not available in the processor-specific data sheet, for implementation examples and values, see the processor-specific SK, as applicable.

### 5.3.8 High-Speed Interface Design Guidelines

For detailed recommendations on USB2.0 and CSI-Rx signals connection and routing, see the [High-Speed Interface Layout Guidelines](#). Include appropriate constraints or routing requirements to be followed during the custom board design.

For USB interface, a common-mode choke can be added to improve the custom board performance when operating in harsh industrial environments. Adding common-mode choke can reduce the signal amplitude and degrade performance. Add provisions to bypass the common-mode choke using  $0\Omega$  resistors. Consider adding external ESD protection based on the application requirement.

### 5.3.9 Recommended Current Source or Sink for LVCMOS (GPIO) Outputs

The DC current outputs sourced need to remain less than the maximum  $I_{OH}$  and  $I_{OL}$  values defined to achieve the  $V_{OL}$  maximum and  $V_{OH}$  minimum values defined in the *Electrical Characteristics* table. The recommendation is to not source or sink currents above the limits defined in the processor-specific data sheet. The preferred DC current source or sink is to be significantly less than the limits as to not increase thermal or other problems.

Switching high levels of current can create electrical noise that can couple to other circuits and require additional decoupling capacitors on the respective IO power rail.

### 5.3.10 Connection of Slow Ramp Inputs or Capacitors to LVCMOS IOs (Inputs or Outputs)

LVCMOS inputs have slew rate requirements specified. Connecting slow ramp signal directly to the LVCMOS inputs or capacitors at the LVCMOS inputs is not recommended. When a slow ramp input is applied, CMOS input has shoot-through current that flow from VDD through the partially turned on P-channel transistor and the partially turned on N-channel transistor to VSS, when the input is at mid-supply. Accumulated exposure to slow ramps results in performance or reliability concerns.

LVCMOS output buffers are not designed to drive large capacitive loads. When LVCMOS type IOs are configured as output and connected to capacitor, follow the data sheet recommendations for the allowed capacitor value or add series resistor to limit the IO output current or perform simulations.

### 5.3.11 Queries and Clarifications Related to Processor During Custom Board Design

For queries and clarifications related to processor selection, features and guidelines, TI recommends using the [E2E](#) forum. Use E2E to ask questions or refer to related questions and previous answers.

### 5.3.12 Before Beginning the Design Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Processor schematics symbol used on custom board schematic follows the ball name, pin numbers and IOSET grouping recommendations for specific peripherals per the corresponding processor data sheet *Pin Attributes* section
3. The required IO functions and PAD configuration are considered
4. Fail-safe operation and loading requirements for processor IOs are considered
5. Buffering of the processor IOs(outputs) based on the use case - to drive higher load
6. Latest version of the selected SK design is referenced

#### Additional

1. Refer to the relevant collaterals on TI.com to minimize design errors and optimize design efforts
2. Frequently check for the latest revision on TI.com for documents of interest
3. Use E2E to seek clarification

### 5.3.13 Device Recommendations

TI does not make device recommendations.

The recommendation is to follow the *DDR Electrical Characteristics* section of the data sheet for selection of LPDDR4 memory.

The MMCSD host controller and PHY associated with the MMC0 are designed in compliance with the standard, as described in the data sheet and TRM.

The recommendation is to follow the *MMC0 - eMMC/SD/SDIO Interface* section of the data sheet when selecting the eMMC/SD card.

Reference [\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM64x / AM243x Design Recommendations / Custom board hardware design - Starter kit / EVM variants \(versions\) and Key components list](#) as a starting point for key components used on the EVMs and SKs.



## 6 Processor-Specific Recommendations

### 6.1 Common (Processor Start-Up) Connection

#### 6.1.1 Power Supply

Follow the recommendations listed below:

- The power requirement for each of the supply rail varies based on the interfaces used and the operating environment.
- The current draw of processor supply rails is estimated using the *Power Estimation Tool (PET)*. If the supply rail powers the other on-board attached (peripheral) devices, include the maximum current draw of the devices.
- For power supply sizing and information on the maximum current rating for different supply rails, check processor ([AM62P](#) / [AM62P-Q1](#)) product page.
- Verify the output current ratings of the selected power architecture (including PMIC, DC/DC converters and LDOs) meet the maximum current requirements of processor and all attached devices. Add additional margins for design variances.
- Verify the recommended power supply sequence (power-up and power-down) is followed. For the recommended power sequencing requirements, refer to the *Power Supply Sequencing* section of processor-specific data sheet.

For processor *Recommended Operating Conditions (ROC)*, see the [\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM64x / AM243x Design Recommendations / Custom board hardware design – SOC ROC Recommended Operating Condition](#).

Here are some guidelines that needs to be considered when selecting or designing the processor power architecture:

1. Power supplies are configured to the required voltage level and are supplies are within the ROC.
2. Power architecture follows the power-up and power-down sequence as specified in the processor data sheet.
3. Power architecture meets the supply slew rate requirements specified in the processor data sheet.
4. All the power supplies are available before the MCU\_PORz is released.
5. Monitoring of all the supply rails. Make sure the supplies are enabled only after the voltages are below 0.3V (no residual voltage) after a power cycle.
6. The delay between the power supply ramp and the MCU\_PORz high is as per the data sheet recommendations (9.5ms min).
7. MCU\_PORz input slew is as minimum as possible to avoid internal reset circuit glitch.

Refer to the FAQ-related to residual voltage and detection:

[\[FAQ\] AM625, AM623, AM62A, AM62D-Q1, AM62P, AM64x, AM243x Design Recommendations. Custom board hardware design – Queries related to Residual Voltage and Detection](#)

#### 6.1.1.1 Supply for Core and Peripherals

For proper operation, connect all power pins (balls) with the supply voltages recommended in the *Recommended Operating Conditions* section of the processor-specific data sheet. Power pins that have specific connectivity requirements are specified in the *Pin Connectivity Requirements* section of the processor-specific data sheet.

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#### Note

Powering the MCU domain and the Main domain independently is not an option. The processor family does not have separate MCU and Main power domains. All power rails need to be powered and sequenced as defined in the processor-specific data sheet. The concept of MCU and Main applies to internal device functions and processor domains.

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#### 6.1.1.1.1 Power Supply Ramp (Slew Rate) Requirement and Dynamic Voltage Scaling / Change

All power supplies associated with the processor must allow for controlled supply ramp (supply slew rate). For more information, see the *Power Supply Slew Rate Requirements* section of the processor-specific data sheet.

## The processor (family) does not support dynamic voltage scaling.

See [\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM64x / AM243x Design Recommendations / Custom board hardware design – Dynamic Voltage Scaling](#) for more information about dynamic voltage scaling (DVS) and dynamic frequency scaling (DFS).

### 6.1.1.1.2 AM62P, AM62P-Q1

Core supplies VDD\_CORE, VDDA\_CORE\_CSI\_DSI, VDDA\_CORE\_DSI\_CLK, VDDA\_CORE\_USB, and VDDA\_DDR\_PLL0 are recommended to be powered from the same power source and are operated at 0.75V or 0.85V, valid operating ranges are defined in the ROC table. When supplies are operating at 0.75V, the recommendation is to ramp 0.75V before all 0.85V supplies.

Core supplies VDD\_MMC0 and VDDA\_0P85\_DLL\_MMC0 are specified to operate at 0.85V when MMC0 is used. The recommendation is to connect VDD\_MMC0 and VDD\_0P85\_DLL\_MMC0 to the same power source as VDD\_CORE when MMC0 is not used.

VDDR\_CORE is specified to operate only at 0.85V. When VDD\_CORE is operating at 0.85V, VDD\_CORE and VDDR\_CORE are recommended to be powered from the same source (ramp together).

The recommendation is to always connect the VDDS\_OSC0 and VDDA\_MCU supplies.

The processor includes multiple analog supply pins that provide power to sensitive analog circuitry like VDDA\_MCU, VDDA\_PLLx [x = 0-4], VDDA\_1P8\_CSI\_DSI and VDDA\_1P8\_OLDIO. Filtered (ferrite) power supplies are recommended.

For more information, see the *Recommended Operating Conditions* and *Power Supply Sequencing* sections of the processor-specific data sheet.

### 6.1.1.1.3 Additional Information

For more information on processor power-sequencing requirements, see [\[FAQ\] AM625 / AM623 Custom board hardware design – Processor power-sequencing requirements for power-up and power-down](#)

For more information on processor power supply rails filtering using ferrite, see [\[FAQ\] AM625 / AM623 Custom board hardware design – Ferrite \(power supply filter\) recommendations for SoC supply rails](#)

The FAQs are generic and can also be used for AM62P, AM62P-Q1 processor family.

### 6.1.1.1.4 Processor Core and Peripheral Core Power Supply Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes, signal description, and electrical specifications
3. Recommended voltages are applied to the core VDD power supply rails 0.75V or 0.85V
4. Refer *Power-Up Sequencing – Supply / Signal Assignments* section of the processor-specific data sheet for sequencing the core supplies when partial IO low power mode is used and when partial IO low power mode is not used.
5. The potential applied to VDDR\_CORE must never exceed the potential applied to VDD\_CORE +0.18V during power-up or power-down. The sequencing requires VDD\_CORE to ramp up before VDDR\_CORE and ramp down after VDDR\_CORE when VDD\_CORE is operating at 0.75V
6. Power VDD\_CORE and VDDR\_CORE from the same source to ramp together when the VDD\_CORE is operating at 0.85V
7. Connection of core supply when specific peripheral is not used as per pin connectivity requirements
8. Connection of core supply (CSIRX0, DSITX0), when a specific peripheral is unused but the boundary scan function is required, as per pin connectivity requirements
9. Connection of VDD\_MMC0 when eMMC is used or when eMMC is not used

#### Schematic Review

Follow the below list for the custom schematic design:

1. Compare the implementation of the bulk and decoupling capacitors for all the supplies rails with SK schematics
2. Ferrite filters are provided for peripheral core supplies (CSI, USB, CANUART) as per the SK schematics
3. When peripherals are unused but the boundary scan function is required, ferrites and bulk capacitors are optional for peripheral core supplies
4. Supply rails connected follow the ROC
5. Connection of VDD\_MMC0 to VDD\_CORE when eMMC is not used

### Additional

1. For all supply rails, place a 0Ω resistor or jumper for isolation or current measurement at the output of the supply rails
2. Changing the core voltage is not allowed after the device is released from reset. If the core supply is turned off, turn off and ramp down all power rails per the power-down sequence and wait until all supply rails decay below 300mV before turning on power again
3. When the USB driver is not initialized and the USB calibration procedure does not happen, connecting the supplies and leaving all of the USB pins for USB0, USB1, or both is acceptable. Grounding the USB supplies per pin connectivity requirements when both USB interfaces are unused saves power when low power is a critical requirement
4. Follow the processor-specific SK for implementation of ferrites and capacitors
5. Dynamic voltage scaling (DVS) of the core supplies is not supported (not allowed or recommended)

#### 6.1.1.1.5 Peripheral Analog Power Supply Checklist

### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes, signal description and electrical specifications.
3. Recommended voltages are applied to the peripheral analog power supply rail 1.8V.
4. Supply rail connections are based on the processor family:

AM62Px: VDDS\_MMC0, VDDA\_MCU, VDDS\_OSC0, VDDA\_PLL0, VDDA\_PLL1, VDDA\_PLL2, VDDA\_PLL3, VDDA\_PLL4, VDDA\_1P8\_CSI\_DSI, VDDA\_1P8\_OLDIO, VDDA\_1P8\_USB, VDDA\_TEMP0, VDDA\_TEMP1, VDDA\_TEMP2, VMON\_1P8\_SOC.

5. Supply rail VDDA\_3P3\_USB 3.3V analog supply connection for supporting USB2.0 interface.
6. Connection of peripheral analog supply when specific peripheral is not used as per pin connectivity requirements.
7. Connection of peripheral analog supply (CSIRX0 and DSITX0), when specific peripheral is unused but boundary scan function is required as per pin connectivity requirements.

### Schematic Review

Follow the below list for the custom schematic design:

1. Compare bulk and decoupling capacitor for all the supplies rails with SK schematics.
2. Ferrite filters are provided for peripheral analog supplies (CSI, DSI, PLL, USB (1.8V), MCU), as per the SK schematics.
3. When specific peripherals are not used and boundary scan function is required, ferrites and bulk capacitors are optional.
4. Supply rails are connected and follow the ROC.

### Additional

1. For all supply rails, use a 0Ω resistor or jumper for isolation or current measurements at the output of the supply rails.
2. When the USB driver is not initialized and the USB calibration procedure does not happen, connecting the supplies and leaving all of the USB pins for USB0, USB1, or both is acceptable. Grounding the USB supplies

per pin connectivity requirements when both USB interfaces are unused saves power when low power is a critical requirement.

3. Follow the processor-specific SK for implementation of ferrites and capacitors.
4. Dynamic voltage scaling (DVS) of the analog supplies is not supported (not allowed or recommended).

### 6.1.1.2 Supply for IO Groups

[\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM64x / AM243x Design Recommendations / Custom board hardware design – CAP\\_VDDSn](#) CAP\_VDDSn provides recommendations on CAP\_VDDSn, capacitor value, and the effect of the capacitor mounted or shorted status.

#### 6.1.1.2.1 AM62P, AM62P-Q1

The processor includes eight dual-voltage IO supply for IO groups (VDDSHVx [x = 0-3, 5-6]), IO supply for IO CANUART (VDDSHV\_CANUART) and IO supply for IO MCU (VDDSHV\_MCU), and each group provides power supply to a fixed set of IOs. Each IO group is configured for 3.3V or 1.8V independently. The group configuration determines a common operating voltage for the entire set of IOs powered by the respective IO group power supply.

Processor pads (pins) designated as CAP\_VDDSn [n = 0-3, 5-6], CAP\_VDDSn\_CANUART, and CAP\_VDDSn\_MCU connect the external capacitor to the internal IO supply for IO group regulator when the IO supply for IO groups connect to 3.3V supply (optional when IO groups supplies connect to 1.8V). A 1µF capacitor connected between the pins and VSS is recommended. See the processor-specific data sheet for the recommended capacitor voltage rating and allowed capacitance range. When IO supply for IO groups are connected to 3.3V, the voltage to be considered for capacitor DC bias effect derating is the steady state DC output which is voltage applied to VDDSHVx/2.

To minimize the loop inductance requirements, place the capacitors on the back side of the PCB in the array of the BGA. The choice of capacitor voltage rating influences capacitor package (size) selection.

Select capacitor with ESR < 1Ω, keep the trace loop inductance < 2.5nH.

#### 6.1.1.2.2 Additional Information

Most of the processor IOs are not fail-safe. For information on fail-safe IOs, see the processor-specific data sheet. Power the IO supply of attached devices from the same power source as the respective processor dual-voltage IO supply for IO groups (VDDSHVx supply rail) to verify that the board never applies potential to an IO that is not powered. Taking care of fail-safe operation is recommended to protect the IOs of processor and attached devices.

For more information on power-sequencing requirements between processor and attached devices including signal isolation for fail-safe operation, see [\[FAQ\] AM625 / AM623 Custom board hardware design – Power sequencing between SOC \(Processor\) and the Attached devices](#). The FAQ is generic and can also be used for AM62P, AM62P-Q1 processor family.

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#### Note

Verify that a valid supply voltage for the VDDSHVx is present before applying inputs to the associated processor IOs or peripherals.

Connect the VDDSHVx supplies and associated CAP\_VDDSn (when IO supply connected is 3.3V, optional for 1.8V) capacitor irrespective of the usage of the processor IOs or peripherals.

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#### 6.1.1.2.3 Supply for IO Groups Checklist

##### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes, signal description, and electrical specifications.
3. Electrical characteristics and additional available information.

4. A valid fixed supply source is connected to (VDDSHV\_CANUART, VDDSHV\_MCU, VDDSHV0, VDDSHV1, VDDSHV2, VDDSHV3) all the IO supply for IO groups as per the ROC.
5. A valid supply (that can be dynamically changed) source is connected to VDDSHV5, VDDSHV6 as per the ROC.
6. Slew rate requirements for IO supply rails are followed.
7. Internal LDO output pins have the recommended capacitors connected (across CAP\_VDDSn pin and VSS).
8. Power sequence recommendations as per the processor data sheet are followed.

## Schematic Review

Follow the list below for the custom schematic design:

1. Connection of the recommended capacitor to CAP\_VDDSn pins and VSS.
2. CAP\_VDDSn capacitor package (use the smallest possible (0201 or greater package possible which is closest to 0201) package to minimize loop inductance).
3. Voltage rating of the capacitor selected for the capacitance value to be in the range 0.8 to 1.5 $\mu$ F including aging, temperature and DC bias effect.
4. All IO supply rails have a valid supply irrespective of the use of the IOs.
5. Supply rails connected follow the ROC.
6. Each CAP\_VDDSn pin requires a separate 1 $\mu$ F capacitor connected with respect to VSS (ground).
7. Select CAP\_VDDSn capacitor with < 1 $\Omega$  ESR, keep the trace loop inductance < 2.5nH.

## Additional

1. For all supply rails, use a 0 $\Omega$  resistor or jumper for isolation or current measurement at the output of the supply rails.
2. When any of the VDDSHVx power rails are sourced from the 3.3V supply, all IOs referenced to the VDDSHVx must operate at 3.3V IO level. If a VDDSHVx power rail is sourced from a 1.8V supply, all IOs referenced to the VDDSHVx must operate at 1.8V IO level.
3. Some interfaces span multiple VDDSHVx, for example MMC2 and GPMC. When using one of the interface, all VDDSHVx domains supporting a specific interface need to share the same voltage source.
4. Most processor IOs are not fail-safe. Applying input voltage to the IOs while the corresponding VDDSHVx supply is off is not allowed or recommended.
5. Verify all IO pins on each VDDSHVx (or VDDSHV\_MCU) only connects to a single voltage level.
6. Follow the processor-specific SK for implementation of ferrites and capacitors.
7. Leaving VDDSHV5 rail unconnected is not recommended. Connect the power pins to either 1.8V or 3.3V, depending on the use case.

### 6.1.1.3 Supply for VPP (eFuse ROM Programming)

An important requirement is for the processor VPP (eFuse ROM programming supply) to remain within the ROC range during eFuse programming. An LDO powered from a higher input voltage supply (2.5V or 3.3V) is recommended to compensate for the voltage drop through the series pass transistor and maintain the correct operating voltage during high load current transients. Local bulk capacitors are recommended near the processor VPP pin to support the LDO transient response.

Powering VPP from a supply rail with a  $\pm 5\%$  variation, or using a load switch or FET can be problematic due to high load current transients and the requirement for the VPP power rail to match the supply range. Load switch or FET topology does not account for the voltage drop going through the load switch. The load switch can be an option if the board designer uses power source with smaller variation, such that the supply variation combined with the voltage drop through the load switch never exceeds the VPP recommended operating range.

For more information, see [\[FAQ\] AM625 / AM623 / AM625SIP / AM625-Q1 / AM620-Q1 Custom board hardware design – Queries regarding VPP eFuse programming power supply selection and application](#). The FAQ is generic and can also be used for AM62P, AM62P-Q1 processor family.



### 6.1.1.3.1 VPP Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes, signal description and electrical specifications.
3. Electrical characteristics and additional available information.
4. Implementation of on-board supply or provision provided to connect external supply.
5. An LDO is recommended (use of FET switch or load switch is not allowed or recommended).
6. Choose on-board LDO that supports a minimum of 400mA current, has excellent load current transient response, and quick output discharge (active discharge).
7. Required bulk and bypass capacitors are provided (follow SK schematics).
8. On-board LDO has provision to be enabled by processor IO.
9. When external supply is connected, add bulk and decoupling capacitor provision on the processor board near to the processor VPP pin and provided a TP to connect the external supply.
10. External supply follows the recommended power sequence and slew rate requirements as per the data sheet.
11. The external supply timing is controlled by the processor IO.
12. Leave the processor VPP supply pin floating (HiZ) or grounded during power-up sequences, power-down sequences, and normal device operation.

#### Schematic Review

Follow the list below for the custom schematic design:

1. A dedicated LDO or PMIC output is used.
2. Nominal voltage connected to VPP is 1.8V and supports current requirements as per data sheet requirements.
3. Selected LDO specifications including load current transient response is similar to the LDO used on the SK schematics.
4. Processor IO is used to control the EN of the LDO and the required pull is provided.
5. Verify the if EN pull holds the LDO is in off-state during power cycling.
6. When an adjustable LDO is used, verify the output voltage configuration, output voltage slew and use of over voltage protection.
7. A series resistor is provided to isolate the processor VPP supply from the LDO output for testing the timing or LDO output.
8. Supply rail connected follows the processor ROC.

#### Additional

1. Always provide provision on the processor board to connect VPP supply (on-board or external supply).
2. Select an LDO with fast transient response and connect LDO output to the processor VPP pin with a low loop inductance path to source the high transient load current, where the VPP pin never drops below the minimum operating voltage.
3. Enable the VPP only during eFuse programming. Connecting the VPP supply to a continuous 1.8V supply rail is not a allowed or recommended or supported option.
4. Due to the transient load current requirement during eFuse programming, using load switch or FET switch is not a recommended approach. A load switch or FET switch is likely to have too much voltage drop that is not compensated when using an LDO.
5. If the use case requires use of load switch or FET switch, then characterize the board by measuring the voltage on the processor VPP pin during programming and verify supply never drops below the ROC minimum limit. Several variables in the path of VPP can cause the supply to be out of the ROC when using load switch or FET and must be without characterized before implementing. Check or test if the load switch or FET switch violates the maximum VPP supply slew rate limit of 6000V per second defined in the data sheet.

#### 6.1.1.4 Supply Connection for Partial IO (Low-Power) Mode Configuration

##### 6.1.1.4.1 Partial IO Used

The recommendation is to connect VDD\_CANUART and VDDSHV\_CANUART to always-on power sources.

VDD\_CANUART operates at 0.75V or 0.85V, there is no voltage dependency to the VDD\_CORE during normal operation. The only voltage dependency is during power-up and power-down sequencing.

For partial IO low power mode implementation, refer [\[FAQ\] AM625 / AM623 / AM625SIP / AM625-Q1 / AM620-Q1 / AM62A7 / AM62A3 / AM62P / AM62P-Q1 Custom board hardware design – Partial IO LPM support](#).

##### 6.1.1.4.2 Partial IO Unused

Connect VDD\_CANUART to the same power source as VDD\_CORE. Connect VDDSHV\_CANUART to any valid IO power source.

##### 6.1.1.4.3 Data Sheet Reference for Power Sequence

See the notes related to partial IO in the *Power-Up Sequencing*, *Power-Down Sequencing* and *Partial IO Power Sequencing* sections of the processor-specific data sheet.

##### 6.1.1.4.4 Partial IO (Low-Power) Mode Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes, signal description and electrical specifications
3. Connect VDD\_CANUART and VDDSHV\_CANUART to an always-on power source when implementing Partial IO low power mode
4. Connect VDDSHV\_CANUART to a valid IO power source Partial IO low power mode is not implemented
5. Connect VDD\_CANUART to the same power source as VDD\_CORE, VDDA\_CORE\_CSIRX0, VDDA\_CORE\_USB, and VDDA\_DDR\_PLL0 when Partial IO low power mode is not implemented
6. When VDD\_CANUART is connected to an always-on power source, never apply a potential to VDD\_CORE which is greater than the potential applied to VDD\_CANUART + 0.18V during power-up or power-down. Partial IO low power mode requires VDD\_CANUART to ramp up before and ramp down after VDD\_CORE

#### Schematic Review

Follow the below list for the custom schematic design:

1. VDDSHV\_CANUART and VDD\_CANUART supplies are available before the other processor supplies are available when partial IO mode is implemented
2. VDDSHV\_CANUART and VDD\_CANUART follow the recommended power sequence when partial IO mode is not used
3. Voltage levels connected to VDDSHV\_CANUART and VDD\_CANUART
4. Verify the connected supply rails follow the ROC

#### Additional

1. Verify the IO level compatibility between the processor IO and the attached device (wakeup source)

##### 6.1.1.5 Additional Information

Placement of 0Ω resistor (shunt) or a jumper in line with the core supply and other supply rails are recommended for initial PCB prototype builds. Placement of 0Ω resistor (shunt) or a jumper can help during board bring-up and debug to isolate the supply or for current measurement. Shunt resistors are used to measure the supply rail currents in SK.

Verify the effect of adding 0Ω resistor provisions on the custom board performance.

#### 6.1.2 Capacitors for Supply Rails



### 6.1.2.1 AM62P, AM62P-Q1

Perform a PDN analysis, verifying that the required number of decoupling and bulk capacitors are provided for all power supply rails, including dual-voltage IO supply for IO group supply rails.

Place the decoupling capacitors as close as possible to the supply pins. Larger bulk capacitors can be placed further away.

Use low-ESL capacitors and mount the capacitors with the shortest possible traces to keep the mounting inductance low. For more information, see the [Sitara Processor Power Distribution Networks: Implementation and Analysis](#) application note.

Use the bulk and decoupling capacitors values from the SK as a reference when PDN analysis is not performed or results are not available. For filtered (ferrite) power supplies implementation, follow the processor-specific SK.

Use feedthrough (3-terminal) capacitors (used on the SK-AM62P-LP starter kit) to optimize the number of capacitors used. Use of 3-terminal capacitors minimizes the loop inductance and helps optimize processor performance, mainly the DDR performance.

### 6.1.2.2 Additional Information

#### 6.1.2.2.1 AM62P, AM62P-Q1

When the processor peripherals (CSI-2 (Camera Serial interface 2) and DSI (Display Serial interface) instance CSIRX0 and DSITX0), DDR Subsystem (DDRSS0) and USB2.0 (USB0 and USB1)) are not used, the supplies (core, analog) associated with the peripherals have specific connectivity requirements. For more information, see the *Pin Connectivity Requirements* section of the processor-specific data sheet. Power supply filter (ferrite) and capacitors (bulk) can be optimized.

### 6.1.2.3 Capacitors for Supply Rails Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes, signal description and electrical specifications
3. Use of low ESL capacitors and 3-terminal capacitors connected with short traces to minimize the board loop inductance
4. Voltage rating of the capacitors used (> twice the worst-case applied voltage is a commonly used guideline)

#### Schematic Review

Follow the below list for the custom schematic design:

1. Compare the capacitors used for all the supply rails with SK schematics
2. Verify each of the power rail pins have a decoupling capacitor and each of the supply rail group has a bulk capacitor

#### Additional

1. Power supply decoupling is adequate. All processor power rails use both bulk and high frequency decoupling capacitors. The critical power domains that require the most attentions are the low voltage, high current domains (VDD\_CORE, VDDR\_CORE)
2. As a starting point, the recommendation is to follow the validated SK decoupling strategy
3. Deviations are not recommended without performing static and dynamic PDN analysis to verify that the Reff, Cap LL, and Impedance targets are met
4. In some situations, the SK uses 3-terminal capacitors, due to low inductance packaging and performance. Make sure the 3-terminal capacitors connections in the SK schematics are not implemented as an in-line or filter component
5. Show the connections of the capacitor near to the relevant pin for ease of placement and routing

### 6.1.3 Processor Clock

### 6.1.3.1 Clock Inputs

#### 6.1.3.1.1 High Frequency Oscillator (MCU\_OSC0\_XI / MCU\_OSC0\_XO)

For the operation of the processor, select a crystal as the clock source or a 1.8V LVCMOS square-wave digital clock source.

A 25MHz external crystal connected to the internal high frequency oscillator (MCU\_HFOSC0) is the clock source for the internal reference clock HFOSC0\_CLKOUT.

Place the discrete components used to implement the crystal oscillator circuit as close as possible to the MCU\_OSC0\_XI and MCU\_OSC0\_XO pins. For the crystal, follow the *MCU\_OSC0 Crystal Circuit Requirements* table of the processor-specific data sheet when choosing the load capacitors.

When a 1.8V LVCMOS square-wave digital clock source is used, connect the processor XO pin according to the processor-specific data sheet recommendation.

For information on clock selection, refer to [\[FAQ\] AM625 / AM623 / AM625SIP / AM625-Q1 / AM620-Q1 Custom board hardware design – Queries regarding Crystal selection](#). The FAQ is generic and can also be used for AM62P, AM62P-Q1 processor family.

Refer to [\[FAQ\] AM625 / AM623 / AM625SIP / AM625-Q1 / AM620-Q1 Custom board hardware design – Queries regarding MCU\\_OSC0 Start-up Time](#). The FAQ is generic and can also be used for AM62P, AM62P-Q1 processor family.

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#### Note

25MHz is the only crystal frequency that is currently supported. See the processor-specific data sheet for more details on the recommended crystal parameters.

Refer *MCU\_OSC0 LVCMOS Digital Clock Source, MCU\_OSC0 LVCMOS Digital Clock Source Requirements* section of the processor-specific data sheet

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#### 6.1.3.1.2 Low Frequency Oscillator (WKUP\_LFOSC0\_XI / WKUP\_LFOSC0\_XO)

WKUP\_LFOSC0 has limited use cases and is optional. Based on the use case, select a 32.768kHz crystal as the clock source or a 1.8V LVCMOS square-wave digital clock source.

For more information, see the [\[FAQ\] AM625: LFOSC usage in the device](#). The FAQ is generic and can also be used for AM62P, AM62P-Q1 processor family.

Place all discrete components used to implement the oscillator circuit as close as possible to the WKUP\_LFOSC0\_XI and WKUP\_LFOSC0\_XO pins. For the crystal, the load capacitance selected is required to be in the range recommended in the *WKUP\_LFOSC0 Crystal Electrical Characteristics* table of the processor-specific data sheet.

If WKUP\_LFOSC0\_XI / WKUP\_LFOSC0\_XO is not used, recommended is to connect the XI directly to the VSS and to leave the XO unconnected.

For more information on connecting the unused WKUP\_LFOSC0, see the *WKUP\_LFOSC0 Not Used* section of the processor-specific data sheet.

#### 6.1.3.1.3 EXT\_REFCLK1 (External Clock Input to Main Domain)

EXT\_REFCLK1 pin is routed to clock multiplexers as a selectable input clock source to the Timer modules (DMTIMER/WDT), DMTIMER in Security Subsystem (SMS), MCAN, and CPTS (Time Stamping Module). The EXT\_REFCLK1 is an option for when an application requires a specific clock frequency to be fed to the timer modules. An example of the application is time synchronization or for clock quality reasons.

When EXT\_REFCLK1 is used as a clock source, depending on the availability of external clock, a pulldown is required.

#### 6.1.3.1.4 Additional Information

MCU\_OSC0\_XI / MCU\_OSC0\_XO has specific routing requirements. See the *Clock Routing Guidelines* section of the processor-specific data sheet.

#### 6.1.3.1.5 Clock Input Checklist - MCU\_OSC0

##### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links.
2. Pin attributes, signal description, and electrical specifications.
3. Electrical characteristics, timing parameters and any additional available information.
4. Selection of processor clock input source, either crystal or oscillator.
5. 25MHz is the clock input frequency currently supported. Refer processor-specific data sheet for supported clock input frequency.
6. Selection of crystal load capacitor versus data sheet recommendations.
7. PCB capacitance for MCU\_OSC0 is included in the calculation of crystal load capacitance value.
8. When oscillator is used, add a decoupling capacitor and bulk capacitor near to the oscillator supply pin.

##### Schematic Review

Follow the below list for the custom schematic design:

1. Connection of 25MHz MCU\_OSC0 clock is mandatory.
2. Connections of the crystal circuit (MCU\_OSC0), as per the data sheet recommendations.
3. Direct connection of crystal without series or parallel resistor.
4. Selection of crystal load and load capacitance including around 4pF board capacitance.
5. A load capacitor is recommended to be twice the crystal load, including board capacitance.
6. Connection of XO when external oscillator is used, ground XO.

##### Additional

1. Refer to the *Applications, Implementation, and Layout* section of the data sheet for clock routing guidelines
2. Select crystal and load capacitor such that the load capacitor value can be a standard value
3. Connect the 25MHz crystal directly to the processor XI and XO pins, no series or parallel resistors are recommended. The internal oscillator implements Automatic Gain Control (AGC) for amplitude control
4. The processor is validated only with a 25MHz (only frequency currently supported) clock source.
5. Processor-specific data sheet shows that MCU\_OSC0 does not start until the core voltage ramps because there are some cases where the oscillator does not start until VDD\_CORE ramps. In most cases, the oscillator starts when VDDS\_OSC0 ramps, although the oscillator starts when VDDS\_OSC0 ramps is not always the case. The oscillator start-up diagram in the data sheet shows the maximum start-up time, which includes the case where the delay is based on VDD\_CORE is valid.
6. Recommendation is to retain the HFOSC0 registers in the default state.
7. Refer to the processor-specific data sheet to select the crystal circuit components.

#### 6.1.3.1.6 Clock Input Checklist - WKUP\_LFOSC0

##### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes, signal description, and electrical specifications
3. Electrical characteristics, timing parameters, and any additional available information
4. Selection of WKUP clock input source - crystal or oscillator
5. 32.768kHz is the WKUP clock input frequency supported, refer to the processor-specific data sheet for supported clock input frequency
6. Selection of the crystal load versus data sheet recommendations

7. Selection of load capacitor versus data sheet recommendations
8. WKUP\_LFOSC0 has limited use cases, provide provisions to ground the XI input when the clock option is not used

### Schematic Review

Follow the below for the custom schematic design:

1. Connections of the clock circuit (WKUP\_LFOSC0), as per the data sheet recommendations
2. Selection of crystal load and load capacitance, with the load capacitance being twice the crystal load
3. Connection of the clock circuit when external oscillator is used (XO is grounded)
4. Connection of the XI input when the WKUP\_LFOSC0 is unused (XI is grounded)

### Additional

1. Crystal load capacitance versus LFOSC0 registers. The only LFOSC0 register bits board designers change are BP\_C, PD\_C, and CTRLMMR\_WKUP\_LFXOSC\_TRIM[18:16], where PD\_C is reset (0) to enable the oscillator and the BP\_C bit is only set (1) to place the oscillator in bypass mode when using an LVCMOS clock source. The CTRLMMR\_WKUP\_LFXOSC\_TRIM[18:16] bits are set based on the actual capacitance load applied to the crystal, as defined by the *Load Capacitance Equation*.
2. Refer to the processor-specific data sheet for the recommended circuit configuration during preproduction PCB and the production PCB

#### 6.1.3.2 Clock Outputs

Processor IOs (pins) named CLKOUT0 and WKUP\_CLKOUT0 can be configured as clock outputs. The clock outputs can be used as clock source for the attached devices (external peripherals).

WKUP\_CLKOUT0 is driven low after reset for AM62Px processor family.

##### 6.1.3.2.1 Clock Output Checklist

### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes, signal description, and electrical specifications

### Schematic Review

Follow the list below for the custom schematic design:

1. Connection of the clock output to single or multiple loads. When connected to multiple inputs (loads), each of the inputs are recommended to be connected through a buffer
2. Required pulls are provided near to the attached device clock input

### Additional

1. CLKOUT0: EXT\_REFCLK1 is used as CLKOUT0. Always connect a clock signal point-to-point, without any branches. When connecting CLKOUT0 to multiple clock inputs, use a buffer (with one input and multiple outputs or individual buffers based on the use case)

#### 6.1.4 Processor Reset

##### 6.1.4.1 External Reset Inputs

MCU\_PORz is the external MCU and main domain cold reset input to the processor. The recommendation is to hold the MCU\_PORz pulled low during the supply ramp and oscillator start-up. Follow the recommended MCU\_PORz timing in the *Power-Up Sequencing* diagram of the processor-specific data sheet.

For the MCU\_PORz (3.3V tolerant, fail-safe input), applying a 3.3V input is acceptable. The input thresholds are a function of the 1.8V IO supply voltage (VDDS\_OSC0).

A slow rising reset signal causes internal processor reset circuit to glitch. Use a fast rise time discrete push-pull output buffer as MCU\_PORz input and add a capacitor (22pF) filter provision.

When PMIC is used, connect the output through push-pull output type logic gate or discrete buffer (with fast rise time) as an MCU\_PORz input, rather than a slow rising open-drain output (can glitch the internal reset circuit).

Provision to connect a filter capacitor at the MCU\_PORz input is recommended. The capacitor value and mounting is use-case dependent. Verify the capacitor value does not cause the LVCMOS input to violate the slew rate requirements or glitch internally due to slow ramp.

Not connecting a valid input to MCU\_PORz is not a recommended use case and can cause unpredictable and random behavior. Due to the device not going through a valid reset, internal circuits are in random (undefined) states.

Connect external warm reset inputs MCU\_RESETz and RESET\_REQz as per the *Pin Connectivity Requirements* section of the processor-specific data sheet. Warm reset inputs (LVCMOS inputs) have input slew rate requirements specified. Connecting a capacitor directly at the input is not recommended due to the slow ramp input. A schmitt trigger-based debouncing circuit is recommended. For implementing the debouncing logic, see the processor-specific SK schematic.

### Usage Note for MCU\_RESETz

Refer to the silicon errata advisory *i2407- RESET. MCU\_RESETSTATz is unreliable when MCU\_RESETz is asserted low.*

#### 6.1.4.2 Reset Status Outputs

PORz\_OUT is the main domain POR (cold reset) status output, RESETSTATz is the main domain warm reset status output, and MCU\_RESETSTATz is the MCU domain warm reset status output.

When reset status outputs PORz\_OUT, MCU\_RESETSTATz and RESETSTATz are used to drive the attached device reset inputs (/reset), pulldowns are recommended for reset status outputs to assert the reset (hold the attached devices in reset) to the attached devices during power-up and reset.

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#### Note

An external pulldown holds the attached device reset inputs low, in use cases where none of the attached devices have internal pullups. In cases where an attached device has an internal pullup, the reset signal is pulled to a mid-supply voltage. Verify specific use-case and add pulldown on the reset status outputs.

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RESETSTATz can be used to reset on-board memories or peripherals with reset functionality (eMMC, OSPI, or EPHY) or SD card power switch. The PORz\_OUT can be used to latch the hardware strap configurations during reset including latching the Ethernet PHY strap configurations.

Connect the reset status outputs to a test point for testing or future enhancements when not used. Optionally a pulldown can be provided and be a DNI.

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#### Note

MCU\_RESETz and MCU\_RESETSTATz have specific use case recommendations. Refer to the advisory i2407 of the processor-specific silicon errata.

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#### 6.1.4.3 Additional Information

The BOOTMODE00..15 inputs that are used to configure the processor boot mode need to be held in a known state to select the appropriate boot mode configuration as defined in the processor-specific TRM, until the boot mode configuration is latched during the rising edge of the PORz\_OUT.

#### 6.1.4.4 Processor Reset Input Checklist

##### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links.
2. Pin attributes, signal description, and electrical specifications.
3. Electrical characteristics, timing parameters, and any additional available information.
4. The processor is required to restart (release reset) only after the voltages are below 0.3V after power-down
5. Reset input is asserted (low) while the processor supplies are ramping up or ramping down
6. MCU\_PORz (POR) input is 3.3V tolerant and fail-safe. The threshold follows the VDDS\_OSC0 IO level.
7. IO level of warm reset for MCU and main domains RESET\_REQz (VDDSHV0), MCU\_RESEZz (VDDSHV\_MCU) matches the IO supply for IO group supply (1.8V or 3.3V).
8. Reset inputs follow the slew rate requirements (FS RESET, LVC MOS).
9. Slew rate when open-drain output is connected (connecting through discrete push-pull output buffer is recommended) directly to the reset input.
10. Follow reset requirements including slew rate and MCU\_PORz hold time when a non-TI power architecture is used.

## Schematic Review

Follow the below list for the custom schematic design:

1. Cold and warm reset inputs slew rate requirements are considered.
2. Cold reset input (MCU\_PORz) deassertion hold time (MCU\_PORz input delay after all the supplies ramp, 9.5ms minimum) after all supplies ramps are provided as per the data sheet requirement.
3. Provision for filter capacitor is provided at the input of the reset inputs (add 22pF (place holder) capacitor as a filter option and DNI).
4. Connection of reset inputs when not used as per pin connectivity requirements.
5. Connection of push button warm reset inputs through debouncing circuit (Schmitt trigger buffer output based).

## Additional

1. MCU\_PORz input has slew rate requirement specified. When connecting PMIC\_POWERGOOD (open-drain output) to MCU\_PORz is the only available option, adjust the pullup to optimize the rise time (< 200ns)
2. MCU\_PORz is a fail-safe input and 3.3V tolerant
3. Connect the output from a discrete push-pull output buffer (fast rise time) as MCU\_PORz input rather than slow rising open-drain output
4. Not connecting a valid MCU\_PORz causes unpredictable and random behavior, since processor does not get a valid reset input and the internal circuits are in random states. Slow ramp reset input causes internal processor reset circuit to glitch
5. LVC MOS inputs have slew rate requirements specified. A schmitt trigger based debouncing circuit is recommended for the slow ramp push button RC connected to the processor warm reset inputs. Schmitt trigger based debouncing circuit is recommended when using a push button or an RC reset.
6. Provision for external ESD protection for manual reset input added near to the reset signal.
7. Fail-safe operation when connected to external reset inputs. Applying an external input before supply ramps causes voltage feed and affects the processor performance.
8. Reviewed MCU\_RESEZz related errata.

### 6.1.4.5 Processor Reset Status Output Checklist

## General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links.
2. Pin attributes, signal descriptions, and electrical specifications.
3. Electrical characteristics, timing parameters, and any additional available information.
4. PORz\_OUT is used as input to latch the processor boot mode configuration or attached device strap configuration during reset.
5. RESETSTATz output is used for resetting the attached devices that requires a reset when the processor undergoes any type of global reset (cold or warm).



6. IO level compatibility between the processor reset status output and attached device reset input (can cause residual voltage affecting performance).
7. Loading of the reset status output (capacitor > 22pF (place holder) is connected directly to the output).
8. Reviewed MCU\_RESETSTATz related errata.

### Schematic Review

Follow the below list for the custom schematic design:

1. RESETSTATz, MCU\_RESETSTATz and PORz\_OUT have pulldown to hold the attached devices in reset during supply ramp and reset.
2. Connection of capacitor directly on the reset output near to the reset input of the attached device (capacitor > 22pF). Perform simulation to use higher value capacitor.

### Additional

1. External ESD protection for the reset status outputs when connected to carrier board or external connector

#### 6.1.5 Configuration of Boot Modes (for Processor)

Boot mode inputs do not have internal pullup or pulldown resistors that are active during processor reset. The recommendation is to connect external pullups or pulldowns to set the required boot mode.

When dip switches are used, use a resistor divider ratio of 470Ω (pullup) and 47kΩ (pulldown) for improved noise performance.

When the boot mode is configured using only resistors, a standard resistor (same value for pullup and pulldown) value. As an example a 10kΩ or similar resistor can be used since either the pullup or pulldown is populated.

The recommendation is to connect pullup or pulldowns to boot mode pins marked as Reserved or not used.

BOOTMODE 14 and BOOTMODE 15 pins can be treated as Reserved for AM62Px family of processors.

Optionally, AM62Px family of processors can be configured for POST (Hardware Power-on-Self-Test) functionality when BOOTMODE15 = 1 and DS\_DM\_RESET\_MASK = 0.

Add provision for pullup and pulldown for all the boot mode pins that have configuration capability for debugging, design flexibility, and future enhancement. Populate either pullup or pulldown for each boot mode pins. Direct connection of boot mode pins to ground or IO supply rail is not recommended or allowed since IOs have alternate configuration and, intentionally or unintentionally, are configured as output by the software.

Consider that the boot mode input pins are not fail-safe when boot mode configurations are driven from an external input or a base board.

Based on the application requirement, a buffer that is driven only when reset (MCU\_PORz) is asserted (low) is used to present the boot configuration to the processor.

If the boot mode pins are configured as an output during normal operation, then a series resistor (approximately 1kΩ) is recommended at the output of the buffers. For more information, see the processor-specific SK for implementation.

##### 6.1.5.1 Processor Boot Mode Inputs Isolation Buffers Use Case and Optimization

In the SK, the boot mode pins BOOTMODE [15:00] are asserted through two isolation buffers. The buffers make sure that the SYSBOOT pulls (boot mode configured using resistors) control the IO level of the signals when the boot mode signals are latched (around the PORz\_OUT rising edge) by the processor. Since boot mode signals are used for other functions after processor boot and are connected to attached devices or peripherals. The boot mode configuration resistors are isolated from other connected peripherals so that the other connected peripherals do not conflict with the intended boot mode configuration (IO levels).

The buffers are enabled when PORz\_OUT is driven low by the processor. Once PORz\_OUT is asserted, the buffer outputs are Hi-Z so the signals are not pulled or influenced by the boot mode resistors.



For optimizing the design (including BOM), the buffers can be optimized or deleted depending on the use case. The boot mode pull resistors value are selectable so that the resistors do not affect the operation of attach devices.

### 6.1.5.2 Boot Mode Selection

For configuring the required processor boot mode, refer to the *ROM Code Boot Modes* table in the *Initialization* chapter of the processor-specific TRM.

#### 6.1.5.2.1 Notes for USB Boot Mode

USB0 interface supports USB DFU boot mode. When the USB0 is configured for device firmware upgrade (DFU) boot mode. Permanent or switched 3.3V supply is not recommended to connect directly to the USB0\_VBUS pin. Connecting a permanent supply is not recommended (equivalent to the divider value) to the USB0\_VBUS pin since connection of supply without resistor divider violate fail-safe operation.

A 5V supply from the host (switched) connected through the USB connector is recommended to connect to USB0\_VBUS pin through the resistor voltage divider, as per the processor-specific data sheet recommendations. The zener diode can be deleted and the two resistors can be combined to a 20kΩ resistor for the *USB VBUS Detect Voltage Divider, Clamp Circuit* if the custom board design does not apply a VBUS potential > 5.5V, and the supply is on-board.

### 6.1.5.3 Boot Mode Implementation Approaches

Below FAQs captures the boot mode implementation approach when boot mode buffers are used and unused.

[\[FAQ\] AM625 / AM623 / AM644x / AM243x / AM62A / AM62P - Bootmode implementation with buffers](#)

[\[FAQ\] AM625 / AM623 / AM644x / AM243x / AM62A / AM62P - Bootmode implementation without buffers](#)

### 6.1.5.4 Additional Information

When external inputs drive the boot mode configuration, the recommendation is to stabilize the boot mode configuration inputs before the processor MCU\_PORz (cold reset) is released.

When using an Ethernet boot and a Reduced Gigabit Media Independent Interface (RGMII), implement an EPHY into the design that starts RGMII\_ID mode on the EPHY RX data path and disables RGMII\_ID mode on the TDn data path (the processor implements RGMII\_ID on the TDn outputs). Processor ROM does not enable or disable RGMII\_ID mode on attached EPHYs programmatically. Typically, RGMII\_ID setting is accomplished via pin strapping on the EPHY.

Select a EPHY with the capability to set the RGMII internal delay through a pin strap, see the processor-specific SK. For more information, see the advisory *i2329 MDIO: MDIO interface corruption (CPSW and PRU-ICSS)* of the processor-specific silicon errata.

### 6.1.5.5 Configuration of Boot Modes (for Processor) Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes, signal description, and electrical specifications
3. Electrical characteristics and any additional available information
4. All BOOTMODE pins have external pulls or a circuit to drive the required boot mode. Leaving any of the boot mode inputs unconnected is not recommended or allowed
5. Connecting the boot mode inputs directly to supply or VSS is not recommended. Shorting of multiple boot mode inputs together and connecting a common resistor is not recommended. (Board designers can have problems with the firmware configuration, where the LVCMOS GPIOs that are intended as inputs are mistakenly configured as outputs, driving a logic high signal instead of remaining in a high-impedance state).
6. Boot mode inputs are connected to the processor using resistor divider or through buffers as per the SK implementation
7. Boot mode configuration using dip switches or resistors. When only resistors are used, a resistor divider is optional. A pullup or pulldown can be used

8. IO compatibility (1.8V or 3.3V referenced to VDDSHV3, boot mode inputs are not fail-safe)
9. The boot mode inputs are stable before cold reset status output is pulled high
10. Boot mode pins connected to alternate functions through 0Ω for isolation or testing

## Schematic Review

Follow the below list for the custom schematic design:

1. Use a common resistor value (10kΩ or similar) when dip switch is not used for boot mode configuration
2. Use 470Ω and 47kΩ resistors when dip switches are used to configure the boot
3. Series resistor 1kΩ is used at the output of the buffer when boot mode is implemented with buffers or driven by external control signals
4. Boot mode configuration for PLL clock, primary and secondary boot

## Additional

1. BOOTMODE pins do not have internal pullup or pulldown resistors that are active during power reset.
2. For early designs, recommend that all boot mode pins are brought out to an optional PU/PD pair with pop and no-pop options, depending on the required boot mode. See processor-specific TRM for complete boot mode definitions.
3. Boot values are latched at the release of power-on reset. If the boot mode pins are reconfigured for alternate function during operation, boot mode pins must be released/set back to the proper configuration to select the boot mode whenever the device enters the power-on reset state. Boot mode configuration specifically is a concern if signal is driven from external peripheral.
4. Add external ESD protection in case the boot mode switches are configured in an uncontrolled environment.
5. Boot mode inputs are not fail-safe. No input can be applied before the processor IO supplies ramp. Applying an external input before supply ramps can cause voltage feed and can affect the custom board functions.
6. Boot mode buffers are optional and are provided on the SK for test automation
7. When using buffers or logic gates to configure the boot mode, verify the device used has OE (output enable feature).

## 6.2 Board Debug Using JTAG and EMU

### 6.2.1 JTAG and EMU Used

The recommendation is to connect the JTAG (TDI, TCK, TMS and TRSTn) and EMU (EMU0 and EMU1) signals as per the *Pin Connectivity Requirements* section of the processor-specific data sheet.

Optionally, connect a series resistor (22Ω) on the TDO (close to processor) signal for matching buffer impedance. The recommendation is to add external ESD protection for all JTAG and EMU signals when the signals interface to external connector. EMU 0/1 signals support boot sequence debug after cold reset (MCU\_PORz).

Pullup for TDO is optional and depends on the debugger used.

Refer to the *On-Chip Debug* chapter of the processor-specific TRM.

For more information, see the below FAQs:

[\[FAQ\] AM625 / AM623 / AM625SIP / AM625-Q1 / AM620-Q1 / AM62A7 / AM62A3 / AM62P / AM62P-Q1 / AM6442 / AM2432 Custom board hardware design – JTAG](#)

[\[FAQ\] AM625: JTAG Pulldown/Pullup](#)

### 6.2.2 JTAG and EMU Not Used

For connecting the JTAG and EMU signals, refer to the *Pin Connectivity Requirements* section of the processor-specific data sheet.

During custom board design, TI recommends provisioning at least a minimal JTAG port including EMU0/1 connected to test points or a header footprint to support early prototype debugging. JTAG components can be DNI in the production version of the board. Also, provide provision to add recommended pulls per the *Pin Connectivity Requirements* section, and external ESD protection.

### 6.2.3 Additional Information

Buffering of clock and signals are recommended whenever the JTAG interface connects to more than one attached device. Buffering of clock is recommended even for single device implementations. For implementation, see the processor-specific SK.

If trace operation is used, connect TRC\_DATAn signals directly to the emulation connector. All TRC\_DATAn signals are pin-MUXed with other signals. Use either trace functionality or a GPMC interface. Short and skew matched connections (board trace) for TRC\_DATAn signals are used for trace functionality. The trace signals are referenced to VDDSHV3, and can be at a different supply voltage from the other JTAG signals. For additional recommendations on TRC/EMU design and layout, see the [Emulation and Trace Headers Technical Reference Manual](#). A summary is available in the [XDS Target Connection Guide](#).

If boundary scan is used, connect EMU0 and EMU1 pins directly to the JTAG connector.

For proper implementation of the JTAG interface, see the [Emulation and Trace Headers Technical Reference Manual](#) and the [XDS Target Connection Guide](#).

### 6.2.4 Board Debug Using JTAG and EMU Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes, signal descriptions, and electrical specifications
3. Electrical characteristics, timing parameters, and any additional available information
4. JTAG signals IO compatibility (IO supply referenced to VDDSHV\_MCU)
5. Connection of the required pulls as per the pin connectivity requirements near to the processor JTAG pins

#### Schematic Review

Follow the below list for the custom schematic design:

1. Connection of supply voltage to the JTAG connector including filter capacitor (connect the voltage source that connects to VDDSHV\_MCU)
2. Pullup and pulldown values (use 47k $\Omega$  or 10k $\Omega$ )

#### Additional

1. TI recommends that all custom board designs contain at least a minimal JTAG port connection to test points or header for early prototype debugging. The minimum connections are TCK, TMS, TDI, TDO and TRSTn. If desired, delete JTAG routes and component footprints (except the pulldown on TRSTn and the pullups on TMS and TCK) in the production version of the board
2. Provision to configure EMU0 and EMU1 signals is recommended
3. If trace operation is needed, the TRC\_DATAn signals must connect to the emulation connector. All TRC\_DATAn signals are pin-muxed with other signals. If the trace connections are needed, do not use other muxed interfaces on the pins. Use short and skew matched routes for TRC\_DATAn signals. Trace signals are on a separate power domain and can be at a different voltage from the other JTAG signals
4. Provision for external ESD protection. Populate when JTAG interface is used
5. Verify fail-safe operation when connected to external signals. Applying an external input before supply ramps can cause voltage feed and can affect the custom board functions

## 7 Processor Peripherals

### 7.1 Supply Connections for IO Groups

#### 7.1.1 AM62P, AM62P-Q1

Each dual-voltage IO supply for IO group (VDDSHVx [x = 0-3, 5-6], VDDSHV\_MCU and VDDSHV\_CANUART) provides power supply to a fixed set of IOs (peripherals). Connect 3.3V or 1.8V supply voltage to each of the dual-voltage IO supply for IO group.

VDDSHV5 and VDDSHV6 are designed to support power-up, power-down, or dynamic voltage changes, without any dependency on other power rails. Dynamic voltage change capability is required to support UHS-I SD cards.

SDIO or LVCMOS type IO buffers are implemented for processor IOs. The IO supply requirements depends on the IO buffer type.

Based on the selected memory type (LPDDR4), DDR PHY IO supply and DDR clock IO supply as per the ROC are connected.

### 7.1.2 Supply Connections for IO Groups Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links.
2. Pin connectivity requirements, pin attributes, and signal description.
3. Standards referenced in the electrical characteristics including recommended operating conditions and any additional available information.
4. IO buffer type implemented and the allowed supply configuration (LVCMOS fixed (1.8V/3.3V) or SDIO dynamic voltage change).
5. Connection of valid supply to all the IO supply for IO groups (VDDSHVx, VDDSHV\_MCU, and VDDSHV\_CANUART).
6. Sequencing of the IO supply.
7. 3.3V IO supply connection.
8. Connection of processor DDRSS IO supplies (PHY IO and Clock IO) based on the selected memory

#### Schematic Review

Follow the list below for the custom schematic design:

1. Attached device IO supply and the IO supply for IO group referenced by the interface signals are connected to the same supply source.
2. Pullups are connected to the same supply rail that is connected to the processor VDDSHVx and attached device.
3. Connecting the 3.3V supply connected to the PMIC input directly to the IO supply for IO groups VDDSHVx is not recommended since the IO supply is available for an undefined time in case the PMIC does not start-up and generate the other processor supply rails.

#### Additional

1. Note the power sequencing requirements based on the IO supply rail voltage level used.
2. Dynamic voltage change is supported by some specific IO supply for IO groups (VDDSHV5 and VDDSHV6).
3. Dynamic voltage change of the IO supply for IO group referenced to LVCMOS IO buffers is not recommended or allowed (VDDSHV0-3, VDDSHV\_MCU, VDDSHV\_CANUART).

## 7.2 Memory Interface (DDRSS (DDR4/LPDDR4), MMCSD (eMMC/SD/SDIO), OSPI/QSPI and GPMC)

### 7.2.1 DDR Subsystem (DDRSS)

See the following FAQ:

[\[FAQ\] AM625 / AM623 / AM62A / AM62P Design Recommendations / Commonly Observed Errors during Custom board hardware design – DDR4 / LPDDR4 MEMORY Interface](#)

#### 7.2.1.1 DDR4 SDRAM (Double Data Rate 4 Synchronous Dynamic Random-Access Memory)

##### 7.2.1.1.1 AM62P, AM62P-Q1

*Currently Not Supported.*

## 7.2.1.2 LPDDR4 SDRAM (Low-Power Double Data Rate 4 Synchronous Dynamic Random-Access Memory)

### 7.2.1.2.1 AM62P, AM62P-Q1

For implementation guidelines and routing topology, see the [AM62Ax, AM62Px, AM62Dx LPDDR4 Board Design and Layout Guidelines](#).

#### 7.2.1.2.1.1 Memory Interface Configuration

The allowed memory configurations are 1 × 32-bit or 1 × 16-bit.

1 × 8-bit memory configuration is not a valid configuration.

#### 7.2.1.2.1.2 Routing Topology and Terminations

When a 32-bit, single-rank, and dual-rank LPDDR4 is used, follow balanced *T* topology for address, CKE, and CK signals routing.

When a 16-bit, single-rank LPDDR4 is used, follow the point-to-point topology. Connect the unused Data strobe pins (DDR0\_DQS2-3 and DQS2-3\_n) as per the [AM62Ax, AM62Px, AM62Dx LPDDR4 Board Design and Layout Guidelines](#) recommendation.

The data signal connection topology is point-to-point for LPDDR4, and is categorized into different byte lanes.

VTT termination does not apply for LPDDR4. Terminations required for address and control signals are handled internally (on-die).

#### 7.2.1.2.1.3 Resistors for Control and Calibration

Connect a pull-down for DDR0\_RESET0\_n (LPDDR4\_RESET\_N) close to memory (LPDDR4) device.

Connect recommended resistors for DDR0\_CAL0 (close to processor), ODT\_CA\_A-B (close to memory (LPDDR4) device) and ZQn (n = 0-1, close to memory (LPDDR4) device).

#### 7.2.1.2.1.4 Capacitors for the Power Supply Rails

Verify adequate bulk and decoupling capacitors are provided for the processor DDR supply rails and memory (LPDDR4) device supply rails.

Follow the processor-specific SK implementation whenever recommendations are not available.

#### 7.2.1.2.1.5 Data Bit or Byte Swapping

During custom board design, in case bit swapping is required, bit swaps within a data byte, and swapping across bytes is allowed with some restrictions. Address and control bit swapping is not supported.

For more information, see the *Channel, Byte, and Bit Swapping* section of [AM62Ax, AM62Px, AM62Dx LPDDR4 Board Design and Layout Guidelines](#).

The recommendation is to update the schematics with the bit swapping changes for future reference or reuse.

#### 7.2.1.2.1.6 LPDDR4 Implementation Checklist

### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes, signal description, and electrical specifications
3. Electrical characteristics, timing parameters, and any additional available information
4. Connection of address, clock, control and data signals - follow the processor-specific DDR design guidelines
5. DDR0\_CAL0, DDRSS IO pad calibration resistor (240Ω, 1%) connected to VSS
6. ZQ0..1, Memory device IO calibration resistor (240Ω, 1%) connected to VDD\_LPDDR4
7. Memory device ODT pulled up through a resistor (2.2kΩ or similar, no connection from DDRSS)
8. Connection of chip select CSn0..1
9. For LPDDR4, x 16 and x 32 are the supported data bus width

10. Connection of DDRSS RESETn signal directly to LPDDR4\_RESET\_N memory reset input. To hold the signal low during power-on initialization, add a pull-down (10kΩ) and placed near the memory device
11. Connection of DDRSS to 16-bit and 32-bit memory devices - refer DDR design guide
12. Termination of unused DDRSS interface signals as per DDR design guide

## Schematic Review

Follow the below list for the custom schematic design:

1. Compare the bulk and decoupling capacitors used and the values with SK schematics
2. Value and tolerance used for the calibration resistors
3. Reset pull-down value and connection of ODT pullup
4. Memory selected confirms to the JEDEC standards
5. Supply rails connected follow the ROC

## Additional

1. Add layout notes on the schematic (for DDR routing to follow the recommended guidelines)

### 7.2.2 Multi-Media Card/Secure Digital (MMCSD)

The processor supports three MMCSD instances. The MMCSD Host Controller provides an interface to 1 × eMMC (8-bit) and 2 × SD/SDIO (4-bit) instances.

#### 7.2.2.1 MMC0 - eMMC (Embedded Multi-Media Card) Interface

See the following FAQs:

[\[FAQ\] AM625 / AM623 / AM62A / AM62P Design Recommendations / Commonly Observed Errors during Custom board hardware design – eMMC MEMORY Interface](#)

##### 7.2.2.1.1 AM62P, AM62P-Q1

For more information, see the *MMC0 - eMMC Interface* section of the processor-specific data sheet.

##### 7.2.2.1.1.1 MMC0 Used

###### 7.2.2.1.1.1.1 IO Power Supply

The MMC0 interface of the processor is powered by the VDD\_MMC0 (0.85V), VDD\_0P85\_DLL\_MMC0 (0.85V) and VDDS\_MMC0 (1.8V) supplies.

Connecting VDDS\_MMC0 and IO supply rail of the attached device to the same supply source is recommended.

VDD (core voltage) of the attached device can be powered from an independent supply source.

###### 7.2.2.1.1.1.2 eMMC (Attached Device) Reset

The recommendation is to implement the attached device reset using a 2-input ANDing logic. Processor general purpose input/output (GPIO) is connected as one of the input to the AND gate with provision for pullup (to support boot) near to the input and 0Ω to isolate the GPIO for testing or debug. The other AND gate input is the main domain warm reset status output (RESETSTATz) signal.

In case an ANDing logic is not used and processor main domain warm reset status output (RESETSTATz) is used to reset the attached device, match the IO voltage level of the attached device and RESETSTATz. A level translator is recommended to match the IO voltage level.

###### 7.2.2.1.1.1.3 Signals Connection

Make the following connections:

- Connect a series resistor (0Ω) for MMC0\_CLK signal (close to processor)
- Connect a resistor between MMC0\_CALPAD (close to processor) and VSS. Refer to the processor-specific data sheet for recommended resistor value and tolerance.



### Note

No external pulls are required for MMC0 eMMC PHY since the PHY enables and controls the internal pulls as required for an eMMC.

Pullups for DAT0-7 and CMD are internally enabled during reset and after reset. Pulldown is enabled for the DS and the clock output (CLK) is driven low after reset and by the SS.

There are no PADCONFIG registers associated with the MMC0 pins. The internal pulls associated with the MMC0 pins are dynamically controlled by the MMC0 host and PHY.

Provision for external pulls are not a requirement for the eMMC Data, CMD, DS and the CLK signals.

#### 7.2.2.1.1.4 Capacitors for the Power Supply Rails

Verify the required bulk and decoupling capacitors are provided for MMC0 supply rails and the attached device (core and IO supplies).

Follow the processor-specific SK implementation whenever recommendations are not available.

#### 7.2.2.1.1.2 MMC0 Not Used

MMC0 interface signals do not have alternate function. When MMC0 is not used, the interface signals and the MMC0 supplies have specific connectivity requirements.

For connecting the interface signals and MMC0 supply rails, see the *Pin Connectivity Requirements* section of the processor-specific data sheet.

#### 7.2.2.1.1.3 MMC0 (eMMC) Checklist

### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links.
2. Pin attributes, signal description, and electrical specifications.
3. Electrical characteristics, timing parameters, and any additional available information.
4. MMC0 interface is compliant with the JEDEC eMMC electrical standard v5.1 (JESD84-B51).
5. The AM62Px processor family implements a hard and dedicated PHY for eMMC interface. Refer pin connectivity requirements when eMMC is not used.
6. Include a series resistor (0Ω) on MMC0\_CLK and place as close to the processor clock output pin as possible to dampen reflections. MMC0\_CLK is looped back internally on read transactions, and the resistor is needed to eliminate possible signal reflections, which can cause false clock transitions. Use 0Ω initially and adjust as required to match the PCB trace impedance.
7. Required pulls for data, CMD, and clock are internally enabled by the eMMC hard PHY. eMMC memory provides pullup for DAT1-7 and is controlled by the software (processor pullups are enabled and eMMC pullups are disabled).
8. Powering VDDS\_MMC0 MMC0 PHY IO supply (1.8V) and the attached eMMC device IO supply from the same power source is required.
9. Processor eMMC hard PHY controls the clock input to the eMMC attached device.
10. For implementing eMMC device reset, use a 2-input ANDing logic when the memory is used for boot. Connect RESETSTATz as one of the input and processor IO as another input. Add a pullup for the processor IO input near the AND gate input pin and an isolation resistor near to the processor IO output pin. Alternatively, use RESETSTATz as the reset source. When RESETSTATz is used as the reset source, verify the IO voltage level compatibility with the eMMC IO supply. Use a level shifter as required.
11. When eMMC boot is not configured, the eMMC attached device reset can be controlled by the processor IO. The recommendation is to pulldown the reset of the eMMC memory device during reset.
12. Add additional decoupling capacitors for attached memory device as required. Refer to the SK-AM62P-LP schematics.



## Schematic Review

Follow the below list for the custom schematic design:

1. Required bulk and decoupling capacitors are provided. Compare with the SK schematics.
2. Pull values for the data, command and clock signals. Compare with the SK schematics.
3. Series resistor value and placement on the clock output signal near to the processor.
4. Implementation of reset logic including the IO level compatibility. Adding a capacitor at the reset input of eMMC attached device is not recommended when RESETSTATz or processor IO is connected directly to control the reset. A stand-alone reset connection using RC to reset the eMMC memory device is not recommended.
5. Supply rails connected follow the ROC.
6. Here is a quick checklist in case eMMC interface issues are observed:
  - Was the custom board designed to be compliant to the PCB trace delay requirements defined in the MMC0 timing conditions table found in the data sheet?
  - Which data transfer mode are users using when the issue is seen?
  - Have users checked to see if the interface works as expected when reducing the operating speed?

### Additional

1. The PHY implemented for the AM62Px MMC0 port only supports eMMC devices and does not require external pulls to hold the attached device in a known state until the port is initialized. Internal pulls are enabled when the processor is reset. There are no PADCONFIG registers associated with the MMC0 pins. The internal pulls associated with the MMC0 pins are controlled by the MMC0 host and PHY.
  - The MMC0\_CLK pin is driven low after reset. An external pulldown is not required.
  - The MMC0\_DAT0-7 pins has internal pullups enabled on during reset. So, an external pullup is not required.
  - The MMC0\_CMD pin is driven high during reset. So, an external pullup is not required.
  - The MMC0\_DS pin has the internal pulldown enabled during reset. So, an external pulldown is not required.

In summary, pull resistors for MMC0 (eMMC) signals. are enabled internally during reset and there is no requirement to add external pulls.

2. Verify that the eMMC\_RSTn reset input is enabled in the eMMC device (eMMC non-volatile configuration space) for the reset logic to be functional. The GPIO reset option makes the software able to reset the attached device (eMMC or OSPI or SD card or OLDI or EPHY) without resetting the entire processor if there is a case where the peripheral becomes unresponsive. An option is to eliminate the GPIO option and only use the reset output (warm) where the software forces a warm reset if the peripheral becomes unresponsive. However, using warm reset status output resets the entire device, rather than trying to recover the specific peripheral without resetting the entire device. When RESETSTATz is used to reset the attached device, verify the IO voltage level of the attached device matches the RESETSTATz IO voltage level. A level translator is recommended to match the IO voltage level. Alternatively, use a resistor divider, provided the optimum impedance value of the resistor divider is selected. If this is too high, then the rise and fall time of the eMMC reset input can be slow and introduce too much delay. A low resistor value causes the processor to source too much steady-state current during normal operation.
3. ANDing logic additionally performs IO level translation. Verify the reset IO level compatibility before optimizing the reset ANDing logic. IO level mismatch can cause supply leakage and affect processor operation.

#### 7.2.2.1.2 Additional Information on eMMC PHY

See the notes in the *Signal Descriptions, MMC, MAIN Domain* section of the processor-specific data sheet.

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**Note**

There can be implementation difference in the eMMC Controller and eMMC PHY IPs used on different processor families. Pay attention on the interface including terminations recommended when migrating to a different processor family.

The recommendation is to review the processor-specific data sheet, TRM, and following the connection recommendations for the processor and attached device.

Processor-specific SK implementation can be followed as required.

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**7.2.2.1.3 MMC0 – SD (Secure Digital) Card Interface**

The CD (Card Detect) and WP (Write Protect) pins are not available on MMC0 interface. MMC0 can be used to interfaces with fixed SDIO devices (on-board).

**7.2.2.2 MMC1/MMC2 – SD (Secure Digital) Card Interface**

For more information, see to the *MMC1/MMC2 - SD/SDIO Interface* section of the processor-specific data sheet.

**7.2.2.2.1 IO Power Supply**

Processor MMC1 (CMD, CLK and Data) interface IOs are powered by VDDSHV5 supply rail (IO supply for IO group 5) and MMC2 (CMD, CLK and Data) interface IOs are powered by VDDSHV6 supply rail (IO supply for IO group 6).

VDDSHV5 and VDDSHV6 are designed to support power-up, power-down, or dynamic voltage change independently of other power rails, allowing the operating voltage to change from 3.3V to 1.8V as the transfer speed increases.

VDDSHV5 and VDDSHV6 supplies are required to start with 3.3V and allow changing to 1.8V when software is ready to change the supply voltage.

Recommend using separate supply sources (LDO or similar) for VDDSHV5 and VDDSHV6 supply rails when configured as SD card interface.

Processor MMC1 SD Card Detect (CD) and Write Protect (WP) signals are powered by VDDSHV0 supply rail (IO supply for IO group 0). The recommendation is to connect the pullups for MMC1\_SDCD, MMC1\_SDWP from the SD card to the same supply rail VDDSHV0.

SD Card Detect (CD) input to the processor connects directly to ground when the SD card is inserted. A series resistor to limit the current in case the IO is configured as output due to programming error is recommended.

Processor MMC2 SD Card Detect (CD) and Write Protect (WP) signals are powered by VDDSHV6 (IO supply for IO group 6) supply rail or VDDSHV0 supply rail (IO supply for IO group 0).

**7.2.2.2.2 SD Card Supply Reset and Boot Configuration**

The recommendation is to provision for a software-enabled (controlled) power switch (load switch) that sources the SD card power supply (VDD). A fixed 3.3V supply (processor IO supply) is connected as an input to the power switch.

Use of power switch allows power cycling of the SD card (since resetting the power switch is the only way to reset the SD card) and resetting the SD card to the default state.

Recommendation is to implement the SD card power switch enable reset logic using a 3-input ANDing logic. Processor general purpose input/output (GPIO) is connected as one of the input to the AND gate with provision for pullup (to support boot) near to the input and  $0\Omega$  to isolate the GPIO for testing or debug. The other two AND gate inputs are the main domain POR (cold reset) status output (PORz\_OUT) and main domain warm reset status output (RESETSTATz) signals.

If the SD card is configured as a boot device, the external power switch sourcing the SD card power supply must default to ON (powered state).

For the implementation details, see the processor-specific SK.

### 7.2.2.2.3 Signals Connection

Make the following connections:

- Connect a series resistor (0Ω) for MMC1\_CLK and MMC2\_CLK (close to processor) and external pulldown for MMC1\_CLK and MMC2\_CLK (close to attached device or SD card socket).
- Add external pullups (47kΩ) for the data lines (MMC1\_DAT0-3 and MMC2\_DAT0-3) and CMD signal (MMC1\_CMD and MMC2\_CMD) and connect to the respective dual-voltage IO supply for IO group (MMC1 = VDDSHV5, MMC2 = VDDSHV6) supply rails (place close to attached device or SD card socket).
- Add external pullups for the MMC1\_SDCD and MMC1\_SDWP signals connected to the VDDSHV0 supply rail (close to attached device or SD card socket).
- For supporting SD card interface, configure MMC2\_SDCD and MMC2\_SDWP signals referenced to VDDSHV0. Add external pullups for the MMC2\_SDCD and MMC2\_SDWP signals connected to VDDSHV0 supply rail close to attached device or SD card socket.

See the following FAQs:

[\[FAQ\] AM62A7: Why is MMC1 powered by two different voltage supplies, VDDSHV0 and VDDSHV5?](#)

[\[FAQ\] AM62A7-Q1: how to connect the pin net VDDSHV4, VDDSHV5, and VDDSHV6 if SD card is not used](#)

[\[FAQ\] AM6442: AM6442 MMC1](#)

[FAQ\] AM625: MMC interface](#)

The FAQs are generic and can also be used for the AM62P, AM62P-Q1 processor family.

### 7.2.2.2.4 ESD Protection

External ESD protection is recommended for data, clock, and control signals. Internal ESD protection is not designed to handle the board or system level ESD requirements.

### 7.2.2.2.5 Capacitors for the Power Supply Rails

Verify the required bulk and decoupling capacitors are provided for VDDSHV5 and VDDSHV6 supply rails and attached device.

Follow the processor-specific SK implementation whenever recommendations are not available.

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#### Note

Follow the processor-specific connection recommendations for data and control signals. The recommendation is to place the series resistor for the clock output close to processor clock output pin.

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### 7.2.2.2.6 MMC1 SD Card Interface Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links.
2. Pin attributes, signal description, and electrical specifications.
3. Electrical characteristics, timing parameters and any additional available information.
4. Include a series resistor (0Ω) on MMC1\_CLK placed as close to processor clock output pin as possible to dampen reflections. MMC1\_CLK is looped back internally on read transactions, and the resistor can be needed to eliminate possible signal reflections, which can cause false clock transitions. Use 0Ω initially and adjust as required to match the PCB trace impedance.
5. The MMC1 CLK, CMD, and DAT0-3 signal functions are implemented with SDIO buffers on pins powered from VDDSHV5 (power source that changes the operating voltage from 3.3V to 1.8V as the transfer speed increases).
6. The MMC1 SDCD and SDWP signal functions are implemented with LVCMOS buffers on pins powered from VDDSHV0, which operate at fixed 1.8V or 3.3V.
7. The SDIO buffers are designed to support dynamic voltage change. Dynamic voltage change is necessary since UHS-I SD cards begins operating with 3.3V signaling and changes to 1.8V signaling when the SD card

transitions to one of the higher speed data transfer modes. Processor IO buffers are off during reset. An external pullup is required for any of the processor or attached device IOs that can float. Pullups are needed on all data and command signals. Verify internal pullups are not configured when (improves noise immunity) external pullups are used.

8. To meet the SD card specification, a 47k $\Omega$  pullup is recommended when internal pulls are unexpectedly enabled. The 47k $\Omega$  pullup verifies the resulting pull resistance is within the specified range.
9. When UHS-I speed support is required, implementing an LDO supply that switches between 3.3V and 1.8V is required. Switching IO supply can be an external discrete implementation or internal to the PMIC. Connect the switchable voltage output to the IO supply for IO group, referencing the SD interface signals (VDDSHV5).
10. When UHS-I speed support is required, while the IO voltage for SD card interface is either 1.8V or 3.3V, the SD card VDD supply is connected to a fixed 3.3V source.
11. When UHS-I speed support is required, the 3.3V SD card power is required to be switched through a load switch to allow resetting of the SD card IO supply to 3.3V. Provision to enable the SD card load switch during reset is required.
12. Provide provision to reset the load switch using the SD card load switch EN signal during cold reset, warm reset and normal operation using processor IO is required to be provided. An option is to use a 3-input ANDing logic.
13. During boot, the ROM code checks the status of the card detect pin (SDCD, pin P23). The signal is expected to be low to indicate SD card is detected (inserted).

### Schematic Review

Follow the list below for the custom schematic design:

1. Required bulk and decoupling capacitors are provided. Compare with the SK schematics.
2. Pull values used for the data, command and clock signals. Compare with the relevant SK schematics.
3. Series resistor value and placement on the clock output signal near to the processor.
4. When UHS-I speed support is required, verify IO supply rail switching and the SD card power switching circuits are added.
5. Supply rail connected to the SD card power supply (use SYS voltage).
6. Implementation of reset logic for resetting the SD card power control load switch. Provision for slew rate control of the SD card supply control power switch is provided.
7. Supply rails connected follow the ROC.
8. Required external ESD protection are provided for the SD interface signals.

### Additional

1. The logic state of the MMC1\_SDCD and MMC1\_SDWP inputs to the host must not change when a UHS-I SD card changes the IO operating voltage. Maintaining a valid logic state is not possible if the signals propagate through an input buffer of a dual-voltage SDIO cell that changes voltage. The signal functions are assigned to IOs that do not change voltage dynamically. Signals only connect to switches in the SD card connector, so there is no reason for the signals to change voltage when the SD card signals change operating voltage. The MMC1\_SDCD and MMC1\_SDWP signals are required to connect to the SD card connector switches and pull high with external pull resistors connected to the VDDSHV0. The other MMC1 SD card signals with pullups are required to have pulls powered by the VDDSHV5 source that dynamically changes voltage.
2. The MMC2\_SDCD and MMC2\_SDWP pins are referenced to the same IO supply for IO group the other MMC2 pins. However, the recommendation is not to use the control for the MMC2\_SDCD and MMC2\_SDWP signal functions if users are trying to connect an UHS-I SD card to MMC2. For SD card use case, the signal functions needs to be implemented using one of the other pin multiplexing options that uses an IO cell powered from a fixed voltage source. The MMC2 assignments are different because we only expected MMC2 to be used with on-board fixed voltage SDIO devices similar to Wi-Fi or Bluetooth<sup>®</sup> transceivers.
3. An SD card power switch, the power switch supply EN pin reset logic, and the host IO power supply circuit are required to support UHS-I SD cards, which begins communication using 3.3V IO level and later changes to 1.8V IO level when changing to one of the faster data transfer speeds.

Cycling power to the SD card is the only way to put the SD card back into 3.3V mode since SD cards do not have a reset pin. The host IO power supply must power off and on, and change voltage at the same time as the SD card. The circuits and the software driver operating the signals sourcing the circuits verifies that both devices are off, or on and operating at the same IO voltage at the same time.

4. To optimize the ANDing logic, use a dual input AND gate with RESETSTATz and the processor IO as inputs.
5. Add a series resistor 100Ω to the SDCD pin since the processor IO connects directly to the ground when the SD card is inserted.

### 7.2.2.3 MMC1 / MMC2 SDIO (Embedded) Interface

For more information, see to the *MMC1/MMC2 - SD/SDIO Interface* section of the processor-specific data sheet.

#### 7.2.2.3.1 IO Power Supply

The processor MMC1 (CMD, CLK and Data) interface IOs are powered by VDDSHV5 supply rail (IO supply for IO group 5) and MMC2 (CMD, CLK and Data) interface IOs are powered by VDDSHV6 supply rail (IO supply for IO group 6).

Processor MMC1 SD Card Detect (CD) and Write Protect (WP) signals are powered by VDDSHV0 supply rail (IO supply for IO group 0). The recommendation is to connect the pullups for MMC1\_SDCD, MMC1\_SDWP from the SDIO to the same supply rail VDDSHV0.

Processor MMC2 SD Card Detect (CD) and Write Protect (WP) signals are powered by VDDSHV6 (IO supply for IO group 6) supply rail or VDDSHV0 supply rail (IO supply for IO group 0). The recommendation is to connect the pullups for MMC2\_SDCD, MMC2\_SDWP from the SDIO to the same supply rail VDDSHV6 or VDDSHV0.

#### 7.2.2.3.2 Signals Connection

Make the following connections:

- Connect a series resistor (0Ω) for MMC1\_CLK and MMC2\_CLK (close to processor) and external pulldown for MMC1\_CLK and MMC2\_CLK (close to attached device).
- Add external pullups for the data lines (MMC1\_DAT0-3 and MMC2\_DAT0-3) and CMD signal (MMC1\_CMD and MMC2\_CMD) connected to the respective dual-voltage IO supply for IO group (MMC1 = VDDSHV5, MMC2 = VDDSHV6) supply rails (close to attached device).
- Add external pullups for the MMC1\_SDCD and MMC1\_SDWP signals connected to the VDDSHV0 supply rail (close to attached device).
- Add external pullups for the MMC2\_SDCD and MMC2\_SDWP signals connected to the VDDSHV6 or VDDSHV0 supply rail (depending on the pins (IOs) selected) (close to attached device).

#### 7.2.2.3.3 MMC2 SDIO (Embedded) Interface Checklist

### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes, signal description, and electrical specifications.
3. Electrical characteristics, timing parameters, and any additional available information.
4. Include a series resistor (0Ω) on the MMC2\_CLK, placed as close to processor clock output pin as possible to dampen reflections. To prevent signal reflections and false clock transitions, a resistor can be required to eliminate possible signal reflections on MMC2\_CLK, which is looped back internally on read transactions. Use 0Ω initially and adjust as required to match the PCB trace impedance.
5. The MMC2 CLK, CMD, and DAT0-3 signal functions are implemented with SDIO buffers on pins powered from VDDSHV6, which operate at fixed 1.8V or 3.3V.
6. The MMC2 SDCD and SDWP signal functions are implemented with LVCMOS buffers on pins powered from VDDSHV6 or VDDSHV0, which are operated at fixed 1.8V or 3.3V.
7. The SDIO buffers are designed to support dynamic voltage change. When SDIO interface is used, connecting a fixed IO voltage (1.8V or 3.3V) is recommended.
8. Processor IO buffers are off during reset. An external pullup is required for any of the processor or attached device IOs that can float. Pullups are needed on all data and command signals. Verify internal pullups are not configured when (improves noise immunity) external pullups are used. As a good design practice, a



47k $\Omega$  pullup is recommended for the pullup value to be within the SDIO specification when internal pulls are enabled unexpectedly. With 47k $\Omega$ , the resulting pull resistance is still within the specified.

9. Attached device reset implementation using processor IO. Verify the IO level compatibility and the connection of required pull (polarity is attached device dependent).

### Schematic Review

Follow the list below for the custom schematic design:

1. Required bulk and decoupling capacitors are provided. Compare with the SK schematics.
2. Pull values used for the data, command and clock signals. Compare with the relevant SK schematics.
3. Series resistor value and placement on the clock output signal near to the processor.
4. Implementation of reset logic.
5. Supply rails connected follow the ROC and is a fixed supply.

### Additional

1. Verify required external ESD protection are provided for the interface signals when connected over an add-on card.
2. Follow similar guidelines when using MMC1. When using MMC1, software changes are required because the SK only implements the SDIO interface on MMC2.
3. There are no specific guidelines about SDIO devices providing or not providing internal pulls. The board designer implementing an embedded SDIO device must understand what the SDIO device provides and apply the appropriate external pull if not provided by the SDIO device. Most of the processor IOs buffers are off during reset and are not enabled until the board has booted and the software configures. To prevent floating inputs, use external pulls on any signals connected to the inputs of attached devices.
4. For embedded SDIO application, the recommendation is to power IO supply rail from the same fixed 1.8V or 3.3V power source that is used to power the IOs of the SDIO attached device (an example is a Wi-Fi<sup>®</sup> module).

#### 7.2.2.4 Additional Information

See the notes in the *Signal Descriptions, MMC, MAIN Domain* section of the processor-specific data sheet.

#### 7.2.3 Octal Serial Peripheral Interface (OSPI) or Quad Serial Peripheral Interface (QSPI)

For more information, see the *OSPI/QSPI/SPI Board Design and Layout Guidelines* section of the processor-specific data sheet.

See the following FAQ:

[\[FAQ\] AM625 / AM623 / AM62A / AM62P Design Recommendations / Commonly Observed Errors during Custom board hardware design – OSPI/QSPI MEMORY Interface](#)

##### 7.2.3.1 IO Power Supply

The processor IOs used for the OSPI or QSPI are powered by VDDSHV1 supply rail (IO supply for IO group 1).

The recommendation is to connect VDDSHV1 and the IO supply rail of the attached device to the same supply source.

VDD (core voltage) of the attached device can be powered from an independent supply source.

##### 7.2.3.2 OSPI/QSPI Device Reset

The recommendation is to implement the attached device reset using a 2-input ANDing logic. Processor general purpose input/output (GPIO) is connected as one of the input to the AND gate with provision for pullup (to support boot) near to the input and 0 $\Omega$  to isolate the GPIO for testing or debug. The other AND gate input is the main domain warm reset status output (RESETSTATz) signal.

In case an ANDing logic is not used and processor main domain warm reset status output (RESETSTATz) is used to reset the attached device, match the IO voltage level of the attached device and RESETSTATz. A level translator is recommended to match the IO voltage level.



### 7.2.3.3 Signals Connection

Make the following connections:

- Provision for a series resistor (0Ω) for OSPI0\_CLK and OSPI0\_LBCLKO (close to processor) and external pulldown for OSPI0\_CLK (close to attached device).
- Provision for external pullups for CS pin and INT# pin (close to attached device).
- Provision for external pullups for the data lines (DAT0:7) (close to processor). Depending on the availability of pulls internal to the attached device, populate the external pulls.

### 7.2.3.4 Loopback Clock

Verify the required loopback clock configuration. Different configuration of clock loopback can be made using OSPI0\_LBCLKO (OSPI0 Loopback Clock Output) and OSPI0\_DQS (OSPI0 Data Strobe or Loopback Clock Input). For the following loopback configurations, see the processor-specific data sheet:

- *No Loopback, Internal PHY Loopback, and Internal Pad Loopback*

#### **External Board Level Loopback**

*Processor DQS or Loopback Clock is used along with the DS data strobe of attached memory device*

When DS (Read Data Strobe) pin is available on the attached device, connect the DS pin of the attached device to the OSPI0\_DQS pin of the processor. Leave the OSPI0\_LBCLKO pin unconnected.

In case DS pin is not being currently used, to configure the external loopback connect the OSPI0\_LBCLKO output pin of the processor to the OSPI0\_DQS input pin of the processor.

If External Loopback is not used, the recommendation is to leave the OSPI0\_LBCLKO and OSPI0\_DQS pins unconnected.

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#### **Note**

D0 and D1 pins of the processor OSPI0 interface must be connected to D0 and D1 pins of the OSPI/QSPI memory device to support legacy x1 commands. Data bit swapping is not allowed.

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### 7.2.3.5 Interface to Multiple Devices

Connecting an OSPI0 interface to multiple memory devices is currently not supported. Connect the OSPI0 interface (processor) to a memory device. In case the OSPI0 is interfaced to multiple memory devices, the interface creates a split data bus which can severely degrade signal integrity at higher speeds. For accessing OSPI memory device at high speeds, a point-to-point connection of the data bus is recommended.

### 7.2.3.6 Capacitors for the Power Supply Rails

Verify the required bulk and decoupling capacitors are provided for VDDSHV1 supply rail and the attached device (core and IO supplies).

Follow the processor-specific SK implementation whenever recommendations are not available.

### 7.2.3.7 OSPI or QSPI Interface Implementation Checklist

#### **General**

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes, signal description and electrical specifications
3. Electrical characteristics, timing parameters and any additional available information
4. Required memory interface configuration and recommended connections for the attached device are provided
5. The attached device IO supply and the IO supply for IO group VDDSHV1 referenced to the interface signals are connected to the same supply source
6. Series resistor 0Ω provision for clock signal is provided near to the processor clock output pin

7. Provision for pullups are provided for data and control signals that can float. Verify the supply source connected to the pullups
8. Pulldown 10k $\Omega$  is provided for the clock input near to the attached (memory) devices
9. Reset logic implementation when used for boot using a 2-input (RESETSTATz and processor IO) ANDing logic or using warm reset status output RESETSTATz is recommended
10. Verify the reset IO level compatibility between processor and attached device
11. Pulling up the reset input to a high state during reset or supply ramp is not recommended
12. Clock loop back configuration based on the memory device and interface selected (OSPI/QSPI)
13. In case OSPI/QSPI boot mode is implemented, verify the Errata, selected memory meets the boot mode criteria described in the TRM (or verify with TI using E2E)

## Schematic Review

Follow the below list for the custom schematic design:

1. Compare the implementation with SK schematics for parallel pulls and series resistors for values
2. Compare implementation of attached device reset logic with the SK schematics
3. Connecting the interface to multiple attached devices (more than 1 attached device) is not allowed or recommended
4. Supply rails connected follow the ROC
5. Implementation of external loopback based on the use case

## Additional

1. Verify that the *OSPI/QSPI/SPI Board Design and Layout Guidelines* section of the data sheet is followed
2. Review and follow the electrical, timing and switching characteristic

### 7.2.4 General-Purpose Memory Controller (GPMC)

#### 7.2.4.1 IO Power Supply

The processor IOs used for GPMC interface are powered by VDDSHV3 supply rail (IO supply for IO group 3).

The recommendation is to connect VDDSHV3 and the IO supply rail of the attached device to the same supply source.

VDD (core voltage) of the attached device can be powered from an independent supply source.

#### 7.2.4.2 GPMC Interface

Verify the number of attached devices connected to the GPMC interface.

The recommendation is to connect the GPMC interface to one device in synchronous mode. Using multiple devices or CSns requires splitting the GPMC clock (and other interface signals) on-board, which can cause signal integrity issues.

A detailed timing analysis is recommended when interfacing multiple devices in asynchronous mode. Interfacing multiple devices is not recommended. When interfacing multiple devices in asynchronous mode, the control signals are required to be routed to multiple devices. The split routing and loading (trace length and number of devices) issues have an affect on custom board performance.

#### 7.2.4.3 Memory (Attached Device) Reset

When using NAND flash or NOR flash with GPMC, many memories interfaced over GPMC can lack a reset pin.

In case the reset pin is available, review the reset requirements and connect the reset pin to the relevant reset source.

#### 7.2.4.4 Signals Connection

Provide a series resistor (0 $\Omega$ ) for GPMC0\_CLK (close to processor).

Recommend provisioning for external pullups on GPMC0\_CS0-3 (depending on the configuration) to hold the signal high when processor is held in reset, or after reset, before software has configured the PADCONFIG registers to enable the TX buffer.

#### 7.2.4.4.1 GPMC NAND

The active high ready and active low busy (R/B#) output from the NAND flash is open-drain and is connected to the GPMC0\_WAIT0 and GPMC0\_WAIT1 signals (depending on the configuration). The recommendation is to provide the pullup (commonly used value 4.7k $\Omega$  or 10k $\Omega$ ) close to the attached device.

#### 7.2.4.5 Capacitors for the Power Supply Rails

Verify the required bulk and decoupling capacitors are provided for VDDSHV3 supply rail and the attached device (core and IO supplies).

Follow the processor-specific SK implementation whenever recommendations are not available.

#### 7.2.4.6 GPMC Interface Checklist

##### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin connectivity requirements, pin attributes and signal description
3. Electrical characteristics, Timing parameters and any additional available information
4. GPMC interface configuration and recommended connections
5. IO level compatibility between processor and attached device
6. GPMC memory interface configuration (NAND or NOR flash), interface mode used - Async or Sync clock mode
7. Connection to multiple devices in allowed in Async mode, perform timing and load calculation before use
8. Series resistor 0 $\Omega$  near to the processor GPMC clock output pin
9. The attached device IO supply and IO supply for IO group VDDSHV3 referenced to the GPMC interface signals are connected to the same supply source
10. Verify the recommended or required pulls are provided
11. Verify the required interface configuration and recommended connections are provided
12. Attached device IO compatibility with the processor GPMC controller signals
13. Supported address and data range (IOs pinned out of the device as mentioned in the data sheet)
14. GPMC interface timing required versus feasible and effect of layout
15. Addition of pulls as required
16. Connection of GPMC memory NAND/ NOR, address and data signals - multiplexed or non-multiplexed, synchronous or asynchronous, data bit width as per the TRM

##### Schematic Review

Follow the below list for the custom schematic design:

1. Required pulls are provided based on the memory interfaced
2. Pulls are provided for any of the interface signals that can float
3. Supply rails connected follow the ROC

### 7.3 External Communication Interface (Ethernet (CPSW3G), USB2.0, UART and Controller Area Network (CAN))

#### 7.3.1 Ethernet Interface Using CPSW3G (Common Platform Ethernet Switch 3-Port Gigabit)

CPSW3G supports the RGMII (10/100/1000) and RMII (10/100) interfaces.

##### 7.3.1.1 IO Power Supply

The processor Gigabit Ethernet Media Access Controller (GEMAC) IOs (used for Ethernet interface) are powered by VDDSHV2 supply rail (IO supply for IO group 2).

The recommendation is to connect VDDSHV2 and the IO supply rail of the attached device to the same supply source.

VDD (core voltage) of the attached device can be powered from an independent supply source.

### 7.3.1.2 Ethernet PHY Reset

The recommendation is to implement the attached device reset using a 3-input ANDing logic. Processor general purpose input/output (GPIO) is connected as one of the input to the AND gate with provision for pullup (to support boot) near to the input and 0Ω to isolate the GPIO for testing or debug. The other two AND gate inputs are the main domain POR (cold reset) status output (PORz\_OUT) and main domain warm reset status output (RESETSTATz) signals.

If a dual input AND gate is used, PORz\_OUT or RESETSTATz can be connected as one of the input along with the processor GPIO input as the second input based on the use case. When more than one EPHY is used, provide provision to reset the EPHYs individually.

A pullup or pulldown at the output of the ANDing logic is recommended based on the EPHY reset input pin configuration. The EPHYs are required to be held in reset for a specified minimum reset hold time after the respective clocks are valid.

In case an ANDing logic is not used and processor main domain warm reset status output (RESETSTATz) is used to reset the attached device, match the IO voltage level of the attached device and RESETSTATz. A level translator is recommended to match the IO voltage level.

### 7.3.1.3 Ethernet PHY Pin Strapping

Many of the TI EPHYs configure the outputs as inputs during reset and captures the configuration (pin strapping is done through resistors) information on strap inputs when the processor reset is released. Applying appropriate pullup or pulldown on strap inputs (IOs) can be necessary, which also connects to processor IOs. TI EPHYs used on the processor-specific SK use a combination of pullup and pulldown allowing multiple configuration modes to be configured using each pin. During processor reset, the IO buffers and internal pullup or pulldown are disabled, which minimizes any concern of a mid-supply potential being applied to the processor input buffer by the EPHY. The EPHYs are required to be configured to normal state from reset state to drive a valid logic state before enabling any of the associated processor input buffers.

### 7.3.1.4 Ethernet PHY (and MAC) Operation and Media Independent Interface (MII) Clock

Verify the clock input option used for Ethernet PHY and MAC based on the interface.

#### 7.3.1.4.1 Crystal

If a crystal is used as the clock source for the EPHY, the recommendation is to match crystal (clock) specifications with the processor crystal (clock) specifications to optimize performance.

#### 7.3.1.4.2 Oscillator

Using an external clock (LVCMOS) oscillator as the clock source for the processor and the EPHY allows for the use of either a shared oscillator or a separate oscillator. When using one oscillator, buffer the clock output before connecting to the processor and EPHY.

Use a single output, individual buffer, or dual or multiple output buffer to connect the clock output of the oscillator to the processor and EPHYs.

For specific use case (requirement for some of the industrial applications using one Time Sensitive Networking (TSN)) input or two or more outputs (based on number of EPHYs used) buffer is recommended for the processor and the EPHYs.

Verify that the crystal XO of the EPHY is connected according to the recommended guidelines.

#### 7.3.1.4.3 Processor Clock Output (CLKOUT0)

For optimizing the design, the processor clock output (CLKOUT0) can be used as clock input to the EPHY. Clock output is buffered internally and is intended to be used for a point-to-point clock topology. A series resistor is recommended at the source end of the CLKOUT0 to minimize reflections.

RGMII EPHYs require a 25MHz clock input that is not synchronous to any other signals. 25MHz clock signal does not have any timing requirements, but is important the EPHY does not receive any non-monotonic transitions on the clock input.

RMII EPHY clocking option changes with the EPHY controller or device configuration.

When configured as a controller, most RMIIE PHYs require a 25MHz input clock that is not synchronous to any other signals, the 25MHz clock signal does not have any timing requirements, but is important to make sure the PHY does not receive any non-monotonic transitions on the clock input.

The RMIIE PHY provides the 50MHz clock output to the MAC. For RMIIE use case, the 50MHz data transfer clock is delayed to the MAC relative to the PHY. The delay shifts clock to data timing relationship which can erode the timing margin. Eroded timing margin can be problematic for some designs if the delay is too large.

When configured as a device, the MAC and the PHY uses a 50MHz common clock that is synchronous to both transmit and receive data. The 50MHz clock is defined in the RMIIE specification as a common data transfer clock signal that is used by both the MAC and the PHY, where transitions are expected to arrive simultaneously at the MAC and PHY device pins. The common clock provides better timing margin for both transmit and receive data transfers. Important requirement is that the MAC and PHY do not receive any non-monotonic transitions on the clock inputs. To take care of the clock signal integrity, recommendation is to route the common clock signal through a two-output phase aligned buffer. Recommend using equal length signal traces that are half the length of the data signals for connecting the clock buffer outputs, where one clock output connects to the MAC and the other connects to the PHY.

For RMIIE interface, the recommended configuration is *RMIIE Interface Typical Application (External Clock Source)* as explained in the processor-specific TRM. If the *RMIIE Interface Typical Application (Internal Clock Source)* configuration explained in the processor-specific TRM is used, then the performance has to be validated on a board level. Provision for an external clock for initial performance testing and comparison is recommended. The Ethernet performance (RGMII) is validated on the processor and the PHY with 25MHz clock.

The CLKOUT0 function can be used to source a 25MHz or a 50MHz clock input to PHY. However, using CLKOUT0 signal function requires the software to configure the clock output. The CLKOUT0 clock configuration cannot be used if the board design must support Ethernet boot. CLKOUT0 connected as PHY clock is likely to glitch anytime the configuration is changed.

For AM62Px family of processor, WKUP\_CLOCKOUT0 is required to be configured to source the device reference clock (MCU\_OSC0\_XO). The clock output does not glitch after the clock begins to toggle. However, the first high or low pulse can be short because reset is released asynchronous to the HFOSC0 clock.

The PHYs are required to be held in reset for a specified minimum reset hold time after the respective clocks are valid.

Processor clock output performance is not defined because clock performance is influenced by many variables unique to each custom board design. The board designer must validate timing of all peripherals by using the actual PCB delays, minimum or maximum output delay characteristics, and minimum setup and hold requirements of each device to confirm there is enough timing margin.

### 7.3.1.5 MAC (Data, Control and Clock) Interface Signals Connection

Series resistors are recommended for the Ethernet MAC interface signals. Use smallest possible package (0402 or smaller) and place series resistors close to source. To start with place series resistor (22Ω) for the TDn signals near to the processor pins. For the RDn signals the internal impedance control (series resistors) of the PHY can be used. Providing provision for external series resistors (0Ω) are recommended on the RDn signals.

The interrupt output of the PHY can be connected to the processor EXTINTn (interrupt) pin. The recommendation is to connect a pullup for the EXTINTn close to processor.

### 7.3.1.6 External Interrupt (EXTINTn)

EXTINTn is an open-drain output type buffer, fail-safe IO. The recommendation is to connect an external pullup resistor when a PCB trace is connected to the pad and an external input is not being actively driven. Open-drain output type buffer IO has slew rate requirements specified when the IO is pulled up to 3.3V. An RC is recommended for limiting the slew rate.

For more information, see the [\[FAQ\] AM625 / AM623 / AM625SIP / AM625-Q1 / AM620-Q1 / AM62A7 / AM62A3 / AM62P / AM62P-Q1 Custom board hardware design – EXTINTn pin pullup connection](#).



### 7.3.1.6.1 External Interrupt (EXTINTn) Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes (open-drain output IO buffer) and signal description
3. Electrical characteristics (fail-safe and slew rate requirements when pulled to 3.3V), timing parameters and any additional available information
4. An external pullup is recommended when a signal trace is connected and not being actively driven
5. EXTINTn is an open-drain output type buffer, fail-safe IO. An external pullup is recommended when a trace or external input is connected
6. Open-drain output type IO. EXTINTn has slew rate requirements specified when pulled to 3.3V supply. Add an RC at the input to limit the slew rate. Refer TMDS64EVM

#### Schematic Review

Follow the below list for the custom schematic design:

1. Pullup value used. Compare with the SK schematics
2. Pullup referenced to the processor VDDSHVx (pullup connected to correct IO voltage level)
3. RC provision for slew rate control and RC values used. Refer TMDS64EVM

### 7.3.1.7 MAC (Media Access Controller) to MAC Interface

For applications requiring EPHY-less (MAC-to-MAC) connection between processors, using the RGMII interface is recommended (check with TI if the MAC-to-MAC interface is officially supported on the selected processor family) since the clocks are source synchronous.

When MAC-to-MAC interface between 2 processors are used, verify fail-safe operation, matching of clock specifications, and IO level compatibility.

### 7.3.1.8 MDIO (Management Data Input/Output) Interface

The processor IOs used for MDIO interface are powered by VDDSHV2 supply rail (IO supply for IO group 2).

The recommendation is to connect an external pullup (close to the EPHY) for the MDIO0\_MDIO (MDIO data) signal.

Before configuring the MDIO interface, see the advisory *i2329 MDIO: MDIO interface corruption (CPSW and PRU-ICSS)* of the processor-specific silicon errata.

### 7.3.1.9 Ethernet MDI (Medium Dependent Interface) Including Magnetics

In case the EPHY and MDI interface including the magnetics and the RJ45 connector are implemented on the processor board, follow the processor-specific SK for MDI interface connections, recommended magnetics used on the SK, external ESD protection, and connection of RJ45 connector shield to circuit ground.

### 7.3.1.10 Capacitors for the Power Supply Rails

Verify the required bulk and decoupling capacitors are provided for VDDSHV2 supply rail and the attached device (core and IO supplies).

Follow the processor-specific SK implementation whenever recommendations are not available.

### 7.3.1.11 Ethernet Interface Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes and signal description.
3. Electrical characteristics, timing parameters, and any additional available information.



4. MAC interface configuration and recommended connections including series resistors (on the TDn signals near to processor MAC TDn output pins and optional 0Ω series resistors near the attached device for the RDn signals).
5. IO level compatibility between processor MAC and EPHY (attached device). The attached device IO supply and the IO supply for IO group VDDSHV2 referenced by the interface signals are recommended to be connected to the same supply source.
6. Matching of processor and EPHY clock specifications.
7. Clocking of EPHY and processor MAC including addition of buffers based on the EPHY configuration and clock architecture (use of common Oscillator and Buffer or RMII interface). When the clock output connects to more than one inputs, each of the clock inputs must be buffered using individual buffers.
8. Interface connections, IO level compatibility, fail-safe operation (when MACs are powered by different power sources) and matching of clock specifications when MAC-to-MAC interface is used.
9. MDIO interface connection including pullup for MDIO data added near to the EPHY. MDIO connection to multiple devices and the addition of pullup near each EPHY.
10. When two EPHYs are used, configuration of EPHY device address to read the internal registers through the MDIO interface.
11. Implementation of EPHY reset logic. When 2 EPHYs are used, the recommendation is to provide provision to reset the EPHYs individually. When used for boot a 2 or 3 input ANDing logic can be used.
12. In case implementing an Ethernet boot is required, verify the errata, supported EPHY interface configurations, MAC interface port used versus recommended, and the recommended clock and interface connection.

## Schematic Review

Follow the list below for the custom schematic design:

1. Provision for series resistor for the processor MAC transmit signals TDn near to the processor output pins have been provided and the initial value (0Ω or 22Ω)
2. Verify the EPHY reset implementation including ANDing logic, EPHY reset input pull and compare with SK as required.
3. Verify EPHY device address configuration when 2 EPHYs are used and MDIO interface is required.
4. MDIO data pullup is provided near to the EPHY
5. Verify the IO level compatibility - the attached device IO supply and IO supply for IO group referenced by the processor interface signals are connected to the same supply source.
6. Compare the bulk and decoupling capacitors used for all the EPHY supply rails with SK schematics when TI EPHY is used.
7. Pullup is provided for processor GPIO input of the EPHY reset ANDing logic.
8. Pullup on the MDIO clock can be optional (EPHY can have internal pulldown; verify in the data sheet)
9. Supply rails connected follow the ROC.
10. When more than 1 EPHY is connected, provision to reset the EPHYs individually is provided. Addition of pull at the EPHY reset input as required

## Additional

1. Follow the steps below when TI EPHY is used:
  - Obtain a review of the implementation done with the EPHY business unit or product line.
  - Verify the power sequence requirements for two-supply configuration and three-supply configuration.
  - Verify the RBIAS resistor tolerance as per the EPHY data sheet.
  - Selection of the RJ45 connector with integrated magnetics, follow SK.
  - Provision for external ESD protection for the MDI signals.
  - Connection of RJ45 connector shield to circuit ground.
  - The recommended bulk and decoupling capacitors are provided (refer SK as required).
2. Use a single output, individual buffer device, or dual or multiple output buffer to connect the clock output of the oscillator to the processor and EPHYs. For a specific use case (requirement for some of the industrial applications using a Time Sensitive Networking (TSN)), input and two or more output (based on number of EPHYs used) buffer is recommended for the processor and the EPHYs.
3. When EPHY is configured as RMII peripheral, two-output phase aligned buffer with a common input is recommended.

4. If space is not a constraint, then consider adding 0Ω series resistors on the RDn signals near to the EPHY.
5. ANDing logic additionally performs IO level translation. Verify the reset IO level compatibility before optimizing the reset ANDing logic. IO level mismatch can cause supply leakage and affect processor operation.
6. To simplify the ANDing logic, use a dual input AND gate with RESETSTATz and the processor GPIO as inputs.
7. Verify recommendations as per the data sheet or EVM implementation are considered for the attached device, including terminations and external ESD protection.

### 7.3.2 Universal Serial Bus (USB2.0)

The processor provides 2 USB2.0 interfaces that are configurable as host, device, or dual-role device (DRD).

USBn\_VBUS (n = 0-1) is recommended to connect in accordance with the *USB Design Guidelines* section of the processor-specific data sheet. The supply voltage range for the USBn\_VBUS pins is defined in the *Recommended Operating Conditions* section of the processor-specific data sheet. The nominal voltage value applied is equal to the resistor divider output when VBUS supply voltage level is 5V.

USBn\_ID functionality is supported through any of the processor GPIOs.

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#### Note

USBn\_VBUS are fail-safe inputs. The fail-safe input is valid only if the VBUS supply is connected through recommended *USB VBUS Detect Voltage Divider / Clamp Circuit*.

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#### 7.3.2.1 USBn (n = 0-1) Used

The recommendation is to connect the USB supplies VDDA\_CORE\_USB (USB0 and USB1 core supply), VDDA\_1P8\_USB (USB0 and USB1 1.8V analog supply), and VDDA\_3P3\_USB (USB0 and USB1 3.3V analog supply) to the recommended power supply rails in the processor-specific data sheet.

Connect USBn\_DM (n = 0-1) and USBn\_DP (n = 0-1) signals directly (without any series resistors or capacitors). Route USBn signals with traces that does not include any stubs or test points.

Connect a resistor between USBn\_RCALIB (n = 0-1) (close to processor) and VSS. Refer to the processor-specific data sheet for recommended resistor value and tolerance.

##### 7.3.2.1.1 USB Host Interface

The recommendation is to provide a power switch to control the VBUS supply to externally connected device and protect power switch input supply from being overloaded.

The power switch output connects to the USB type A connector. The recommendation is to connect a capacitor (> 120μF) to the VBUS supply close to the connector.

The USBn\_DRVVBUS (n = 0-1) signals with an internal pulldown is used to enable the VBUS power switch. An external pulldown near to the power switch enable (EN) pin is recommended. Connection of USBn\_VBUS (VBUS supply input including Voltage Divider, Clamp) is optional.

If the power switch used has an OC (over current) indication output, pullup the OC indication output and connect to the processor IO (input).

##### 7.3.2.1.2 USB Device Interface

The VBUS power is sourced by an external host. USB standard for device operation recommends connecting < 10μF capacitor to the VBUS close to the USB Type-B connector.

Follow the *USB VBUS Design Guidelines* section of the processor-specific data sheet to scale the USB VBUS voltage (supply near the USB interface connector) before connecting to USBn\_VBUS pins.

Based on the use case, the zener diode can be deleted if the user is absolutely sure that the board never experiences a VBUS signal potential > 5.5V (sourced on-board).

### 7.3.2.1.3 USB Dual-Role-Device Interface

If the custom board design uses USB Micro-AB connector, the USBn\_ID signal from the connector can be routed to the processor GPIO pin. USBn\_ID can be connected to any available GPIO pin. The GPIO pin is specified in the board device tree file, including the pinmux setting of the GPIO pin.

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#### Note

Full compliant USB On-The-Go (OTG) feature is not supported. The ID pin is not bonded out.

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### 7.3.2.1.4 USB Type-C®

If the custom board design uses USB Type-C® connector, the USBn\_ID signals connection is not a requirement. The DRD mode switching is controlled by the USB Type-C companion device.

DRP (Dual Role Port) requires a controller, primarily to switch power based on the negotiated role. In a Device Mode only, USB2.0 only, USB Type-C implementations where the device is not powered by the USB Type-C connector, no USB Type-C controller is required.

- The CC pins at the connector are required to be independently grounded via 5.1kΩ resistors.
- The USB DP and USB DM connector pins are shorted on the PCB (DM=B7:A7, DP=B6:A6). Shorting allows for USB2.0 connectivity regardless of cable orientation. Keep the resulting stubs as short as possible.

Refer to the *USB VBUS Design Guidelines* section of the processor-specific data sheet for more details on USBn\_VBUS input scaling recommendations.

The AM62 SK USB0 interface design can be a reference for implementation of the USB Type-C interface.

### 7.3.2.2 USBn (n = 0-1) Not Used

When USB0 and USB1 are not used or USB0 or USB1 is not used, the interface signals and the USB supplies have specific connectivity requirements.

For connecting the interface signals and USB supply pins, see the *Pin Connectivity Requirements* section of the processor-specific data sheet.

The recommendation is to connect the USB supplies (VDDA\_CORE\_USB, VDDA\_1P8\_USB, and VDDA\_3P3\_USB) to VSS through separate 0Ω resistors.

In case USB0 or USB1 are used for future expansion, connect the signals (USBn\_DM, USBn\_DP, USBn\_RCALIB and USBn\_VBUS) with the shortest possible traces and connect at test points or connectors. Additionally, recommendation is to provide provision to connect the required USB supplies.

### 7.3.2.3 Additional Information

Connect USBn\_DM and USBn\_DP signals directly from the processor to the USB hub upstream port. The hub then distributes USBn signals to the downstream ports as needed. As each hub has different implementation requirements, follow the hub manufacturer recommendations.

For more information on USB2.0 interface, see the [\[FAQ\] AM625 / AM623 / AM625SIP / AM625-Q1 / AM620-Q1 Custom board hardware design – USB2.0 interface](#). The FAQ is generic and can also be used for AM62P, AM62P-Q1 processor family.

### 7.3.2.4 USB Interface Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links.
2. Pin connectivity requirements, pin attributes and signal description.
3. Referenced specific standard for electrical characteristics, timing parameters and any additional available information.
4. Required USB interface configuration (Host or Device) and recommended connections.
5. USB VBUS design guidelines based on the USB interface configuration. USBn\_VBUS connection is optional for Host configuration. Connecting 5V supply from the USB connector directly to the USBn\_VBUS pin is

not allowed or recommended. Changing the data sheet VBUS recommended divider value is not allowed or recommended. VBUS fail-safe capability of the IO is valid only when the recommended divider values are implemented.

6. Connection of recommended IO calibration resistor.
7. Connection of the recommended USB supplies including filtering.
8. Direct connection of the USB signals.
9. Common-mode chokes can be used for EMI control. Adding common-mode choke can reduce the signal amplitude and degrade performance. Add provision to bypass the CMC using 0Ω resistors
10. Marking of differential signals and the differential impedance value.
11. Implementation of USB power switch when USB interface is configured as host.
12. USB power switch enable control using DRVVBUS (internal pulldown is enabled during reset).
13. Connection of the power switch OC output to processor IO.
14. Connection of the USB signals to the USB connector.
15. Provision for recommended capacitors on the USB VBUS pin of the USB connector.
16. Provision for required external ESD protections for the USB interface.
17. In case USB boot is implemented, verify the errata, supported interface configuration, USB port and the connections.

### Schematic Review

Follow the list below for the custom schematic design:

1. USB interface connection matches the required USB interface configuration (Host or Device). Compare the interface connection with the SK.
2. External ESD protection and CMC implementation with provision to bypass using 0Ω resistors.
3. VBUS voltage divider values (follow data sheet) and tolerance (1%). Follow the data sheet recommendations. Use of multiple resistors is allowed provided the value, tolerance and ratio is maintained.
4. VBUS capacitor values used versus requirements (refer SK).
5. Power switch enable connection (in case processor USBn\_DRVVBUS is used, pullup is not recommended or allowed since the DRVVBUS has an internal pulldown enabled).
6. Connection of power switch OC output to the processor IO and IO level compatibility.
7. Supply rails connected follow the ROC.

### Additional

1. In case a Type-C USB interface is implemented using TI devices, obtain a review of the implementation done with the relevant business unit or product line.
2. A filtered supply (ferrite and capacitors) is used for VDDA\_CORE\_USB and VDDA\_1P8\_USB. VDDA\_3P3\_USB can be connected to the 3V3 SYS voltage. Refer to the specific and latest SK for implementation as filters are being continuously optimized.
3. Verify fail-safe operation of USB interface. Applying an external interface signal before supply ramps can cause voltage feed and can affect the custom board functions.
4. When a CMC is used on the USB data lines, verify the connections including the polarity. Reversing the polarity can short the data signals.
5. DNI USBn\_DRVVBUS pullup and pulldown to implement wakeup from deep sleep.

### 7.3.3 Universal Asynchronous Receiver/Transmitter (UART)

Verify the application requirements for UART interface (external communication interface or debug) and configuration (2-wire or 4-wire with flow control). For the number of UART instances supported, see the processor-specific data sheet.

When an external transceiver is used, match the external interface signal IO levels and the dual-voltage IO supply for IO group voltage level. The recommendation is to power the IO supply of the transceiver and the processor IO supply rail from the same source. Verify fail-safe operation and the pullup voltage reference as required.

The recommendation is to provision the series resistors on the interface signals, close to source, for isolation or debug.

A pullup is recommended on the processor UART receive pins (UARTn\_RXD (n = 0-6), MCU\_UART0\_RXD, and WKUP\_UART0\_RXD). Verify the availability of pulls on the external interface signal and configure the pull accordingly.

External ESD protection is recommended in case the interface signals from the processor are directly connected to external inputs.

The UART interface is frequently hooked up incorrectly. Connect the signals as below:

- TX to RX
- RX to TX

Verify the connections if additional interface signals are used.

When the debug interface UART signals are directly connected to external interface, take note of fail-safe operation, IO levels. Provide provision for external ESD protection.

### 7.3.3.1 Universal Asynchronous Receiver/Transmitter (UART) Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above section, including relevant application notes and FAQ links
2. Pin attributes and signal description
3. Electrical characteristics, timing parameters, and any additional available information
4. Provision for series resistors near to source added for all the interface signals to minimize reflections or isolate for testing
5. Parallel pull added for any of the processor or attached IOs that can float
6. Interface signal polarity and connection
7. External ESD protection when the interface signals are connected directly to external inputs
8. Required speed, programmed Baud rate versus supported baud rate, and required versus calculated error due to clock divider mismatch

#### Schematic Review

Follow the below list for the custom schematic design:

1. Pullup values used (10k $\Omega$  or similar) and compare with the SK schematics.
2. Series resistor value used (22 $\Omega$ ) and the placement (near to source).
3. Pullup referenced to the processor VDDSHVx for corresponding UART instance and signals.
4. Processor VDDSHVx and the attached device IO supply sourced from the same supply.
5. Processor IOs are not fail-safe. Applying an input before the processor supply ramps is not allowed or recommended.
6. Supply rails connected follow the ROC.

#### Additional

1. Verify fail-safe operation when connected to external interface signals. Applying an external input signal before processor supply ramps can cause voltage feed and can affect the custom board functions.
2. Verify recommendations as per the data sheet or EVM implementation have been considered for the attached device including terminations and external ESD protection.

### 7.3.4 Controller Area Network (CAN)

For the number of CAN instances supported, see the processor-specific data sheet. The CAN interface to the processor includes external CAN transceiver.

When an external transceiver is used, match the external interface signal IO levels with the dual-voltage IO supply for IO group voltage level.

Provide the required terminations for the CAN transceiver.

Recommend provisioning for series resistors on the interface signals (close to source) for isolation or debug.



### 7.3.4.1 Controller Area Network Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above section, including relevant application notes and FAQ links
2. Pin attributes and signal description
3. Electrical characteristics, timing parameters, and any additional available information
4. Provision for series resistors added for all the interface signals to minimize reflections or isolate for testing
5. Parallel pull added for any of the processor or attached device IOs that can float

#### Schematic Review

Follow the below list for the custom schematic design:

1. Series resistor value used ( $0\Omega$ ) and the placement (near to source)
2. Pullup referenced to the processor VDDSHVx for corresponding CAN instance and pins
3. Processor VDDSHVx and the attached device IO supply sourced from the same supply
4. Processor IOs are not fail-safe. No input can be applied before the processor supply ramps
5. Supply rails connected follow the ROC

#### Additional

1. Verify fail-safe operation when connected to external interface signals. Applying an external input signal before processor supply ramps can cause voltage feed and can affect the custom board functions.
2. Verify recommendations as per the data sheet or EVM implementation have been considered for the attached device including terminations and external ESD protection.

## 7.4 On-board Synchronous Communication Interface (MCSPi, MCASP and I2C)

### 7.4.1 Multichannel Serial Peripheral Interface (MCSPi) and Multichannel Audio Serial Ports (MCASP)

Provide series resistors ( $22\Omega$ ) for SPI clock outputs SPI0..2\_CLK (MCSPi 0..2) and MCU\_SPI0..1\_CLK (MCU\_MCSPi 0..1) (close to processor).

Provide series resistors ( $22\Omega$ ) for transmit clock (Transmit Bit Clock) outputs MCASP0..2\_ACLKX and Transmit Frame Sync signals MCASP0..2\_AFSX (close to processor).

Provide series resistors ( $22\Omega$ ) for receiver clock (Receive Bit Clock) outputs MCASP0..2\_ACLKR and Receive Frame Sync signals MCASP0..2\_AFSR (close to attached device).

Processor IO buffers are off during reset. Verify external parallel pulls are provided for SPI Chip Select signals SPI0..2\_CS0..3 (MCSPi 0..2) and MCU\_SPI0..1\_CS0..3 (MCU MCSPi 0..1) (close to attached device). Add pulls to the processor and the attached device inputs that can float.

#### 7.4.1.1 MCSPi Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin attributes and signal description
3. Electrical characteristics, timing parameters and any additional available information
4. Interface configuration and recommended connections (including IOSET)
5. Series resistor ( $22\Omega$ ) added to the clock outputs near to the processor clock output pin
6. Parallel pull (pulldown for attached device clock input) added for any of the processor or attached IOs that can float
7. Performance and signal integrity related concerns have been analyzed (simulated) when connecting to multiple attached devices
8. Provision for series resistors added for all the interface signals to minimize reflections or isolate for testing



## 9. Configuration of SPI data D0 and SPI data D1 bits (data direction)

### Schematic Review

Follow the below list for the custom schematic design:

1. Pullup values used (10k $\Omega$  or similar)
2. Series resistor value used (22 $\Omega$ ) and the placement (near to processor pin)
3. Pullup referenced to the processor VDDSHVx for corresponding MCSPI instance and pins
4. Processor VDDSHVx and the attached device IO supply are sourced from the same supply
5. Supply rails connected follow the ROC

### Additional

1. Verify fail-safe operation when connected external interface connector (carrier or add-on board). Applying an external input before supply ramps can cause voltage feed and can affect the custom board functions
2. Verify recommendations as per the data sheet or EVM implementation have been considered for the attached device including terminations

#### 7.4.1.2 MCASP Checklist

### General

Review and verify the following for the custom schematic design:

1. Above section, including relevant application notes and FAQ links
2. Pin attributes and signal description
3. Electrical characteristics, timing parameters and any additional available information
4. MCASP interface configuration and recommended connections (including IOSET)
5. Series resistor 22 $\Omega$  added to the clock outputs (transmit bit clock, frame sync) near to the processor clock output pin
6. Parallel pull (pulldown for clock output) added for any of the processor or attached IOs that can float
7. Performance and signal integrity related concerns have been analyzed (simulated) when connecting to multiple attached devices
8. Provision for series resistors added for all the interface signals to minimize reflections or isolate for testing

### Schematic Review

Follow the below list for the custom schematic design:

1. Pullup values used (10k $\Omega$  or similar) and compare with the SK schematics
2. Series resistor value used (22 $\Omega$ ) and the placement (near to processor pin)
3. Pullup referenced to the processor VDDSHVx for corresponding MCASP instance and pins
4. Processor VDDSHVx and the attached device IO supply sourced from the same supply
5. Supply rails connected follow the ROC

### Additional

1. Verify fail-safe operation when connected to external signals. Applying an external input before supply ramps can cause voltage feed and can affect the custom board functions
2. Verify recommendations as per the data sheet or EVM implementation have been considered for the attached device including terminations and external ESD protection
3. Two devices can be connected to MCASP. The recommendation is to follow good or recommended layout practices when routing the bit clock (transmit bit clock and receive bit clock). Perform simulations using IBIS model

#### 7.4.2 Inter-Integrated Circuit (I2C)

Verify if the application requires an I2C interface that is fully compliant to I2C-bus specification. The MCU\_I2C0 and WKUP\_I2C0 are fail-safe, true open-drain output type buffers, and are fully compliant to the I2C specifications. I2C can support 3.4Mbps I2C operations (when the IO buffers (interface) are operating at 1.8V).

**Note**

For I2C interfaces with open-drain output type buffer (MCU\_I2C0 and WKUP\_I2C0), an external pull is recommended, irrespective of peripheral usage and the IO configuration.

Refer to the *Pin Connectivity Requirements* section of the processor-specific data sheet. A pullup (4.7kΩ, adjust after testing) is recommended.

When the open-drain output type buffer I2C interfaces are pulled to 3.3V supply, the IOs have slew rate requirements specified. An RC can be used to limit the slew rate. For RC implementation, refer [Starter Kit SK-AM62P-LP](#) for implementation.

For more information, see the [Connecting Supply Rails to Pullups](#) section.

In the case that additional I2C interfaces are required, use I2C0-3 interfaces.

I2C0-3 interface uses LVCMOS output type buffer IOs to emulate an open-drain output type buffer and are not fully compliant with the I2C specification, in particular falling edges are fast (< 2ns). Any devices connected to I2C0-3 ports need to function properly with the faster fall time. I2C0-3 ports support 100kHz and 400kHz operation. Pullups are recommended for I2C signals when the IOs are configured for I2C interface. Connect the pullups with the shortest possible stub.

For I2C0-3 interface, use series resistors to control the falling edge rate. The value depends on the custom board design and is recommended to be finalized during testing.

For more information, see the following FAQs:

[\[FAQ\] AM62P / AM62P-Q1 Custom board hardware design – I2C interface](#)

[\[FAQ\] AM62A7-Q1: Internal pull configuration registers for MCU\\_I2C0 and WKUP\\_I2C0](#)

If the plan is to use TI provided software, connect the recommended processor I2C interface to the PMIC, as I2C0 is the I2C interface used for PMIC control.

**Note**

When an I2C2 and I2C3 interfaces are used, refer to the I2C2 and I2C3 note (can be multiplexed to more than one pin) in the *Timing and Switching Characteristics, Peripherals, I2C* section of the processor-specific data sheet.

**Note**

Refer to the *Exceptions* in the *Timing and Switching Characteristics, I2C* section of the processor-specific data sheet during the custom board design. Take note of the exceptions for the simulated I2C interface in the data sheet. Add a low pass filter to reduce the fall time or interface speed to match the timing.

**7.4.2.1 I2C (Open-drain Output Type Buffer) Interface Checklist****General**

Review and verify the following for the custom schematic design:

1. Above section, including relevant application notes and FAQ links
2. Pin connectivity requirements (during reset, RX buffers are enabled. A pullup (4.7kΩ, adjust after testing) is recommended irrespective of IO configuration), pin attributes and signal description
3. Electrical characteristics (fail-safe and slew rate requirements when pulled to 3.3V), timing parameters and any additional available information including exceptions
4. RC at the input of the open-drain IOs for slew rate control when pulled to 3.3V
5. Attached device address pin connected to IO supply through a resistor (> 1kΩ)
6. Verify the target I2C interface clock rates. The I2C bus can only be operated as fast as the slowest peripheral on the bus. If faster operation is required, move the slow devices to another I2C port

7. Verify that there are no I2C address conflicts on any of the I2C interface utilized. There are multiple I2C ports available on the processor, so if a conflict is seen, move the conflicting devices to a different I2C bus. If this is not possible, use an I2C bus switch
8. Do not place more than one set of pullup resistors on the I2C lines. This can result in excessive loading and potential incorrect operation. Choose the pullup value commensurate with the bus speed being utilized.
9. Make sure that the supply rail powering the processor I2C IO supply for IO group matches the supply voltage used for the pullup resistors and the attached I2C devices. Proper pullup can prevent device damage or incorrect operation due to voltage mismatch

### Schematic Review

Follow the below list for the custom schematic design:

1. WKUP\_I2C0 and MCU\_I2C0 controllers have dedicated I2C compliant open-drain output type buffers
2. Verify the pullup values used. Compare with the SK schematics or calculate based on the load
3. The I2C pullup supply amplitude connected follows the steady-state maximum voltage at all fail-safe IO pins requirements. The supply threshold depends on the supply voltage connected to IO supply for IO group
4. Provision for RC to limit slew rate and RC values
5. Processor VDDSHVx and the attached device IO sourced from the same supply
6. Supply rails connected follow the ROC

### Additional

1. Verify recommendations as per the data sheet or EVM implementation have been considered for the attached device
2. Review the *Timing and switching characteristics, I2C Exceptions* section of the data sheet during the design stage

#### 7.4.2.2 I2C (Emulated Open-drain Output Type Buffer) Interface Checklist

### General

Review and verify the following for the custom schematic design:

1. Above section, including relevant application notes and FAQ links
2. Pin attributes and signal description
3. I2C interface configuration and recommended connections (including IOSET)
4. Electrical characteristics, timing parameters and any additional available information including exceptions
5. Attached device address pin connected to IO supply through a resistor (> 1k $\Omega$ )
6. A pullup is recommended when IO is configured as I2C interface
7. Note the I2C exceptions in the timing and switching characteristics section of the processor-specific data sheet

### Schematic Review

Follow the below list for the custom schematic design:

1. Verify the pullup resistor values used
2. Pullup referenced to the processor VDDSHVx (I2C pullup connected to correct voltage)
3. Addition of series resistor (low pass filter) for fall time control
4. Fail-safe interface (emulated IOs are not fail-safe, no input can be applied before the processor supply ramps)
5. Processor VDDSHVx and the attached device IO sourced from the same supply
6. Supply rails connected follow the ROC

### Additional

1. Verify fail-safe operation when connected to external interface signals. Applying an external input before supply ramps can cause voltage feed and can affect the custom board functions
2. Review the *Timing and switching characteristics, I2C Exceptions* section of the data sheet during the design stage

- I2C controllers are multiplexed with standard LVCMOS IO, connected to emulate open-drain

## 7.5 User Interface (CSIRX0, DPI, OLDI0, DSI), GPIO and Hardware Diagnostics

### 7.5.1 Camera Serial Interface (CSI-Rx (CSI-2 port, CSIRX0 Instance))

Refer to the processor-specific data sheet for supported data rate.

#### 7.5.1.1 CSIRX0 Used

The processor CSIRX0 interface is powered by CSIRX0 and DSITX0 core supplies VDDA\_CORE\_CSI\_DSI and VDDA\_CORE\_DSI\_CLK, and CSIRX0 and DSITX0 1.8V analog supply VDDA\_1P8\_CSI\_DSI.

Connect a resistor between CSI0\_RXRCALIB (close to processor) and VSS. Refer to the processor-specific data sheet for recommended resistor value and tolerance.

For more information on CSIRX0, see the [\[FAQ\] AM625 / AM623 / AM625SIP / AM625-Q1 / AM62A / AM62P Custom board hardware design – CSI-2 capabilities](#).

#### 7.5.1.2 CSIRX0 Not Used

CSIRX0 when not used has specific connection requirements for interface signals and power supplies.

For connecting the interface signals, power supplies (core and analog), see the *Pin Connectivity Requirements* section of the processor-specific data sheet.

When boundary scan function is used, CSIRX0 and DSITX0 supplies (VDDA\_CORE\_CSI\_DSI, VDDA\_CORE\_DSI\_CLK and VDDA\_1P8\_CSI\_DSI) are required to be connected to the recommended supply rails. Decoupling capacitors on the supply pins are recommended. Bulk capacitors and ferrites are optional.

When boundary scan function is not required and DSITX0 interface is not used, connect CSIRX0 and DSITX0 supplies (VDDA\_CORE\_CSI\_DSI, VDDA\_CORE\_DSI\_CLK and VDDA\_1P8\_CSI\_DSI) to VSS through separate 0Ω resistors. Decoupling capacitors, bulk capacitors and ferrites are not recommended to be populated.

#### 7.5.1.3 CSIRX0 Checklist

##### General

Review and verify the following for the custom schematic design:

- Above sections, including relevant application notes and FAQ links
- Pin connectivity requirements, pin attributes and signal description
- Electrical characteristics, timing parameters and any additional available information
- Connection of recommended IO calibration resistor
- Connection of the CSIRX0 interface signals with attached devices including the polarity
- Marking of differential signals and the differential impedance value

##### Schematic Review

Follow the below list for the custom schematic design:

- Connection of the CSIRX0 interface signals to the attached device
- Ferrite and capacitors used for CSIRX0 analog and core supply, when CSIRX0 interface is used
- Connection of CSIRX0 analog and core supply with optional ferrite and bulk capacitors and IO calibration resistor, when CSIRX0 interface not used. But, boundary scan functionality is required
- Pin connectivity requirement when boundary scan is not used
- Supply rails connected follow the ROC

##### Additional

- Need for external ESD protection based on the use case
- Verify fail-safe operation when connected to external signals. Applying an external input before supply ramps can cause voltage feed and affect the processor performance

### 7.5.2 Display Subsystem

### 7.5.2.1 Display Parallel Interface (DPI)

#### 7.5.2.1.1 AM62P, AM62P-Q1

Refer below FAQ:

[\[FAQ\] AM625 / AM623 / AM625SIP / AM625-Q1 Custom board hardware design – Display Parallel Interface \(DPI\) 24-bit RGB](#). The FAQ is generic and can also be used for AM62P, AM62P-Q1 processor family.

##### 7.5.2.1.1.1 IO Power Supply

The processor DPI interface is powered by VDDSHV3 supply rail (IO supply for IO group 3).

##### 7.5.2.1.1.2 DPI (Attached Device) Reset

The recommendation is to implement the attached device reset using a 2-input ANDing logic. Processor general purpose input/output (GPIO) is connected as one of the input to the AND gate with provision for pullup (to support boot) near to the input and 0Ω to isolate the GPIO for testing or debug. The other AND gate input is the main domain warm reset status output (RESETSTATz) signal.

In case an ANDing logic is not used and processor main domain warm reset status output (RESETSTATz) is used to reset the attached device, match the IO voltage level of the attached device and RESETSTATz. A level translator is recommended to match the IO voltage level.

##### 7.5.2.1.1.3 Connection

Verify display (RGB) connections.

Interface support includes 12-, 16-, 18-, and 24-bit RGB active matrix displays. When connecting only 16-bit data to an 18-bit panel (BGR565 to BGR666), connect D0-D4 to B1-B5 on LCD, D5-D10 to G0-G5 on the LCD, and D11-D15 to R1-R5 on LCD. On the 18-bit panel, connect B0 to B5 and R0 to R5.

##### 7.5.2.1.1.4 Signals Connection

Provide provision for connecting a series resistor (0Ω) for VOUT0\_PCLK (Pixel Clock Output) (close to processor). If space is not a constraint, recommend adding series resistors (0Ω) for all other control and data pins.

##### 7.5.2.1.1.5 Capacitors for the Power Supply Rails

Verify the required bulk and decoupling capacitors are provided for VDDSHV3 supply rail and the attached device.

Follow the processor-specific SK implementation whenever recommendations are not available.

##### 7.5.2.1.1.6 DPI (VOUT0) Checklist

### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin connectivity requirements, pin attributes and signal description
3. Electrical characteristics, timing parameters and any additional available information
4. Addition of series resistor 0Ω for the clock output near to the processor
5. Optional series resistors for the control and data interface signals

### Schematic Review

Follow the below list for the custom schematic design:

1. Connection of the interface signals including DPI pin mapping of the processor with the attached device RGB and control signals
2. Supply rails connected follow the ROC
3. Compare the decoupling capacitor of DPI IO supply used versus relevant SK

## Additional

1. Need for external ESD protection based on the use case

### 7.5.2.2 Open LVDS Display Interface (OLDI)

Refer to the processor-specific data sheet for supported display resolution.

#### 7.5.2.2.1 AM62P, AM62P-Q1

##### 7.5.2.2.1.1 OLDI0 Used

Refer below FAQ:

[\[FAQ\] AM625 / AM623 / AM625SIP / AM625-Q1 / AM62P Custom board hardware design – OLDI \(Open LVDS Display Interface\) capabilities.](#)

##### 7.5.2.2.1.1.1 IO Power Supply

The processor OLDI0 interface is powered by VDDA\_1P8\_OLDI0 (OLDI0 1.8V analog supply rail).

##### 7.5.2.2.1.1.2 OLDI0 (Attached Device) Reset

The recommendation is to implement the attached device reset using a 2-input ANDing logic. Processor general purpose input/output (GPIO) is connected as one of the input to the AND gate with provision for pullup (to support boot) near to the input and 0Ω to isolate the GPIO for testing or debug. The other AND gate input is the main domain warm reset status output (RESETSTATz) signal.

In case an ANDing logic is not used and processor main domain warm reset status output (RESETSTATz) is used to reset the attached device, match the IO voltage level of the attached device and RESETSTATz. A level translator is recommended to match the IO voltage level.

##### 7.5.2.2.1.1.3 OLDI0 Interface Compatibility

For verifying the voltage level compatibility, see the *OLDI LVDS (OLDI) Electrical Characteristics* section of the processor-specific data sheet.

##### 7.5.2.2.1.1.4 Capacitors for the Power Supply Rails

Verify the required bulk and decoupling capacitors are provided for VDDA\_1P8\_OLDI0 supply rail.

Follow the processor-specific SK implementation whenever recommendations are not available.

##### 7.5.2.2.1.1.5 OLDI0 Checklist

## General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin connectivity requirements, pin attributes and signal description
3. Electrical characteristics, timing parameters and any additional available information
4. Connection of the OLDI0 interface signals with attached devices including the polarity of the signals
5. Marking of differential signals and the differential impedance value
6. Configuration of the required terminations
7. When not used, connection of the recommended power supply and signals as per the pin connectivity requirements

## Schematic Review

Follow the below list for the custom schematic design:

1. Connection of 1 x 8 lane (dual link mode) and 2 x 4 lane (single link, mirror mode) OLDI0 signals
2. Supply rails connected follow the ROC

## Additional

1. Need for external ESD protection based on the use case



#### 7.5.2.2.1.2 OLDIO Not Used

OLDIO when not used has specific connection requirements for interface signals. For connecting the interface signals, see the *Pin Connectivity Requirements* section of the processor-specific data sheet.

The OLDIO 1.8V analog supply rail (VDDA\_1P8\_OLDIO) is recommended to be powered by a valid 1.8V source. Ferrite and bulk capacitor are optional.

#### 7.5.2.2.1.3 Additional Information

The signals are recommended to be connected as a point-to-point interface from the processor to a connector (display), without stubs.

Any board-level implementation is required to comply with the physical layer definition of *IEEE1596.3* standard and *ANSI/TIA/EIA644-A standard (Electrical Characteristics of Low Voltage Differential Signaling (LVDS) interface Circuits)*.

#### 7.5.2.3 Display Serial Interface (DSI)

Refer processor-specific data sheet for supported display resolution.

##### 7.5.2.3.1 AM62P, AM62P-Q1

###### 7.5.2.3.1.1 DSITX0 Used

The processor DSITX0 interface is powered by CSIRX0 and DSITX0 core supplies VDDA\_CORE\_CSI\_DSI and VDDA\_CORE\_DSI\_CLK and CSIRX0 and DSITX0 1.8V analog supply VDDA\_1P8\_CSI\_DSI.

Connect a resistor between DSI0\_TXRCALIB (close to processor) and VSS. Refer processor-specific data sheet for recommended resistor value and tolerance.

###### 7.5.2.3.1.1.1 DSITX0 Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above section, including relevant application notes and FAQ links
2. Pin connectivity requirements, pin attributes and signal description
3. Electrical characteristics, timing parameters and any additional available information
4. Connection of recommended IO calibration resistor
5. Connection of the DSI0 interface signals with attached devices including the polarity
6. Marking of differential signals and the differential impedance value
7. Configuration of the required terminations
8. When not used, connection of the recommended power supplies and signals as per the pin connectivity requirements

#### Schematic Review

Follow the below list for the custom schematic design:

1. Compare the ferrite and capacitors used for DSI0 analog and core supply, when DSI0 interface is used
2. Verify the connection of DSI0 analog and core supply with optional ferrite and bulk capacitors and IO calibration resistor, when DSI0 interface not used. But, boundary scan functionality is required
3. Verify the pin connectivity requirement of no boundary scan use case
4. Compare the connection of power supplies and signals versus relevant SK
5. Supply rails connected follow the ROC

#### Additional

1. Need for external ESD protection based on the use case

##### 7.5.2.3.1.2 DSITX0 Not Used

DSITX0 when not used has specific connection requirements for interface signals and power supplies.

For connecting the interface signals, power supplies (core and analog), see the *Pin Connectivity Requirements* section of the processor-specific data sheet.

When boundary scan function is used, CSIRX0 and DSITX0 supplies (VDDA\_CORE\_CSI\_DSI, VDDA\_CORE\_DSI\_CLK and VDDA\_1P8\_CSI\_DSI) are required to be connected to the recommended supply rails. Decoupling capacitors on the supply pins are recommended. Bulk capacitors and ferrites are optional.

When boundary scan function is not required and CSIRX0 interface is not used, connect CSIRX0 and DSITX0 supplies (VDDA\_CORE\_CSI\_DSI, VDDA\_CORE\_DSI\_CLK and VDDA\_1P8\_CSI\_DSI) to VSS through separate 0Ω resistors. Decoupling capacitors, bulk capacitors and ferrites are not recommended to be populated.

### 7.5.3 General Purpose Input/Output (GPIO)

Refer below FAQ:

[\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM62D-Q1 / AM64x / AM243x Design Recommendations / Custom board hardware design - Data sheet Pin Attributes and Pin connectivity related queries](#)

#### 7.5.3.1 Availability of CLKOUT on Processor GPIO

MCU\_OSC0\_XO can be configured as WKUP\_CLKOUT0 output for AM62Px processor family.

#### 7.5.3.2 Connection and External Buffering

The recommendation is to add a series resistor (with a value that is use case dependent) to limit the current. Externally buffer the GPIO outputs when higher (above the data sheet specified value) current sourcing is required.

Common processor LVCMOS IO interface guidelines:

1. Most of the processor IOs are not fail-safe. No input can be applied before supply ramps.
2. Processor LVCMOS IOs have slew rate requirements specified, applying a slow ramp input or connecting a capacitor directly at the input is not recommended.
3. Connecting a capacitor load > 22pF at the output is not recommended. DNI capacitor or perform simulations based on the use case.
4. Processor IO buffers are off during reset. A pull is required near to the attached device being driven by the processor IO that can float.
5. A parallel pull is recommended for any processor IO pad that has a trace connected. When adding pull is not feasible, route the traces away from noisy signals.

Verify capacitor loading of the processor GPIO output (when capacitor value > 22pF is connected, perform simulations), slew rate of the input signal (LVCMOS input slew is 1000ns or less), IO compatibility, and fail-safe operation between the processor IOs and attached devices.

#### 7.5.3.3 Additional Information

Pins or Pads on unused interfaces can typically be left unconnected, unless otherwise stated. Many of the IOs have a *Pad Configuration Register* that provides control over the input capabilities of the IO (RXENABLE field in each conf\_<module>\_<pin> register). For more details, refer to the *Control Module* chapter of the processor-specific TRM. Software can disable the IO receive buffers (that is, RXENABLE=0) that are not connected in the design as soon as possible during initialization. Software must not accidentally enable the receiver of an IO (by setting the RXENABLE bit) when the associated pin is floating.

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#### Note

For specific guidance on configuring certain unused pins, refer to the *Pin Connectivity requirements* section of the processor-specific data sheet.

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#### Note

For specific guidance on configuring IOs, refer to the *Pad Configuration Registers* chapter of the processor-specific TRM.

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For more information on processor unused peripherals and I/Os, see the [\[FAQ\] AM625 / AM623 / AM62A / AM62P Design Recommendations / Commonly Observed Errors during Custom board hardware design – SOC Unused peripherals and I/Os](#).

For more information on used pins, unused pins, and peripherals handling, see the [\[FAQ\] AM62x, AM64x, AM243x, Custom board hardware design – How to handle Used / Unused Pins / Peripherals ? \(e.g. GPIOs, SERDES, USB, CSI, MMC \(eMMC, SD-card\), CSI, OLDI, DSI, CAP\\_VDDSn, .....\)](#). The FAQ is generic and can also be used for AM62P, AM62P-Q1 processor family.

#### 7.5.3.4 GPIO Checklist

##### General

Review and verify the following for the custom schematic design:

1. Above sections, including relevant application notes and FAQ links
2. Pin connectivity requirements and pin attributes.
3. Electrical characteristics and any additional available information.
4. Input signal applied to the processor LVCMOS inputs follow the slew rate requirements. Connecting a capacitor directly at the input increases the signal slew and is not recommended.
5. Connection of capacitor load directly to the processor output for control or enabling of attached device is not allowed (recommand simulation when capacitor load > 22pF (place holder) is used).
6. All IO pins referenced to VDDSHVx or VDDSHV\_MCU or VDDSHV\_CANUART connect to a single voltage level. Each IO has an associated supply voltage used to power the IO cell (VDDSHVx). If VDDSHVx is sourced from 3.3V (1.8V) supply, all IO referenced to VDDSHVx rail operate at 3.3V (1.8V) levels.
7. No input voltage applied to the processor I/Os before the VDDSHVx supply ramps (excluding fail-safe I/Os). Most processor I/Os are not fail-safe. Applying voltage to the I/Os is not recommended or allowed, while the corresponding IO supply for IO group (VDDSHVx) is off. Fail-safe I/Os include MCU\_PORz, WKUP\_I2C0\_SCL, WKUP\_I2C0\_SDA, MCU\_I2C0\_SCL, MCU\_I2C0\_SDA, EXTINTn, and USBn\_VBUS (n = 0-1), when a recommended VBUS divider is used.
8. One of the common use case for the IO interface is driving LEDs for indication. The designer can review the LED source or sink current and the effect on the voltage level and adjust the LED current accordingly.
9. Shorting of multiple I/Os together directly is not recommended.
10. Pad configuration based on the required IO direction.
11. Directly connecting processor I/Os with alternate functions to supply or VSS is not allowed or recommended, including boot mode inputs. The board designer can have errors with the firmware and miss-configure the LVCMOS GPIOs that are intended as inputs, to be outputs driving logic high instead.

##### Schematic Review

Follow the below list for the custom schematic design:

1. Pulls are added for any of the processor or attached device I/Os that can float.
2. Pullups are connected to the same IO supply for IO group VDDSHVx referenced by the I/Os.
3. The supply voltage for all pullups that are connected to processor I/Os matches the voltage applied to the corresponding IO supply for IO group (VDDSHVx). Pulling a signal to the wrong IO voltage causes voltage leakage between the IO rails of the device.
4. IO level compatibility for externally applied inputs from a add-on or carrier board or through an external connector.
5. Supply rails connected follow the ROC.

##### Additional

1. Common processor LVCMOS IO interface guidelines, refer to [Section 7.5.3.2](#).
  - Most of the processor I/Os are not fail-safe. This is not allowed or recommended to apply input before supply ramps.
  - Processor LVCMOS I/Os have slew rate requirements specified, applying a slow ramp input or connecting a capacitor directly at the input is not recommended.
  - Connecting a capacitor load > 22pF (place holder) at the output is not recommended. DNI capacitor or perform simulations based on the use case.

- Processor IO buffers are off during reset. A pull is required near to the attached device being driven by the processor IO that can float.
- 2. A parallel pull is recommended for any processor IO pad that has a trace connected. When adding pull is not feasible, route the traces away from noisy signals. Processor IO buffers are off during reset. A pullup is recommended near to the attached device, to hold the attached device IO inputs that can float in a known state. Use of pulls are attached-device dependent.
- 3. IO compatibility and fail-safe operation between the processor IOs and attached devices connected through IOs.
- 4. Fail-safe operation when connected to external signals. Applying an external input before supply ramps cold causes voltage feed and affects the processor performance.
- 5. Capacitor loading of the processor output (when capacitor value > 22pF (place holder) is connected, designer must simulate), slew of the input signal (LVCMOS input slew is 1000ns or less).
- 6. IO current sink or source follows the data sheet recommendations.
- 7. External ESD protection is provided when the IOs connect directly to external interface signals.

### 7.5.4 On-board Hardware Diagnostics

#### 7.5.4.1 Monitoring of On-board Supply Voltages Using Processor Voltage Monitors

Voltage monitor pins can be used to monitor the external supply rails. The VMON\_1P8\_SOC and VMON\_3P3\_SOC can be directly connected to 1.8V or 3.3V. The VMON\_VSYS is connected through an external voltage divider and provides flexibility to monitor any of the supply rail.

##### 7.5.4.1.1 Voltage Monitor Pins Used

The recommendation is to connect the main DC voltage rail powering the board (such as 5V or higher) to the VMON\_VSYS pin through an external resistor voltage divider ( $0.45V \pm 3\%$ ) for early supply failure indication. The recommendation is to implement a noise filter (capacitor) across the resistor voltage divider output since VMON\_VSYS has minimum hysteresis and a high-bandwidth response to transients as described in the *System Power Supply Monitor Design Guidelines* section of the processor-specific data sheet.

Connect VMON\_1P8\_SOC and VMON\_3P3\_SOC pins directly to the respective supplies. See the *Recommended Operating Conditions* section of the processor-specific data sheet for the allowed supply voltage range.

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#### Note

For VMON\_VSYS, the fail-safe condition is valid when the recommendations in section *System Power Supply Monitor Design Guidelines* of processor-specific data sheet are followed.

For VMON\_1P8\_SOC and VMON\_3P3\_SOC pins, the fail-safe condition is valid when the supply voltage connected is within the *Recommended Operating Conditions* section of processor-specific data sheet.

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For more information, see the [\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM64x / AM243x Design Recommendations / Custom board hardware design – POK VMON Voltage Monitor](#)

##### 7.5.4.1.1.1 Voltage Monitor Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above section, including relevant application notes and FAQ links
2. Pin attributes and signal description
3. The recommendation is to provide provision to connect an external resistor divider as per *System Power Supply Monitor Design Guidelines* section of the data sheet for early detect using VMON\_VSYS
4. For VMON\_VSYS detection to be effective, connect a DC voltage of 5V or higher
5. VMON\_VSYS - add a filter capacitor. Refer processor data sheet section *System Power Supply Monitor Design Guidelines*. The value of the capacitor is determined by the designer based on the trip time requirement

- Direct connection of 1.8V to VMON\_1P8\_SOC and 3.3V to VMON\_3P3\_SOC pins without any external filter capacitors

### Schematic Review

Follow the below list for the custom schematic design:

- 1% tolerance resistors are used for the VMON voltage divider resistors
- Addition of filter capacitor and selection of capacitor value (select based on the power architecture)

### Additional

- The recommendation is to always implement the voltage monitoring functionality using VMON\_VSYS for early detection of supply failure. VMON\_VSYS is meant to be a power-fail indicator for the main input (higher) voltage rail that enters the PCB. For example: 5V, 12V, or 24V. The error associated with the VMON\_VSYS monitor requires you to set the threshold significantly lower than the nominal to avoid false trigger. Refer *System Power Supply Monitor Design Guidelines* section of the data sheet

#### 7.5.4.1.2 Voltage Monitor Pins Not Used

The recommendation is to use VMON\_VSYS for early supply failure indication. When not used, connect VMON\_VSYS and VMON\_3P3\_SOC pins to VSS through separate 0Ω resistors and add a test point for future expansion.

The recommendation is to connect the VMON\_1P8\_SOC pin to respective supply. Grounding VMON\_1P8\_SOC pin shorts the internal 1.8V supply.

#### 7.5.4.2 Internal Temperature Monitoring

The temperature monitors are placed near the anticipated hot spots of the processor. Read the on-die temperature sensors in Linux and perform thermal management. See the [E2E thread](#).

The Voltage and Thermal Manager (VTM) module on the processor supports voltage and thermal management of the processor by providing control of on-chip temperature sensors.

The processor supports one VTM module, VTM0, which is located in the WKUP domain.

For more information, see [\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM64x / AM243x Design Recommendations / Custom board hardware design – VTM](#).

#### 7.5.4.2.1 Internal Temperature Monitoring Checklist

### General

Review and verify the following for the custom schematic design:

- Above section, including relevant application notes and FAQ links
- Pin attributes and signal description
- Connection of the recommended supply

### Schematic Review

Follow the below list for the custom schematic design:

- Addition of filter capacitors for the TEMPn (n = 0-2) supply pins

#### 7.5.4.3 Connection of Error Signal Output (MCU\_ERRORn)

The recommendation is to connect the MCU\_ERRORn signal as per the *Pin Connectivity Requirements* section of the processor-specific data sheet for testing or when using the signal for other board level functions.

#### 7.5.4.4 High Frequency Oscillator (MCU\_OSC0) Clock Loss Detection

The processor supports HFOSC0 clock loss detection circuitry to detect HFOSC0\_CLK malfunction (stops). Dedicated hardware logic monitors HFOSC0 clock using CLK\_12M\_RC clock. When HFOSC0\_CLK stops toggling for 9 CLK\_12M\_RC clock periods, a HFOSC0 clock stop loss condition is detected. If



CTRLMMR\_MCU\_PLL\_CLKSEL [8] CLKLOSS\_SWITCH\_EN is set, the reference clock is switched from HFOSC0\_CLKOUT to CLK\_12M\_RC to allow the processor to operate with a slower clock.

During clock-loss condition, the processor reports the error to the external device through MCU\_ERRORn pin by driving the pin low. The recovery mechanism is up to the external device (such as a PMIC to take action).

Example, doing a full board power cycle to see if the board recovers. If the board does not recover then the processor has to indicate board designer to take alternate actions or perform board level tests such as checking on-board system clocks, external crystal or supply rails.

## 7.6 Verifying Board Level Design Issues

### 7.6.1 Processor Pin Configuration Using PinMux Tool

Recommend verifying the processor peripheral and IO configuration using the TI [SysConfig-PinMux](#) tool to take care valid IOSETs have been configured.

For more information, see the PinmuxConfigSummary.csv file provided by the SysConfig-PinMux tool.

### 7.6.2 Schematics Configurations

Verify the circuit options provided for alternate functionality or testing that are optional for the normal functioning of the board or can affect or influence custom board performance are marked as DNI.

### 7.6.3 Connecting Supply Rails to Pullups

Connecting a signal pullup to the wrong IO supply rail can cause leakage between the IO rails of the processor and affect the custom board performance or processor reliability. Each signal has an associated IO supply for IO group (Ex: VDDSHVx [x = 0-6]). For more information, see the *Pin Attributes* table in the processor-specific data sheet.

For example, to pullup SPI0\_CLK signal in any MUX mode (EHRPWM1\_A, GPIO1\_17, and so forth), pullup the signal supply rail connected to VDDSHV0.

### 7.6.4 Peripheral (Subsystem) Clock Outputs

For any of the processor peripheral that has a clock output, configure the RXACTIVE bit of the appropriate CTRLMMR\_MCU\_PADCONFIGx, CTRLMMR\_PADCONFIGy registers. The bit configuration is required for the clock output to work properly.

### 7.6.5 General Board Bring-up and Debug

Board bring-up tips:

Before starting the board bring-up, verify the following:

- The processor and the attached devices used match the design requirements
- Boards have been checked for component assembly (DNI (Do Not Install)) and inspected for assembly (soldering of the components)
- No external inputs are connected to the processor IO inputs before the board supply is applied and processor supply ramps

Refer to [\[FAQ\] Board bring up tips for Sitara devices \(AM64x,AM243x, AM62x, AM62Ax, AM62Px\)](#).

#### 7.6.5.1 Clock Output for Board Bring-Up, Test, or Debug

The following clock outputs are available on the processor for test and debug purposes only:

- OBSCLK0, MCU\_OBSCLK0 (recommended): Observation clock outputs

OBSCLK0, MCU\_OBSCLK0 are observation clock outputs for test and debug purposes only. OBSCLK pins can be used to select one of the several different clocks as output. We do not expect OBSCLK signal to be used as a clock source for any external device. As stated in the data sheet, OBSCLK0 signal is provided for test and debug purposes only.

- SYSCLKOUT0 (optional): SYSCLK0 is divided by 4 and then sent out of the processor as a LVCMOS clock signal (SYSCLKOUT0)



- MCU\_SYCLKOUT0 (optional): MCU\_SYCLK0 is divided by 4 and then sent out of the processor as a LVCMOS clock signal (MCU\_SYCLKOUT0)

In case the processor pins designated OBSCLK0..1, MCU\_OBSCLK0, SYCLKOUT0, MCU\_SYCLKOUT0 are not used, provide a test point for test or debug. Recommend adding pull resistors to the pads.

In case clock output pins are used, a test point can be inserted on the trace and provision to isolated the signals from the attached devices can be provided for test or debug.

System clock output pins (MCU\_SYCLKOUT0 and SYCLKOUT0) are hardwired to dedicated clock resources.

#### 7.6.5.2 Additional Information

The recommendation is to provide test points for MCU\_RESETSTATz, RESETSTATz and PORz\_OUT for testing or debug when not used.

For other on-board devices (DC/DC Converter or LDO or Sensor) that have an alert output, over-current indication output or PG (power good) output that is not used, provide a pullup and test point for testing or future enhancements.

#### 7.6.5.3 General Board Bring-up and Debug Checklist

##### General

Review and verify the following for the custom schematic design:

1. Add provision to isolate the IOs that can be used for debug from alternate function
2. Add provision for connecting UART interfaces for debug during initial board build
3. Add provision for JTAG connector or Test points for JTAG interface connection including external ESD protection. Place the pulls as per pin connectivity requirements near to the processor JTAG interface pins

##### Schematic Review

Follow the below list for the custom schematic design:

1. The required pullup and series resistors are provided for the UART interfaces used for debug when external interface signals are directly connected to the processor UART signals
2. External ESD protection when external interface signals are directly connected to the processor UART signals

##### Additional

1. Processor UART and most of the IO signals are not fail-safe. Recommendation is to apply external inputs only after the processor supplies ramp
2. The recommendation is to disconnect the external interface signals when processor board is powered off

Refer to [\[FAQ\] SK-AM62: Purpose Of Different UARTs](#).

## 8 Self-Review of the Custom Board Schematics Design

Once the schematics design is completed following the design guidelines provided in the application note and referring to the SK schematics and other available collaterals, customer can do a self review using the check list provided at the end of each design guidelines section.

Example:

*Processor Core and Peripheral Core Power Supply Checklist*

*General Board Bring-up and Debug Checklist*

The below FAQ lists the collaterals and steps that can be followed for performing self-review of custom board schematics:

[\[FAQ\] AM62P / AM62P-Q1 Design Recommendations / Custom board hardware design - Custom board schematics self-review](#)

The below FAQ lists common errors observed while reviewing customer schematics. The recommendation is to read the list and make the required updates:

[\[FAQ\] AM625 / AM623 / AM62A / AM62P / AM62D-Q1 / AM64x / AM243x Design Recommendations / Custom board hardware design - List of errors observed during customer schematics review](#)

## 9 Layout Notes (Added on the Schematic)

Recommend adding required design notes for the processor peripherals (Example: USB2.0 interface, Ethernet interface, Camera interface, Display (OLDI0, DSITX0) interface, eMMC, OSPI, SD, and other available processor peripherals). Notes added can include Board Boot mode configurations, placement of series and parallel resistors, placement of decoupling and bulk capacitors.

Consider adding the required or applicable design notes to the processor attached devices and on-board devices.

Mark all differential signals, critical signals and specify the target impedance (as required). See the following examples:

- Refer to the *AM62Ax / AM62Px DDR Board Design and Layout Guidelines* for the recommended target impedance for the LPDDR4 clock, address and control signals.
- The differential impedance for the USB2.0 data lines must be within the specified tolerance for a nominal value of 90Ω.
- The differential impedance for the CSIRX0, DSITX0 and OLDI0 signals must be within the specified tolerance for a nominal value of 100Ω.

See the following FAQs:

[\[FAQ\] AM625: PCB Pattern Recommendations for Specific Peripherals](#)

[\[FAQ\] AM625: MMC0 PCB Connectivity Requirements](#)

[AM6442: PCB layout guidelines for MMCSD0\(eMMC\) and MMCSD1\(SD card\)](#)

### 9.1 Layout Checklist

#### General

Review and verify the following for the custom schematic design:

1. Above section, including relevant application notes and FAQ links
2. Is the custom board designed to be compliant to the PCB trace delay requirements defined in the *Timing Conditions* table found in the *Timing and Switching Characteristics* section of the processor data sheet
3. *Applications, Implementation, and Layout* section of the data sheet and followed the relevant sections

## 10 Custom Board Design Simulation

The baseline drive impedance and ODT settings for memory (LPDDR4) derived from the signal integrity (SI) simulations performed on the SK.

The recommendation is to perform simulation for the custom design as the configuration values can differ.

Refer to the FAQs below:

[\[FAQ\] AM625, AM623, AM625SIP, AM625-Q1, AM620-Q1, AM62A7, AM62A3, AM62P, AM62P-Q1, AM6442, AM2432 Custom board hardware design – S-parameter and IBIS model of IO-buffer](#)

[\[FAQ\] Using DDR IBIS Models for AM64x, AM62x, AM62Ax, AM62Px](#)

To get an overview of the board extraction, simulation, and analysis methodologies for high speed LPDDR4 interfaces, see the *LPDDR4 Board Design Simulations* chapter of the [AM62Ax, AM62Px, AM62Dx LPDDR4 Board Design and Layout Guidelines](#) application note.

The drive strength is adjustable using the [DDR Register Configuration Tool](#) on SysConfig.

For more information, see the [\[FAQ\] AM62A7 or AM62A3 Custom board hardware design – Processor DDR Subsystem and Device Register configuration](#). The FAQ is generic and can also be used for AM62P, AM62P-Q1 processor family.

Refer [\[FAQ\] AM62A3-Q1: AM62A3-Q1 PDN Power SI SIMULATION Questions](#). The FAQ is generic and can also be used for AM62P, AM62P-Q1 processor family.

## 11 Additional References

Additional references include FAQs and *Hardware Design Considerations for Custom Board Design* document for specific processor. Schematics for attached devices including PMIC and EPHY.

### 11.1 FAQ Covering AM6xx Processor Family

The following FAQ summarizes key collaterals that can be referenced during custom board design:

[\[FAQ\] AM64x, AM243x, AM62x, AM62Ax, AM62Dx, AM62Px Custom board hardware design - Collaterals for Reference during Schematic design and Schematics Review](#)

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#### Note

While using the SK PDF schematics for custom board schematics review and follow the FAQ links for additional information.

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## 11.2 FAQs - Processor Product Family Wise and Sitara Processor Families

Based on interactions with board designers, queries from multiple board designers and learning from board designer queries, FAQs have been created to answer some of the commonly asked design question or provide design guidelines to support board designers during custom board design. Refer to the following list of FAQs that can be used during custom board design along with other available design collaterals including the *Hardware Design Considerations for Custom Board Design* and the *Schematic Design Guidelines and Schematic Review Checklist*:

### AM62Px Processor Family:

[\[FAQ\] AM62P, AM62P-Q1 Custom board hardware design - FAQs related to Processor collaterals, functioning, peripherals, interface and Starter kit](#)

### AM62Ax Processor Family:

[\[FAQ\] AM62A7, AM62A7-Q1, AM62A3, AM62A3-Q1 Custom board hardware design - FAQs related to Processor collaterals, functioning, peripherals, interface and Starter kit](#)

Above FAQ includes the FAQs relevant to AM62D-Q1 processor family.

### AM62x Processor Family:

[\[FAQ\] AM625, AM623, AM625SIP, AM625-Q1, AM620-Q1 Custom board hardware design - FAQs related to Processor collaterals, functioning, peripherals, interface and Starter kit](#)

### Sitara Processor Families:

[\[FAQ\] Custom board hardware design - Master \(Complete\) list of FAQs for all Sitara processor \(AM62x, AM64x, AM243x, AM335x\) families](#)

See the following FAQ link that lists all the available FAQs including software related FAQs:

[\[FAQ\] AM6x: Latest FAQs on AM62x, AM64x, AM24x, AM3x, AM4x Sitara devices](#)

## 11.3 Processor Attached Devices

[Ethernet PHY PCB Design Layout Checklist](#)

[TPS65219 Schematic, Layout Checklist](#)

[TPS65931211-Q1 PMIC User Guide for AM62A](#)

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### Note

Verify availability of device-specific schematic review checklist on [TI.com](#) for the attached devices and verify the custom board schematic implementation using the available checklist.

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## 12 Summary

This application note is provided as a design guide for use by board designers during the custom board schematic design and review. The recommendations provided in the document can help designers simplify the board design, reduce schematic errors, reduce board bring-up time, board debug time and can possibly minimize future board re-spins.

## 13 References

### 13.1 AM62P , AM62P-Q1

- Texas Instruments, [AM62Px Sitara Processors](#), data Sheet
- Texas Instruments, [AM62Px Sitara Processors](#), Technical Reference Manual
- Texas Instruments, [AM62Px Silicon Errata](#)
- Texas Instruments, [Starter Kit SK-AM62P-LP](#), product page
- Texas Instruments, [Hardware Design Considerations for Custom Board Design Using AM62P, AM62P-Q1 Family of Processors](#), user's guide

- Texas Instruments, [AM62P Power Estimation Tool](#), application note
- Texas Instruments, [PMIC for Powering AM62Px Devices](#), application note
- Texas Instruments, [AM62Px Escape Routing for PCB Design](#), application note
- Texas Instruments, [AM62Ax, AM62Px, AM62Dx LPDDR4 Board Design and Layout Guidelines](#), application note
- Texas Instruments, [SK-AM62P-LP Design Package Folder and Files List](#), product overview

### 13.2 AM62A7 , AM62A3 , AM62A7-Q1 , AM62A3-Q1

- Texas Instruments, [AM62Ax Sitara Processors](#), Data Sheet
- Texas Instruments, [AM62Ax Sitara Processors](#), Technical Reference Manual
- Texas Instruments, [AM62Ax Silicon Errata](#)
- Texas Instruments, [Starter Kit SK-AM62A-LP](#), product page
- Texas Instruments, [Hardware Design Considerations for Custom Board Design Using AM62A3, AM62A7, AM62A3-Q1, AM62A7-Q1 and AM62D-Q1 Processor Families](#), user's guide
- Texas Instruments, [AM62A3, AM62A7, AM62A3-Q1, AM62A7-Q1 and AM62D-Q1 Processor Families Schematic Design Guidelines and Schematic Review Checklist](#)
- Texas Instruments, [AM62Ax Maximum Current Ratings](#), application note
- Texas Instruments, [AM62Ax Power Estimation Tool](#), application note
- Texas Instruments, [PMIC Solution for AM62Ax](#), product overview
- Texas Instruments, [AM62Ax/AM62Dx Escape Routing for PCB Design](#), user's guide
- Texas Instruments, [AM62Ax, AM62Px, AM62Dx LPDDR4 Board Design and Layout Guidelines](#), application note
- Texas Instruments, [SK-AM62A-LP Design Package Folder and Files List](#), product overview

### 13.3 AM62D-Q1

- Texas Instruments, [AM62Dx Sitara Processors](#) data sheet
- Texas Instruments, [AM62Dx Sitara Processors](#) technical reference manual
- Texas Instruments, [AM62Dx Sitara Processors Silicon Errata, Silicon Revision 1.0](#)
- Texas Instruments, [AUDIO-AM62D-EVM](#) web page
- Texas Instruments, [Hardware Design Considerations for Custom Board Design Using AM62A3, AM62A7, AM62A3-Q1, AM62A7-Q1 and AM62D-Q1 Processor Families](#) user's guide
- Texas Instruments, [AM62A3, AM62A7, AM62A3-Q1, AM62A7-Q1 and AM62D-Q1 Processor Families Schematic Design Guidelines and Schematic Review Checklist](#)
- Texas Instruments, [AM62Ax/AM62Dx Escape Routing for PCB Design](#) user's guide
- Texas Instruments, [AM62Ax, AM62Px, AM62Dx LPDDR4 Board Design and Layout Guidelines](#) application note

### 13.4 AM625, AM623, AM625SIP, AM625-Q1, AM620-Q1

- Texas Instruments, [AM62x Sitara Processors](#), data sheet
- Texas Instruments, [AM625SIP – AM6254 Sitara Processor with Integrated LPDDR4 SDRAM](#), data sheet
- Texas Instruments, [AM62x Sitara Processors Technical Reference Manual](#)
- Texas Instruments, [AM62x Silicon Errata](#)
- Texas Instruments, [Hardware Design Considerations for Custom Board Design Using AM623, AM625, AM625SIP, AM620-Q1, AM625-Q1 Family of Processors](#), user's guide
- Texas Instruments, [AM623, AM625, AM625SIP, AM620-Q1, AM625-Q1 Processor Family Schematic Design Guidelines and Schematic Review Checklist](#), application note
- Texas Instruments, [Starter Kit SK-AM62B-P1](#), tool page
- Texas Instruments, [Starter Kit SK-AM62B for discrete power solution](#), tool page
- Texas Instruments, [Starter Kit SK-AM62-LP](#), tool page
- Texas Instruments, [Starter Kit SK-AM62-SIP](#), tool page
- Texas Instruments, [AM62x Power Consumption](#), application note
- Texas Instruments, [AM62x Maximum Current Ratings](#), application note
- Texas Instruments, [AM62x Power Estimation Tool](#), application note
- Texas Instruments, [Powering the AM62x With the TPS65219 PMIC](#)
- Texas Instruments, [Powering the AM625SIP With the TPS65219 PMIC](#), application note
- Texas Instruments, [Discrete Power Solution for AM62x](#), application note

- Texas Instruments, [AM625, AM623 \(ALW\) Escape Routing PCB Design](#), application note
- Texas Instruments, [AM625-Q1, AM620-Q1 \(AMC\) Escape Routing for PCB Design](#), application note
- Texas Instruments, [AM625SIP \(AMK\) Escape Routing for PCB Design](#), application note
- Texas Instruments, [AM625, AM623, AM625-Q1, AM620-Q1 DDR Board Design and Layout Guidelines](#), application note
- Texas Instruments, [PRU-ICSS Feature Comparison](#), application note
- Texas Instruments, [How the AM625SIP Processor Accelerates Development by Integrating LPDDR4](#), application brief
- Texas Instruments, [AM625SIP: System In Package Explained](#), product overview
- Texas Instruments, [SK-AM62B-P1 Design Package Content Overview](#), product overview
- Texas Instruments, [SK-AM62-LP Design Package Content Overview](#), product overview
- Texas Instruments, [SK-AM62-SIP Design Package Folder and Files List](#), product overview
- Texas Instruments, [SK-AM62B Design Package Folder and Files List](#), product overview

### 13.5 Common for all Processor Families

- Texas Instruments, [AM623, AM625, AM625SIP, AM620-Q1, AM625-Q1, AM62A3, AM62A7, AM62A7-Q1, AM62D-Q1, AM62P-Q1 Schematic Design Guidelines and Review Checklist](#) application note
- Texas Instruments, [Sitara Processor Power Distribution Networks: Implementation and Analysis](#) application note
- Texas Instruments, [High-Speed Interface Layout Guidelines](#) application note
- Texas Instruments, [High-Speed Layout Guidelines](#) application note
- Texas Instruments, [Jacinto7 AM6x, TDA4x, and DRA8x High-Speed Interface Design Guidelines](#) application note
- Texas Instruments, [Thermal Design Guide for DSP and Arm Application Processors](#) application note
- Texas Instruments, [Emulation and Trace Headers Technical Reference Manual](#) user's guide
- Texas Instruments, [XDS Target Connection Guide](#) application note
- Texas Instruments, [Interface Circuits for TIA/EIA-644 \(LVDS\)](#) design consideration
- Texas Instruments, [General Hardware Design/BGA PCB Design/BGA Decoupling](#) application note
- Texas Instruments, [MSL Ratings and Reflow Profiles](#) application note
- Texas Instruments, [Moisture sensitivity level search](#) packaging search
- Texas Instruments, [Clocking Design Guide for KeyStone Devices](#) application note
- Texas Instruments, [Hardware Design Guide for KeyStone II Devices](#) application note
- Texas Instruments, [TIDA-01413 - ADAS 8-Channel Sensor Fusion Hub Reference Design](#) design guide
- Texas Instruments, [Jacinto 7 DDRSS Register Configuration Tool](#) application note
- Texas Instruments, [Using IBIS Models for Timing Analysis](#) application note
- Texas Instruments: [Display Interfaces: A Comprehensive Guide to Sitara MPU Visualization Designs](#) application note

### 13.6 Master List of Available FAQs - Processor Family Wise

A complete list of the FAQs are available that can be used to quickly view the available list of FAQs for the selected processor or processor families.

[\[FAQ\] AM62P, AM62P-Q1 Custom board hardware design - FAQs related to Processor collaterals, functioning, peripherals, interface and Starter kit](#)

[\[FAQ\] AM62A7, AM62A7-Q1, AM62A3, AM62A3-Q1 Custom board hardware design - FAQs related to Processor collaterals, functioning, peripherals, interface and Starter kit](#)

Above FAQ includes the FAQs relevant to AM62D-Q1 processor family.

[\[FAQ\] AM625, AM623, AM625SIP, AM625-Q1, AM620-Q1 Custom board hardware design - FAQs related to Processor collaterals, functioning, peripherals, interface and Starter kit](#)

### 13.7 Master List of Available FAQs - Sitara Processor Families

[\[FAQ\] Custom board hardware design - Master \(Complete\) list of FAQs for all Sitara processor \(AM62x, AM64x, AM243x, AM335x\) families](#)



## 13.8 FAQs Including Software Related

[\[FAQ\] AM6x: Latest FAQs on AM62x, AM64x, AM24x, AM3x, AM4x Sitara devices](#)

## 13.9 FAQs for Attached Devices

[\[FAQ\] DP83869-EP: Ethernet compliance Testing failure](#)

[\[FAQ\] List of FAQs for TPS6594-Q1, TPS6593-Q1, LP8764-Q1 PMICs](#)

[\[FAQ\] TPS65219: Benefits of a PMIC vs discrete solution to power Sitara AM62x MPU](#)

## 14 Terminology

<b>BOM</b>	Bill of Materials
<b>CAN</b>	Controller Area Network
<b>CPPI</b>	Communications Port Programming Interface
<b>CPSW3G</b>	Common Platform Ethernet Switch 3-port Gigabit
<b>CSIRX</b>	Camera Streaming Interface Receiver
<b>DDR0_CAL0</b>	IO Pad Calibration Resistor
<b>DFU</b>	Device Firmware Upgrade
<b>DNI</b>	Do Not Install
<b>DPI</b>	Display Parallel Interface
<b>DRD</b>	Dual-Role Device
<b>DSI</b>	Display Serial Interface
<b>E2E</b>	Engineer to Engineer
<b>ECC</b>	Error-Correcting Code
<b>EMC</b>	Electromagnetic Compatibility
<b>EMI</b>	Electromagnetic Interference
<b>eMMC</b>	embedded Multi-Media Card
<b>EMU</b>	Emulation Control
<b>EOS</b>	Electrical Over-Stress
<b>ESD</b>	Electrostatic discharge
<b>ESL</b>	Effective Series Inductance
<b>ESR</b>	Effective Series Resistance
<b>FAQ</b>	Frequently Asked Question
<b>FET</b>	Field-Effect Transistor
<b>GEMAC</b>	Gigabit Ethernet Media Access Controller
<b>GPIO</b>	General Purpose Input/Output
<b>GPMC</b>	General-Purpose Memory Controller
<b>HS-RTDX</b>	High Speed Real Time Data eXchange
<b>I2C</b>	Inter-Integrated Circuit
<b>IBIS</b>	Input/Output Buffer Information Specification
<b>IEP</b>	Industrial Ethernet Peripheral
<b>JTAG</b>	Joint Test Action Group
<b>LDO</b>	Low Dropout
<b>LVC MOS</b>	Low Voltage Complementary Metal Oxide Semiconductor
<b>LVDS</b>	Low Voltage Differential Signaling

<b>MAC</b>	Media Access Controller
<b>MCASP</b>	Multichannel Audio Serial Ports
<b>MCSPi</b>	Multichannel Serial Peripheral Interface
<b>MCU</b>	Micro Controller Unit
<b>MDI</b>	Medium Dependent Interface
<b>MDIO</b>	Management Data Input/Output
<b>MMC</b>	Multi-Media Card
<b>MMcSD</b>	Multi-Media Card/Secure Digital
<b>ODT</b>	On-die Termination
<b>OLDI</b>	Open LVDS Display Interface
<b>OPN</b>	Orderable Part Number
<b>OSPI</b>	Octal Serial Peripheral Interface
<b>PCB</b>	Printed Circuit Board
<b>PDN</b>	Power Distribution Network
<b>PET</b>	Power Estimation Tool
<b>PMIC</b>	Power Management Integrated Circuit
<b>POR</b>	Power-on Reset
<b>QSPi</b>	Quad Serial Peripheral Interface
<b>RGMIi</b>	Reduced Gigabit Media Independent Interface
<b>RMII</b>	Reduced Media Independent Interface
<b>ROC</b>	Recommended Operating Condition
<b>SD</b>	Secure Digital
<b>SDIO</b>	Secure Digital Input Output
<b>SPI</b>	Serial Peripheral Interface
<b>TCK</b>	Test Clock Input
<b>TDI</b>	Test Data Input
<b>TDO</b>	Test Data Output
<b>TEN</b>	Test Enable
<b>TMS</b>	Test Mode Select Input
<b>TRC_DATAn</b>	Trace Data n
<b>TRM</b>	Technical Reference Manual
<b>TRSTn</b>	Reset
<b>UART</b>	Universal Asynchronous Receiver/Transmitter
<b>WKUP</b>	Wake-up
<b>XDS</b>	eXtended Development System
<b>ZQ</b>	Device Calibration reference

## 15 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision * (December 2024) to Revision A (January 2025)</b>	<b>Page</b>
• Added the section Custom Board Design - Implementation References.....	3
• Added all GPNs in one section.....	3
• Updated the list of data sheet with revision number and added Current Data sheet revision, updates and usage notes FAQ.....	5
• Added Data sheet Pin Attributes and Pin connectivity related queries FAQ.....	5
• Added FAQ related to residual voltage and detection.....	6
• Added 8, 9, 10 points in General and point 5 in Additional.....	7
• Added 10, 11, 12 points in General.....	8
• Added information related to drive strength configuration support FAQ.....	11
• Added point 5 in Additional and added Queries related to passive components values, tolerance, voltage rating FAQ.....	11
• Added queries related to processor data sheet pin attributes FAQ.....	13
• Added guidelines that needs to be considered when selecting or designing the processor power architecture and added FAQ related to residual voltage and detection.....	16
• Added section Power Supply Ramp (Slew Rate) Requirement and Dynamic Voltage Scaling / Change.....	16
• Added point 9 in General, added point 5 in Schematic Review and Updated point 5 in Additional.....	17
• Updated point 5 in Additional.....	18
• Added point 7 in Additional.....	19
• Updated 4 and 6 points in Additional.....	25
• Added point 4 in General.....	27
• Updated point 5 in General and point 1 in Additional.....	30
• Updated Additional section.....	36
• Updated the Note.....	43
• Updated the section GPMC NAND.....	45
• Added 4 and 10 points in Schematic Review.....	48
• Updated the section Inter-Integrated Circuit (I2C).....	55
• Updated the section title and added 6, 7, 8, 9 points in General.....	56
• Updated the section title and updated point 1 in Additional.....	57
• Added Data sheet Pin Attributes and Pin connectivity related queries FAQ.....	62
• Updated the section Connection and External Buffering.....	62
• Updated Additional section.....	63
• Added the section Self-Review of the Custom Board Schematics Design.....	68
• Added information about AM62D-Q1 processor family.....	70
• Added processor-specific checklist (SPRADO2).....	71
• Added AM62D-Q1 processor family references as a new section.....	71
• Added processor-specific checklist (SPRADO3).....	71
• Added AM62x processor families combined checklist (SPRAD21).....	72
• Added information about AM62D-Q1 processor family.....	72

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